Features of PX8700

1. Wave Type

• CELLULAR : G7W

• PCS : G7W

2. Frequency Scope

| Transmit Frequency (MHz) | | Receive Frequency (MHz) | | |
|--------------------------|-----------|-------------------------|-----------|---------|
| CELLULAR | PCS | CELLULAR | PCS | GPS |
| 824.82 ~ 848.19 | 1850~1910 | 869.82~893.19 | 1930~1990 | 1575.42 |

3. Rated Output Power: CELLULAR = 0.20W

PCS = 0.20W

4. Output Conversion Method : This is possible by correcting the key board channel.

5. Voltage and Current Value of Termination Part Amplifier (Catalogue included)

| MODE | Part Name | Voltage | Current | Power |
|----------|-----------|---------|---------|-------|
| CELLULAR | AWT6310R | 4.2V | 600mA | 0.20W |
| PCS | AWT6310R | 4.2V | 600mA | 0.20W |

6. Functions of Major Semi-Conductors

| Classification | Function | |
|------------------------------------|--|--|
| MSM6550 | Terminal operation control and digital signal processing | |
| Memory MCP (HYI0UGG0MF1P-6SS0E) | Flash Memory (1Mbit) + SDRAM (512Mbit) Storing of terminal operation program | |
| RFR6500 | Converts Rx RF signal to baseband signal | |
| RFT6150 | Converts baseband signal to Tx RF signal | |

7. Frequency Stability

• CELLULAR: ± 0.5PPM

• PCS: ± 0.1PPM



SERVICE MANUAL

TRI BAND CDMA [PCS/Cellular/GPS] CDMA MOBILE PHONE

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General Introduction

The PX8700 phone has been designed to operate on the latest digital mobile communication technology, Code Division Multiple Access (CDMA). This CDMA digital technology has greatly enhanced voice clarity and can provide a variety of advanced features. Currently, CDMA mobile communication technology has been commercially used in Cellular and Personal Communication Service (PCS). The difference between them is the operating frequency spectrum. Cellular uses 800MHz and PCS uses 1.9GHz. The PX8700 support GPS Mode, we usually call it tri-band phone. Also, PX8700 works on Advanced Mobile Phone Service (S-GPS). We call it dual-mode phone. If one of the Cellular, PCS base stations is located nearby, Call fail rate of triple-mode phone is less than dual-mode phone or single-mode phone.

The CDMA technology adopts DSSS (Direct Sequence Spread Spectrum). This feature of DSSS enables the phone to keep communication from being crossed and to use one frequency channel by multiple users in the same specific area, resulting that it increases the capacity 10 times more compared with that in the analog mode currently used. Soft/Softer Handoff, Hard Handoff, and Dynamic RF power Control technologies are combined into this phone to reduce the call being interrupted in a middle of talking over the phone.

Cellular and PCS CDMA network consists of MSO (Mobile Switching Office), BSC (Base Station Controller), BTS (Base station Transmission System), and MS (Mobile Station). The following table lists some major CDMA Standards.

| CDMA Standard | Designator | Description |
|---------------------|---------------------|---|
| Basic air interface | TIA/EIA/IS-95-A/B/C | Protocol between MS and BTS for Cellular & AMPS |
| | ANSI J-STD-008 | Protocol between MS and BTS for PCS |
| Network | TIA/EIA/IS-634 | MAS-BS |
| | TIA/EIA/IS/651 | PCSC-RS |
| | TIA/EIA/IS-41-C | Intersystem operations |
| | TIA/EIA/IS-124 | Nom-signaling data comm. |
| Service | TIA/EIA/IS-96-B | Speech CODEC |
| | TIA/EIA/IS-99 | Assign data and fax |
| | TIA/EIA/IS-637 | Short message service |
| | TIA/EIA/IS-657 | Packet data |
| Performance | TIA/EIA/IS-97 | Cellular base station |
| | TIA/EIA/IS-98 | Cellular mobile station |
| | ANSI J-STD-018 | PCS personal station |
| | ANSI J-STD-019 | PCS base station |
| | TIA/EIA/IS-125 | Speech CODEC |

* TSB -74: Protocol between an IS-95A system and ANSI J-STD-008

Chapter 1. System Introduction

1.1 CDMA Abstract

The CDMA mobile communication system has a channel hand-off function that is used for collecting the information on the locations and movements of mobile telephones from the cell site by automatically controlling several cell site through the setup of data transmission routes, and then enabling one switching system to carry out the automatic remote adjustment. This is to maintain continuously the call state through the automatic location confirmation and automatic radio channel conversion when the busy subscriber moves from the service area of one cell site to that of another by using automatic location confirmation and automatic radio channel conversion functions. The call state can be maintained continuously by the information exchange between switching systems when the busy subscriber moves from one Cellular system area to the other Cellular system area.

In the Cellular system, the cell site is a small-sized low output type and utilizes a frequency allocation system that considers mutual interference, in an effort to enable the re-use of corresponding frequency from a cell site separated more than a certain distance.

Unlike the time division multiple access (TDMA) or frequency division multiple access (FDMA) used in the band limited environment, the Code Division Multiple Access (CDMA) system which is one of digital Cellular systems is a multi-access technology under the interference limited environment. It can process more number of subscribers compared to other systems (TDMA system has the processing capacity three times greater than the existing FDMA system whereas CDMA system, about 12~15 times of that of the existing system).

CDMA system can be explained as follows; TDMA or CDMA can be used to enable each person to talk alternately or provide a separate room for each person when two persons desire to talk with each other at the same time, whereas FDMA can be used to enable one person to talk in soprano, whereas the other in bass (one of the two talkers can carry out synchronization for hearing in case there is a bandpass filter function in the area of the hearer). Another available method is to make two persons to sing in different languages at the same time, space, and frequency when wishing to let the audience hear the singing without being confused. This is the characteristic of CDMA.

On the other hand, when employing the CDMA technology, each signal has a different pseudo-random binary sequence used to spread the spectrum of carrier. A great number of CDMA signals share the same frequency spectrum. In the perspective of frequency area or time area, several CDMA signals are overlapped. Among these types of signals, only desired signal energy is selected and received through the use of pre-determined binary sequence; desired signals can be separated, and then received with the correlator used for recovering the spectrum into its original state. At this time, the spectrums of other signals that have different codes are not recovered into its original state, and appears as the self-interference of the system.

2. Features and Advantages of CDMA Mobile Phone

2.1 Various Types of Diversities

When employing the narrow band modulation (30kHz band) that is the same as the analog FM modulation system used in the existing Cellular system, the multi-paths of radio waves create a serious fading. However, in the CDMA broadband modulation (1.25MHz band), three types of diversities (time, frequency, and space) are used to reduce serious fading problems generated from radio channels in order to obtain high-quality calls.

Time diversity can be obtained through the use of code interleaving and error correction code whereas frequency diversity can be obtained by spreading signal energy to wider frequency band. The fading related to normal frequency can affect the normal 200~300KHz among signal bands and accordingly, serious effect can be avoided. Moreover, space diversity (also called path diversity) can be realized with the following three types of methods.

First, it can be obtained by the duplication of cell site receive antenna. Second, it can be obtained through the use of multi-signal processing device that receives a transmit signal having each different transmission delay time and then, combines them. Third, it can be obtained through the multiple cell site connection (Soft Handoff) that connects the mobile station with more than two cell sites at the same time.

2.2 Power Control

The CDMA system utilizes the forward (from a base station to mobile stations) and backward (from the mobile station to the base station) power control in order to increase the call processing capacity and obtain high-quality calls. In case the originating signals of mobile stations are received by the cell site in the minimum call quality level (signal to interference) through the use of transmit power control on all the mobile stations, the system capacity can be maximized. If the signal power of mobile station is received too strong, the performance of that mobile station is improved. However, because of this, the interference on other mobile stations using the same channel is increased and accordingly, the call quality of other subscribers is reduced unless the maximum accommodation capacity is reduced.

In the CDMA system, forward power control, backward open loop power control, and closed loop power control methods are used. The forward power control is carried out in the cell site to reduce the transmit power on mobile stations less affected by the multi-path fading and shadow phenomenon and the interference of other cell sites when the mobile station is not engaged in the call or is relatively nearer to the corresponding cell site. This is also used to provide additional power to mobile stations having high call error rates, located in bad reception areas or far away from the cell site.

The backward open loop power control is carried out in a corresponding mobile station; the mobile station measures power received from the cell site and then, reversely increases/decreases transmit power in order to compensate channel changes caused by the forward link path loss and terrain characteristics in relation to the mobile station in the cell site. By doing so, all the mobile transmit signals received by the base station have same strength.

Moreover, the backward closed loop power control used by the mobile station is performed to control power using the commands issued out by the cell site. The cell site receives the signal of each corresponding mobile station and compares this with the pre-set threshold value and then, issues out power increase/decrease commands to the corresponding mobile station every 1.25msec (800 times per second). By doing so, the gain tolerance and the different radio propagation loss on the forward/backward link are complemented.

2.3 Voice Encoder and Variable Data Speed

The bi-directional voice service having variable data speed provides voice communication which employs voice encoder algorithm having power variable data rate between the base station and the mobile station. On the other hand, the transmit voice encoder performs voice sampling and then, creates encoded voice packets to be sent out to the receive voice encoder, whereas the receive voice encoder demodulates the received voice packets into voice samples.

One of the two voice encoders described in the above is selected for use depending on inputted automatic conditions and message/data; both of them utilize four-stage frames of 9600, 4800, 2400, and 1200 bits per second for Cellular and 14400,7200,3600,1800 bits per second for PCS, so PCS provide relatively better voice quality (almost twice better than the existing celluar system). In addition, this type of variable voice encoder utilizes adaptive threshold values on selecting required data rate. It is adjusted in accordance with the size of background noise and the data rate is increased to high rate only when the voice of caller is inputted.

Therefore, background noise is suppressed and high-quality voice transmission is possible under the environment experiencing serious noise. In addition, in case the caller does not talk, data transmission rate is reduced so that the transmission is carried out in low energy. This will reduce the interference on other CDMA signals and as a result, improve system performance (capacity increased by about two times).

2.4 Protecting Call Confidentiality

Voice privacy is provided in the CDMA system by means of the private long code mask used for PN spreading. Voice privacy can ve applied on the traffic channels only. All calls are initiated using the public long code mask for PN spreading. The mobile station user may request voice privacy during call setup using the origination message or page response message, and during traffic channel operation using the long code transition request order.

The Transition to private long code mask will not be performed if authentication is not performed. To initiate a transition to the private or public long code mask, either the base station or the mobile station sends a long code transition request order on the traffic channel.

2.5 Soft Handoff

A handoff in which the mobile station commences communications with a new base station without interrupting communications with the old base station. Soft handoff can only be used between CDMA channels having identical frequency assignments.

2.6 Frequency Re-Use and Sector Segmentation

Unlike the existing analog Cellular system, the CDMA system can reuse the same frequency at the adjacent cell. there is no need to prepare a separate frequency plan. Total interference generated on mobile station signals received from the cell site is the sum of interference generated from other mobile stations in the same cell site and interference generated from the mobile station of adjacent cell site. That is, each mobile station signal

generates interference in relation to the signals of all the other mobile stations.

Total interference from all the adjacent cell sites is the ratio of interference from all the cell sites versus total interference from other mobile stations in the same cell site (about 65%). In the case of directional cell site, one cell normally uses a 120 ° sector antenna in order to divide the sector into three. In this case, each antenna is used only for 1/3 of mobile stations in the cell site and accordingly, interference is reduced by 1/3 on the average and the capacity that can be supported by the entire system is increased by three times.

2.7 Soft Capacity

The subscriber capacity of the CDMA system is flexible depending on the relation between the number of users and service classes. For example, the system operator can increase the number of channels available for use during the busy hour despite the drop in call quality. This type of function requires 40% of normal call channels in the standby mode during the handoff, in an effort to avoid call disconnection resulting from the lack of channels.

In addition, in the CDMA system, services and service charges are classified further into different classes so that more transmit power can be allocated to high class service users for easier call set-up; they can also be given higher priority of using hand-off function than the general users.

3. Specification

3.1 General Specification

3.1.1 Transmit/Receive Frequency Interval:

1) CELLULAR: 45 MHz

2) PCS: 80 MHz

3.1.2 Number of Channels (Channel Bandwidth)

1) CELLULAR: 20 Channels

2) PCS: 48 Channels

3.1.3 Operating Voltage: DC 3.3~4.2V

3.1.4 Battery Power Consumption : DC 3.7V

| | SLEEP | IDLE | MAX POWER |
|---------------|-------|------------|-----------------|
| CELLULAR 1 mA | | 110~140mA | 700 mA (24 dBm) |
| PCS | 1 mA | 120~150 mA | 700 mA (24 dBm) |

3.1.5 Operating Temperature : -20°C ~ +60°C

3.1.6 Frequency Stability

1) CDMA: ± 0.5PPM 2) PCS: ± 0.1PPM

3.1.7 Antenna : Intenna Type, 50Ω

3.1.8 Size and Weight

1) Size: 97(H) * 49.5(W) * 13.6(D) mm

2) Weight: 110 g (Approximately with standard battery)

3.1.9 Channel Spacing

1) CELLULAR: 1.25MHz

2) PCS: 1.25 MHz

3.1.10 Battery Type, Capacity and Operating Time.

Unit = Hours : Minutes

| Cint = Hours: Minutes | | | | | |
|-----------------------|---------------------|----------------------------|--|--|--|
| | Standard (1,100mAh) | | | | |
| Cr. H. Tr. | CELLULAR | About 380 Hours (SCI=2) | | | |
| Standby Time | PCS | About 380 Hours (SCI=2) | | | |
| Talk time | CELLULAR | 230 Minutes (-92dBm input) | | | |
| | PCS | 230 Minutes (-92dBm input) | | | |

3.2 Receive Specification

3.2.1 Frequency Range

1) CELLULAR: 869.820 MHz ~ 893.190 MHz

2) PCS: 1930 MHz ~ 1990 MHz

3) GPS: 1575.42 MHz

3.2.2 Local Oscillating Frequency Range:

1) CELLULAR: 1738.08MHz ~ 1787.94MHz

2) PCS: 1715.56MHz ~ 1768.89MHz

3) GPS: 3150.84MHz

3.2.3 Sensitivity

1) CELLULAR: -104dBm (C/N 12dB or more)

2) PCS: -104dBm (C/N 12dB or more)

3) GPS: -148.5dBm (without SA mode)

3.2.4 Selectivity

1) CELLULAR: 3dB C/N Degration (With Fch ± 1.25 kHz: -30dBm)

2) PCS: 3dB C/N Degration (With Fch ± 1.25 kHz: -30dBm)

3.2.5 Spurious Wave Suppression: Maximum of -80dB

3.2.6 CDMA Input Signal Range

• Dynamic area of more than -104~ -25 dB: 79dB at the 1.23MHz band.

3.3 Transmit Specification

3.3.1 Frequency Range

1) CELLULAR: 824.820MHz ~ 848.190MHz

2) PCS: 1850 MHz ~ 1910 MHz

3.3.2 Output Power

1) CELLULAR: 0.224W

2) PCS: 0.224W

3.3.3 Interference Rejection

1) Single Tone: -30dBm at 900 kHz (CELLULAR), -30dBm at 1.25MHz(PCS)

2) Two Tone : -43dBm at 900 kHz & 1700kHz(CELLULAR), -43dBm at 1.25 MHz & 2.05 MHz (PCS)

3.3.11 CDMA TX Frequency Deviation:

1) CELLULAR: ± 300 Hz or less

2) PCS: ± 150Hz

3.3.12 CDMA TX Conducted Spurious Emissions

1) CELLULAR: 900kHz: - 42 dBc/30kHz below

1.98MHz: - 54 dBc/30kHz below

2) P C S : 1.25MHz : - 42 dBc/30kHz below

1.98MHz : - 50 dBc/30kHz below

3.3.13 CDMA Minimum TX Power Control

1) CELLULAR: - 50dBm below

2) P C S:-50dBm below

3.4 MS (Mobile Station) Transmitter Frequency

3.4.1 CELLULAR mode

| Ch# | Center Freq. (MHz) | Ch# | Center Freq. (MHz) |
|------|--------------------|-----|--------------------|
| 1011 | 824.640 | 404 | 837.120 |
| 29 | 825.870 | 445 | 838.350 |
| 70 | 827.100 | 486 | 839.580 |
| 111 | 828.330 | 527 | 840.810 |
| 152 | 829.560 | 568 | 842.040 |
| 193 | 830.790 | 609 | 843.270 |
| 234 | 832.020 | 650 | 844.500 |
| 275 | 833.250 | 697 | 845.910 |
| 316 | 834.480 | 738 | 847.140 |
| 363 | 835.890 | 779 | 848.370 |

3.4.2 PCS mode

| Ch# | Center Freq (MHz) | Ch# | Center Freq (MHz) | Ch# | Center Freq (MHz) |
|-----|-------------------|-----|-------------------|-----|-------------------|
| 25 | 1851.25 | 425 | 1871.25 | 825 | 1891.25 |
| 50 | 1852.50 | 450 | 1872.50 | 850 | 1892.50 |
| 75 | 1853.75 | 475 | 1873.75 | 875 | 1893.75 |
| 100 | 1855.00 | 500 | 1875.00 | 900 | 1895.00 |
| 125 | 1856.25 | 525 | 1876.25 | 925 | 1896.25 |
| 150 | 1857.50 | 550 | 1877.50 | 950 | 1897.50 |

| 175 | 1858.75 | 575 | 1878.75 | 975 | 1898.75 |
|-----|---------|-----|---------|------|---------|
| 200 | 1860.00 | 600 | 1880.00 | 1000 | 1900.00 |
| 225 | 1861.25 | 625 | 1881.25 | 1025 | 1901.25 |
| 250 | 1862.50 | 650 | 1882.50 | 1050 | 1902.50 |
| 275 | 1863.75 | 675 | 1883.75 | 1075 | 1903.75 |
| 300 | 1865.00 | 700 | 1885.00 | 1100 | 1905.00 |
| 325 | 1866.25 | 725 | 1886.25 | 1125 | 1906.25 |
| 350 | 1867.50 | 750 | 1887.50 | 1150 | 1907.50 |
| 375 | 1868.75 | 775 | 1888.75 | 1175 | 1908.75 |

3.5 MS (Mobile Station) Receiver Frequency

3.5.1 CELLULAR mode

| Ch. # | Center Freq. (MHz) | Ch. # | Center Freq. (MHz) |
|-------|--------------------|-------|--------------------|
| 1011 | 869.640 | 404 | 882.120 |
| 29 | 870.870 | 445 | 883.350 |
| 70 | 872.100 | 486 | 884.580 |
| 111 | 873.330 | 527 | 885.810 |
| 152 | 874.560 | 568 | 887.040 |
| 193 | 875.790 | 609 | 888.270 |
| 234 | 877.020 | 650 | 889.500 |
| 275 | 878.250 | 697 | 890.910 |
| 316 | 879.480 | 738 | 892.140 |
| 363 | 880.890 | 779 | 893.370 |

3.5.2 PCS mode

| Ch# | Center Freq (MHz) | Ch# | Center Freq (MHz) | Ch# | Center Freq (MHz) |
|-----|-------------------|-----|-------------------|------|-------------------|
| 25 | 1931.25 | 425 | 1951.25 | 825 | 1971.25 |
| 50 | 1932.50 | 450 | 1952.50 | 850 | 1972.50 |
| 75 | 1933.75 | 475 | 1953.75 | 875 | 1973.75 |
| 100 | 1935.00 | 500 | 1955.00 | 900 | 1975.00 |
| 125 | 1936.25 | 525 | 1956.25 | 925 | 1976.25 |
| 150 | 1937.50 | 550 | 1957.50 | 950 | 1977.50 |
| 175 | 1938.75 | 575 | 1958.75 | 975 | 1978.75 |
| 200 | 1940.00 | 600 | 1960.00 | 1000 | 1980.00 |

| 225 | 1941.25 | 625 | 1961.25 | 1025 | 1981.25 |
|-----|---------|-----|---------|------|---------|
| 250 | 1942.50 | 650 | 1962.50 | 1050 | 1982.50 |
| 275 | 1943.75 | 675 | 1963.75 | 1075 | 1983.75 |
| 300 | 1945.00 | 700 | 1965.00 | 1100 | 1985.00 |
| 325 | 1946.25 | 725 | 1966.25 | 1125 | 1986.25 |
| 350 | 1947.50 | 750 | 1967.50 | 1150 | 1987.50 |
| 375 | 1948.75 | 775 | 1968.75 | 1175 | 1988.75 |

3.5.3 GPS mode : 1575.42 MHz

3.5.4 Bluetooth mode: 2400 MHz ~ 2483.5 MHz

3.6 AC Adaptor : See Appendix

3.7 Cigar Lighter Charger : See Appendix

3.7 Hands – Free Kit : See Appendix

4. Installation

4.1 Installing a Battery Pack

- 1) The Battery pack is keyed so it can only fit one way. Align the groove in the battery pack with the rail on the back of the phone until the battery pack rests flush with the back of the phone.
- 2) Slide the battery pack forward until you hear a "click", which locks the battery in place.

4.2 For Adapter Use

- 1) Plug the adapter into a wall outlet. The adapter can be operated from a 110V source. When AC power is connected to the adapter.
- Insert the adapter IO plug into the phone with the installed battery pack.
 Red light indicates battery is being charged.. Green light indicates battry is fully charged.

4.3 For Mobile Mount

4.3.1 Installation Position

In order to reduce echo sound when using the Hands-Free Kit, make sure that the speaker and microphone are not facing each other and keep microphone a generous distance from the speaker.

4.3.2 Cradle Installation

Choose an appropriate flat surface where the unit will not interface with driver's movement or passenger's comfort. The driver/user should be able to access the phone with ease. Using the four self-tapping screws provided, mount the supplied braket on the selected area. Then with the four machine screws provided, mount the counterpart on the reverse side of the reverse side of the cradle. Secure the two brackets firmly together by using the two bracket joint screws provide. The distance between the cradle and the interface box must not exceed the length of the main cable.

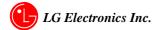
4.3.3 Interface Box

Choose an appropriate flat surface (somewhere under the dash on the passenger side is preferred) and mount the IB bracket with the four self-tapping screws provided. Clip the IB into the IB bracket.

4.3.4. Microphone Installation

Install the microphone either by cliiping I onto the sunvisor (driver's side) or by attaching it to door post (driver's side), using a velcno adhesive tape (not included).

4.3.5 Cable Connections



4.3.5.1 Power and Ignition Cables

Connect the red wire to the car battery positive terminal and the black wire to the car ground. Connect the green wire to the car ignition sensor terminal. (In order to operate HFK please make sure to connect green wire to ignition sensor terminal.) Connect the kit's power cable connector to the interface box power receptacle.

4.3.5.2 Antenna Cable Connection

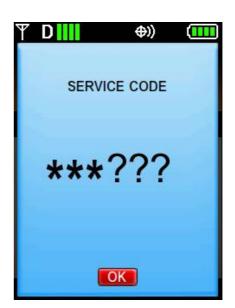
Connect the antenna coupler cable connector from the cradle to the external antenna connector. (Antenna is not included.)

CHAPTER 2. NAM Input Method (Inputting of telephone numbers included)

1. NAM Program Method and Telephone Number Inputting Method

1. Press 'menu' + 0 + "000000"





- 2. Press '1' key for entering 'Service Prg.'
 - Usually pressing 'Soft Key 1' will save the change.
 - To exit Service Program, press 'END' key.



2-1) ESN

You can see the ESN number. Press 'Soft Key 1' to edit more NAM1 items. Press 'Soft Key 2' to exit Service Programming'.



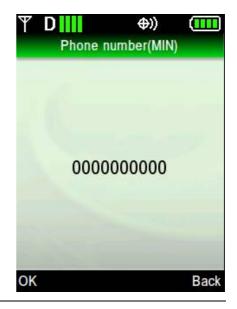
2-2) NAM1 Phone Number (MDN)

You can edit NAM1 Phone Number(MDN). Press soft key 1 to edit more NAM1 items. Press soft key 2 to edit previous NAM1 items.



2-3) NAM1 Phone Number (MIN)

You can edit NAM1 Phone Number(MIN). Press soft key 1 to edit more NAM1 items. Press soft key 2 to edit previous NAM1 items.



2-4) NAM1 Home SID

You can edit NAM1 Home SID. Press 'Soft Key 1' to edit more NAM1 items. Press 'Soft Key 2' to edit previous NAM1 items.



2-5) NAM1 Name

You can edit NAM1 Name.

Press 'OK' to edit more NAM1 items.

Press 'Soft Key 1' to edit NAM1 Name.

Press 'Soft Key 2' to edit previous NAM1 items.

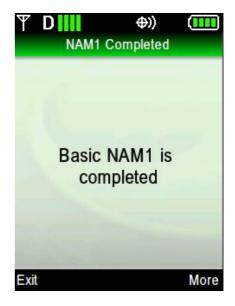


2-6) More NAM1 Programming

You can decide to edit more NAM1 items.

Press 'Soft Key 1' to exit Service Programming.

Press 'Soft Key 2' to edit more advanced NAM1 items.



2-7) Service Code

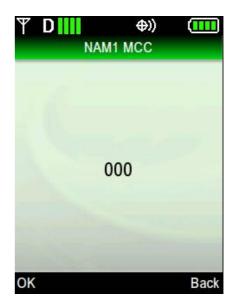
You can edit Service Code.

Press 'Soft Key 1' to edit more NAM1 items. Press 'Soft Key 2' to edit previous NAM1 items.



2-8) NAM1 MCC

You can edit NAM1 Mobile Country Code. Press 'Soft Key 1' to edit more NAM1 items. Press 'Soft Key 2' to edit previous NAM1 items.

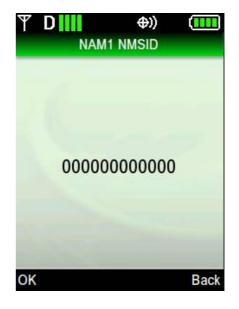


2-9) **NAM1 NMSID**

You can edit NAM1 NMSID.

Press 'Soft Key 1' to edit more NAM1 items.

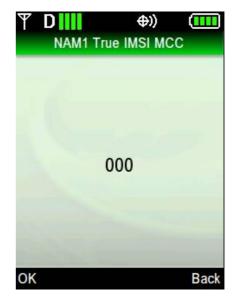
Press 'Soft Key 2' to edit previous NAM1 items.





2-10) NAM1 True IMSI MCC

You can edit NAM1 True IMSI MCC. Press 'Soft Key 1' to edit more NAM1 items. Press 'Soft Key 2' to edit previous NAM1 items.

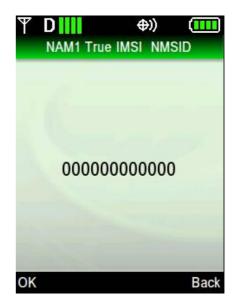


2-11) NAM1 True IMSI NMSID

You can edit NAM1 True IMSI NMSID.

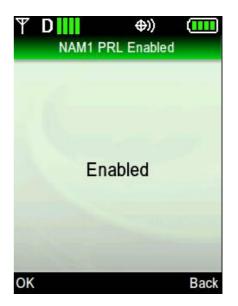
Press 'Soft Key 1' to edit more NAM1 items.

Press 'Soft Key 2' to edit previous NAM1 items.



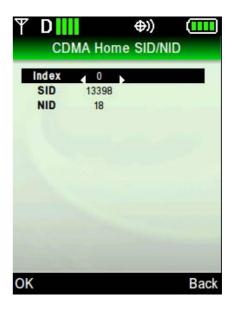
2-12) NAM1 PRL Enabled

You can see NAM1 PRL Enabled. Press 'Soft Key 1' to edit more NAM1 items. Press 'Soft Key 2' to edit previous NAM1 items.



2-13) CDMA Home SID/NID

You can edit NAM1 Home SID/NID Pairs. Press 'Soft Key 1' to edit more NAM1 items. Press 'Soft Key 2' to edit previous NAM1 items.



2-14) NAM1 CDMA Pri. CH A

You can edit NAM1 CDMA Primary Channel A. Press 'Soft Key 1' to edit more NAM1 items. Press 'Soft Key 2' to edit previous NAM1 items.



2-15) NAM1 CDMA Sec. CH A

You can edit NAM1 CDMA Secondary Channel A. Press 'Soft Key 1' to edit more NAM1 items. Press 'Soft Key 2' to edit previous NAM1 items.



2-16) NAM1 CDMA Pri. CH B

You can edit NAM1 CDMA Primary Channel B. Press 'Soft Key 1' to edit more NAM1 items. Press 'Soft Key 2' to edit previous NAM1 items.



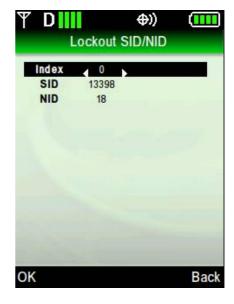
2-17) NAM1 CDMA Sec. CH B

You can edit NAM1 CDMA Secondary Channel B. Press 'Soft Key 1' to edit more NAM1 items. Press 'Soft Key 2' to edit previous NAM1 items.



2-18) Lockout SID/NID

You can edit Lockout SID/NID Pairs. Press 'Soft Key 1' to edit more NAM1 items. Press 'Soft Key 2' to edit previous NAM1 items.



2-19) NAM1 Home Sys Reg

You can edit Home System Registration. Press 'Soft Key 1' to edit more NAM1 items. Press 'Soft Key 2' to edit previous NAM1 items. Press Left, Right, Up, Down key to toggle Yes/No.



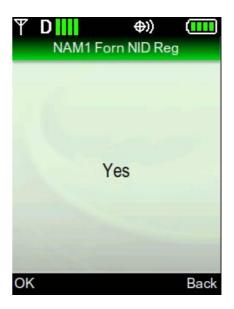
2-20) NAM1 Forn SID Reg

You can edit NAM1 Foreign SID Registration. Press 'Soft Key 1' to edit more NAM1 items. Press 'Soft Key 2' to edit previous NAM1 items. Press Left, Right, Up, Down key to toggle Yes/No.



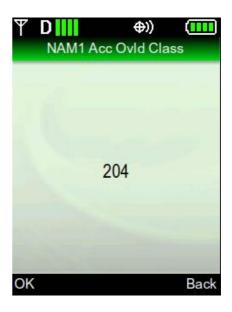
2-21) NAM1 Forn NID Reg

You can edit NAM1 Foreign NID Registration. Press 'Soft Key 1' to edit more NAM1 items. Press 'Soft Key 2' to edit previous NAM1 items. Press Left, Right, Up, Down key to toggle Yes/No.



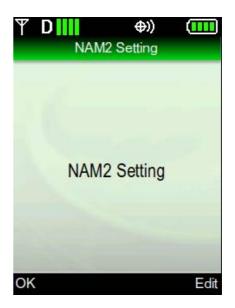
2-22) NAM1 Acc Ovld Class

You can see NAM1 Access Overload Class. Press 'Soft Key 1' to edit more NAM1 items. Press 'Soft Key 2' to edit previous NAM1 items.



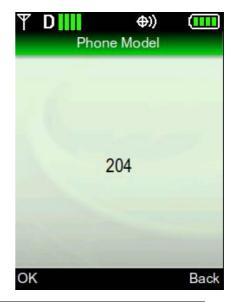
2-23) NAM2 Setting

You can decide to edit NAM2 items. Press 'Soft Key 1' to skip NAM2 items settings. Press 'Soft Key 2' to edit NAM2 related items.



2-24) Phone Model

You can see the Phone Model number. Press 'Soft Key 1' to edit more items. Press 'Soft Key 2' to edit previous items.



2-25) Slot Cycle Index

You can edit Slot Cycle Index Press 'Soft Key 1' to save Slot Cycle Index. Press 'Soft Key 2' to edit previous items.



2-26) **Powering Down** Restart.



CHAPTER 3. Circuit Description

1. RF Transmit/Receive Part

1.1 Overview

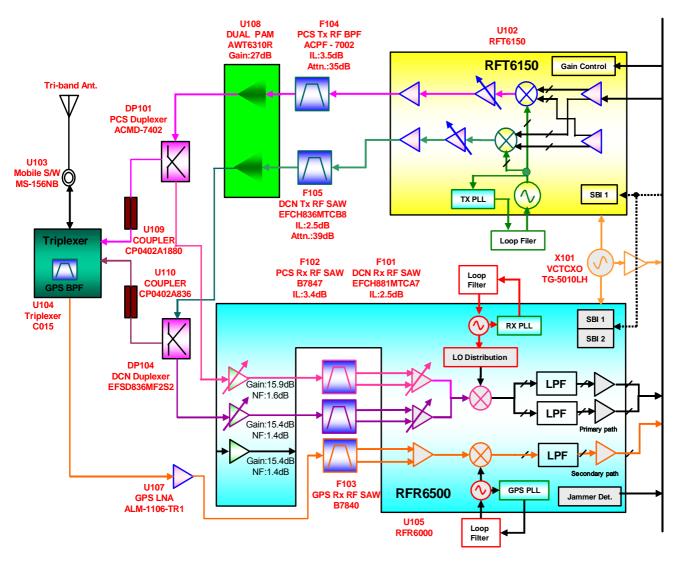
The TX and RX part employs the Direct-Conversion system. The TX and RX frequencies are respectively 824.04~848.97 and 869.04~893.97 for cellular and 1850~1910 and 1930~1990 for PCS. The block diagram is shown in [Figure 1-1]. RF signals received through the antenna are seperated by the Triplexer.

RF Signal fed into the low noise amplifier in RFR6500(LNA) through the duplexer. Then, they are fed into Mixer in RFR6500. In RFR6500, the RF signal is changed into baseband signal directly. Then, this signal is changed into digital signal by the analog to digital converter (ADC, A/D Converter), and the digital circuit part of the MSM(Mobile Station Modem) 6500 processes the data from ADC. The digital processing part is a demodulator.

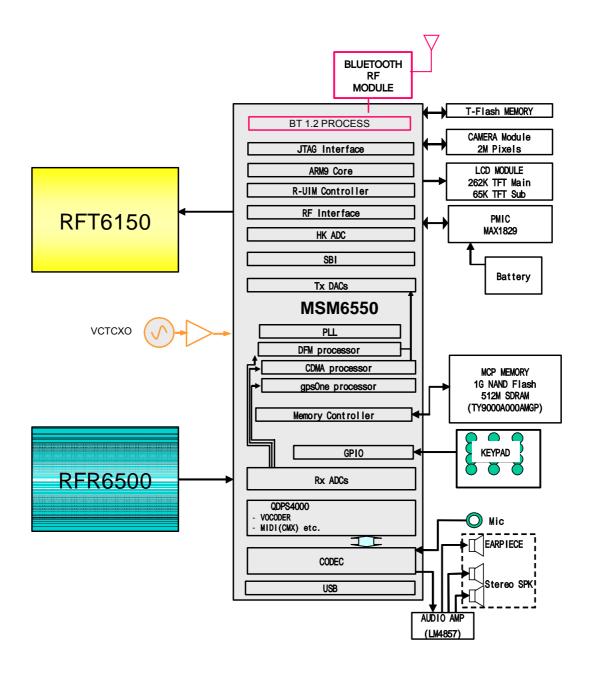
In the case of transmission, RFT6150 receives OQPSK-modulated anlaog signal from the MSM6550.

The RFT6150 connects directly with MSM6550 using an analog baseband interface. In RFT6150, the baseband quadrature signals are upconverted to the Cellular or PCS frequency bands and amplified to provide signal drive capability to the power amp.

After that, the RF signal is amplified by the Power Amp in order to have enough power for radiation. Finally, the RF signal is sent out to the cell site via the antenna after going through the duplexer.



[Figure 1-1] Block Diagram of PX8700



1.2 Description of RX Part Circuit

1.2.1 Triplexer Filter (U104)

The main function of Triplexer is to prohibit the other band signals from flowing into the one band circuit and vice versa. RF designer can use common tri-band antenna regardless of frequency band (800, 1575 and 1900 MHz). The specification of PX8700 Triplexer is described below:

| | Cellular | GPS | PCS | |
|-------------------|---------------|------------------|-----------------|--|
| Frequency Range | 824 – 894 MHz | 1575.42 MHz | 1850 – 1990 MHz | |
| Insertion Loss to | 1.0 dB Max | 1.8 dB Max. | 0.85 dB Max | |
| Common | (At +25 deg) | (At +25 deg) | (At +25 deg) | |
| | 48.5dB | 32.9dB(GPS-Cell) | 53.1dB | |
| Isolation | (Cell TX) | 18.3(GPS-PCS) | (PCS TX) | |
| Temperature Range | | -30 to +85 deg | | |

1.2.2 Duplexer (DP104, DP101)

The duplexer consists of the RX bandpass filter (BPF) and the TX BPF which has the function of separating TX and RX signals in the full duplex system for using the common antenna. The TX part BPF is used to suppress noises and spurious out of the TX frequency band. The RX BPF is used to receive only RX signal coming from the antenna, which is usually called preselector. It's main function is to limit the bandwidth of spectrum reaching the LNA and mixer, attenuate receiver spurious response and suppress local oscillator energy. As a result frequency sensitivity and selectivity of mobile phone increase. The specification of PX8700 duplexer described below;

PCS duplexer:

| TX | | RX | TX to RX (min) | |
|----------------|----------------|----------------|---------------------|--|
| Pass Band | 1850~1910 MHz | 1930~1990 MHz | | |
| Insertion Loss | 3.5dB max | 3.0dB max | | |
| Return Loss | 8.0dB min | 8.0dB min | | |
| | 40dB min | 50dB min | 54dB (1850~1910MHz) | |
| Attenuation | (1930~1990MHz) | (1850~1910MHz) | 44dB (1930~1990MHz) | |

Cellular duplexer

| | TX | RX | TX to RX (min) |
|----------------|-----------------------|--------------|-------------------|
| Pass Band | 824~849 MHz | 869~894 MHz | |
| Insertion Loss | 2.5B max | 3.5dB max | |
| VSWR | 2.2 max | 2.3 max | |
| Attonuction | 40dD | 50dB min | 54dB (824~849MHz) |
| Attenuation | 40dB min (869~894MHz) | (824~849MHz) | 43dB (869~894MHz) |

1.2.3 LNA (U105)

The RFR6500 has cellular, and PCS LNA, respectively. The characteristics of Low Noise Amplifier (LNA) are low noise figure, high gain, high intercept point and high reverse isolation. The frequency selectivity characteristic of mobile phone is mostly determined by LNA.

The specification of PX8700 LNA is described below:

| Parameter | Low gain | | Middle gain | | High gain | | Units |
|--------------|----------|-----|-------------|-----|-----------|-----|-------|
| | Cellular | PCS | Cellular | PCS | Cellular | PCS | |
| Gain | - 19 | -20 | -2 | - 9 | 15.5 | 16 | dB |
| Noise Figure | 19 | 20 | 2 | 9 | 1.4 | 1.6 | dB |
| Input IP3 | 25 | 25 | 20 | 20 | 6 | 8 | dBm |

1.2.4 GPS LNA(U107)

The characteristics of Low Noise Amplifier (LNA) are low noise figure, high gain, high intercept point and high reverse isolation. The frequency selectivity characteristic of mobile phone is mostly determined by LNA.

The specification of PX8700 GPS LNA is described below

| Parameter | GPS Band | Units |
|-----------------------|----------|-------|
| Gain | 14.8 | dB |
| Noise Figure | 0.85 | dB |
| 1dB compression point | 0 | dBm |
| IIP3 | +5 | dBm |

1.2.5 RX RF SAW FILTER(F101, F102, F103)

The main function of RX RF SAW filter is to attenuate mobile phone spurious frequency, attenuate noise amplified by the LNA and suppress second harmonic originating in the LNA.

1.2.6 Down-converter Mixers (U105)

The RFR6500 device performs signal down-conversion for Cellular, PCS and GPS tri-band applications. It contains all the circuitry (with the exception of external filters) needed to support conversion of received RF signals to Base-band signals. The three down-converting Mixers (Cellular, PCS and GPS), and a programmable PLL for generating RX LO frequency and an RX LO Buffer Amplifier and RX Voltage Controlled Oscillator. The GPS LNA & mixers offer the most advanced and integrated CDMA RX solution designed to meet cascaded Noise Figure (NF) and Third-order Intercept Point (IIP3) requirements of IS-98D and J-STD-018 specifications for Sensitivity, Two-Tone Inter-modulation, and Single-tone Desensitization.

Operation modes and band selection are specially controlled from the Mobile Station Modem MSM6550.

The specification of PX8700 Mixers is described below:

| Parameter | Low gain | | High ga | Units | |
|--------------|--------------|----|--------------|-------|-----|
| | Cellular PCS | | Cellular PCS | | |
| Noise Figure | 27 | 27 | 11 | 11 | dB |
| Input IP3 | 4 | 3 | 4 | 3 | dBm |
| Input IP2 | 50 | 50 | 75 | 70 | dBm |

1.3 Description of Transmit Part Circuit

1.3.1 RFT6150 (U102)

The RFT6150 Base-band to RF Transmit Processor performs all TX signal-processing functions required between digital Base-band and the Power Amplifier Modulator (PAM). The Base-band quadrate signals are up-converted to the Cellular or PCS frequency bands and amplified to provide signal drive capability to the PAM. The RFT6100 includes an mixers for up-converting analog Base-band to RF, a programmable PLL for generating TX LO frequency an TX LO Buffer Amplifier and TX Voltage Controlled Oscillator, cellular and PCS driver amplifiers and TX power control through an 85 dB VGA. As added benefit, the single sideband up-conversion eliminates the need for a band pass filter normally required between the up-converter and driver amplifier.

I, I/, Q and Q/ signals proceed from the MSM6550 to RFT6150 are analog signal. In CDMA mode, These signals are modulated by Offset Quadrature Phase Shift King (OQPSK). I and Q are 90 deg. out of phase, and I and I/ are 180 deg. The mixers in RFT6150 converts baseband signals into RF signals. After passing through the upconverters, RF signal is inputted into the Power AMP.

RFT6150 Cellular and PCS CDMA RF Specifications

| Parameter | Condition | Min. | Туре. | Max. | Units |
|--------------------------|-----------------------|------|-------|------|--------|
| Detail Outset Desse | Average CDMA Cellular | | 8 | | dBm |
| Rated Output Power | Average CDMA PCS | | 10 | | dBm |
| Mire Outland Brown | Average CDMA Cellular | | -80 | | dBm |
| Min Output Power | Average CDMA PCS | | -78 | | dBm |
| DV I as I as I as I as I | CDMA Cellular | | - 133 | | 15 /11 |
| RX band noise power | CDMA PCS | | -132 | | dBm/Hz |
| 4000 | Cellular: Fc±885kHz | | - 56 | | dBc/ |
| ACPR | PCS : Fc±1.25MHz | | - 56 | | 30kHz |

1.3.2 Power Amplifier(U108)

The Dual power amplifier that can be used in the PCS and CDMA mode has linear amplification capability and high efficiency. For higher efficiency, it is made up of one MMIC (Monolithic Microwave Integrated Circuit) for which RF input terminal and internal interface circuit are integrated onto one IC after going through the AlGaAs/GaAs HBT (heterojunction bipolar transistor) process. The module of power amplifier is made up of an output end interface circuit including this MMIC. The maximum power that can be inputted through the input terminal is +17dBm and conversion gain is about 28dB. RF transmit signals that have been amplified through the power amplifier are sent to the duplexer.

.

1.4 Description of Frequency Synthesizer Circuit

1.4.1 Voltage Control Temperature Compensation Crystal Oscillator (VCTCXO, X101)

The temperature variation of mobile phone can be compensated by VCTCXO. The reference frequency of a mobile phone is 19.2 MHz. The receiver frequency tuning signals called TRK_LO_ADJ from MSM as $0.5 \, \text{V} \sim 2.5 \, \text{V}$ DC via R and C filter in order to generate the reference frequency of 19.2 MHz and input it into the frequency synthesizer. Frequency stability depending on temperature is $\pm 2.0 \, \text{ppm}$.

2. Digital/Voice Processing Part

2.1 Overview

The digital/voice processing part processes the user's commands and processes all the digital and voice signal processing in order to operate in the phone. The digital/voice processing part is made up of a keypad/LCD, receptacle part, voice processing part, mobile station modem part, memory part, and power supply part.

2.2 Configuration

2.2.1 Keypad/LCD and Receptacle Part

This is used to transmit keypad signals to MSM6550. It is made up of a keypad backlight part that illuminates the keypad, LCD part that displays the operation status onto the screen, and a receptacle that receives and sends out voice and data with external sources.

2.2.2 Voice Processing Part

The voice processing part is made up of an audio codec used to convert MIC signals into digital voice signals and digital voice signals into analog voice signals, amplifying part for amplifying the voice signals and sending them to the ear piece, amplifying part that amplifies ringer signals coming out from MSM6550, and amplifying part that amplifies signals coming out from MIC and transferring them to the audio processor.

2.2.3 MSM (Mobile Station Modem) 6500 Part

MSM is the core elements of CDMA terminal and carries out the functions of CPU, encoder, interleaver, deinterleaver, Viterbi decoder, Mod/Demod, and vocoder.

2.2.4 Memory Part

The memory part is made up of a NAND Flash memory and a SDRAM for storing data.

2.2.5 Power Supply Part

The power supply part is made up of circuits for generating various types of power, used for the digital/voice processing part.

2.3 Circuit Description

2.3.1 Keypad/LCD and Receptacle Part

Once the keypad is pressed, the key signals are sent out to MSM6550 for processing. In addition, when the key is pressed, the keypad/LCD lights up through the use of 18 LEDs. The terminal status and operation are displayed on the screen for the user with the characters and icons on the LCD.

Moreover, it exchanges audio signals and data with external sources through the receptacle, and then receives power from the battery or external batteries.

2.3.2 Audio Processing Part

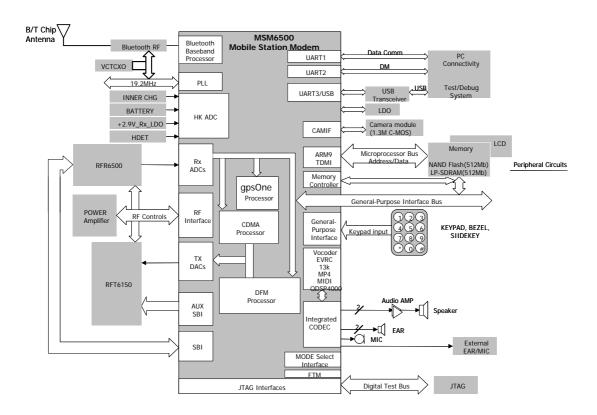
MIC signals are amplified through OP AMP, inputted into the audio codec(included in MSM6550) and converted into digital signals. Oppositely, digital audio signals are converted into analog signals after going through the audio codec. These signals are amplified at the audio amplifier and transmitted to the ear-piece. The signals from MSM6550 activate the ringer by using signals generated in the timer in MSM6550.

2.3.3 MSM Part

MSM6550 is the core element of CDMA system terminal that includes ARM926EJ-S microprocessor core. It supports both CDMA and Digital FM, operating in both the cellular and PCS spectrums. The subsystems within the MSM6550 include a CDMA processor, a DFM processor, a multi-standard Vocoder, an integrated CODEC with earpiece and microphone amplifiers, general-purpose ADC for subsystem monitoring, an ARM926EJ-S microprocessor, and an RS-232 serial interfaces supporting forward and reverse link MDR data communications of 230.4 Kbps simultaneously. And it also contains complete digital modulation and demodulation systems for both CDMA and AMPS cellular standards, as specified in IS-95-A/B/C.

In MSM, coded symbols are interleaved in order to cope with multi-path fading. Each data channel is scrambled by the long code PN sequence of the user in order to ensure the confidentiality of calls. Moreover, binary quadrature codes are used based on walsh functions in order to discern each channel. Data created thus are 4-phase modulated by one pair of Pilot PN code and they are used to create I and Q data.

When received, I and Q data are demodulated into symbols by the demodulator, and then de-interleaved in reverse to the case of transmission. Then, the errors of data received from viterbi decoder are detected and corrected. They are voice-decoded at the vocoder in order to output digital voice data.



[Figure 2-2] Block Diagram of Digital/Voice Processing Part

2.3.4 Memory Part

MCP contents 512Mbits NAND FLASH memory and 256Mbits SDRAM. In the NAND Flash Memory part of MCP are programs used for terminal operation. The programs can be changed through downloading after the assembling of terminals. On the SDRAM data generated during the terminal operation are stored temporarily.

2.3.5 Power Supply Part

When the battery voltage (+4.0V) is fed and the PWR key of keypad is pressed, U402(PMIC) is activated by the PWR_ON_SW signal, and The PWRON signal is held high, Buck and LDO1,2,3 are turned on; when LDO1 reaches 87% of its final value a 60ms reset timer is started at after which RESET\ is asserted high. Now the BB Processor is initialized and will assert PWRHOLD high. PWRHOLD maintains the power on.

The Buck/LDO1,2,3 are generating the +1.4V_MSMC, +2.6V_MSMA, +1.8V_MSMP1 and +2.8V_LCD respectively.

The Rx part LDO(Out5) is operated by the control signal SLEEP/ from MSM6550

The Tx part LDO(Out7) is operated by the control signal IDLE/ from MSM6550.

The TCXO part LDO(U403) is operated by the control signal TCXO_EN/ from MSM6550.

2.3.6 Logic Part

The logic part consists of internal CPU of MSM, RAM, MCP. The MSM6550 receives TCXO (=19.2MHz) from the X101 and controls the phone in CDMA modes. The major components are as follows:

CPU

The ARM926J-S microprocessor includes a 3 stage pipelined RISC architecture, both 32-bit ARM and 16-bit THUMB instruction sets, a 32-bit address bus, and a 32-bit internal data bus. It has a high performance and low power consumption.

• MCP

NAND Flash is used to store the terminal's program. Using the down-loading program, the program can be changed even after the terminal is fully assembled.

SDRAM is used to store the internal flag information, call processing data, and timer data.

• KEYPAD

For key recognition, key matrix is setup using KYPD[1][3][5][7][9][11][13][15][17][19][21] signal from MSM6550. 18 LEDs and backlight circuitry are included in the keypad for easy operation in the dark.

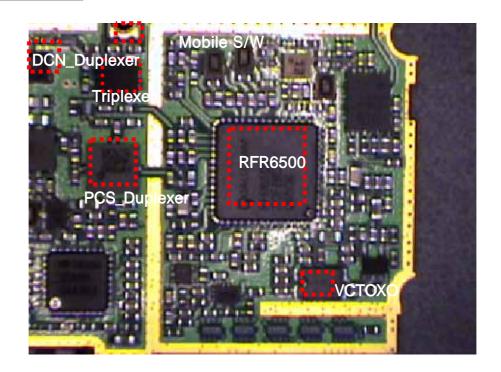
• LCD MODULE

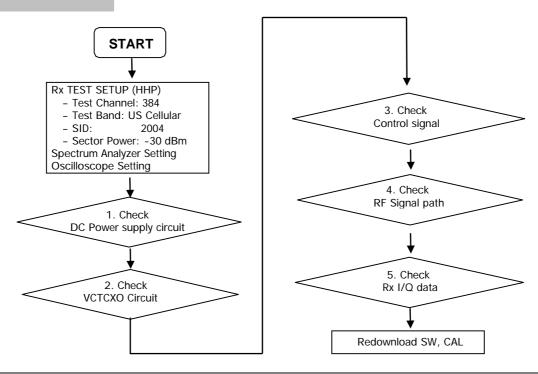
LCD module contains a controller which will display the information onto the LCD by 16-bit data from the MSM6550. It is also supplied stable +2.8V_LCD by Out3 in U402 for fine view angle and LCD reflects to improve the display efficiency. 4 LEDs is used to display LCD backlight.

CHAPTER 4. Trouble Shooting

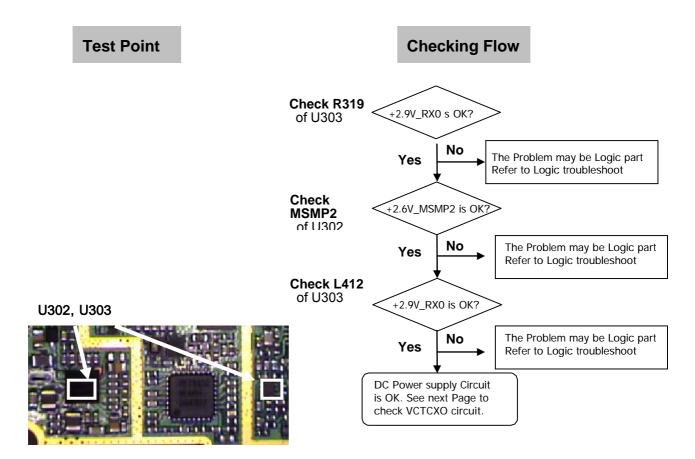
4.1.1 DCN Rx

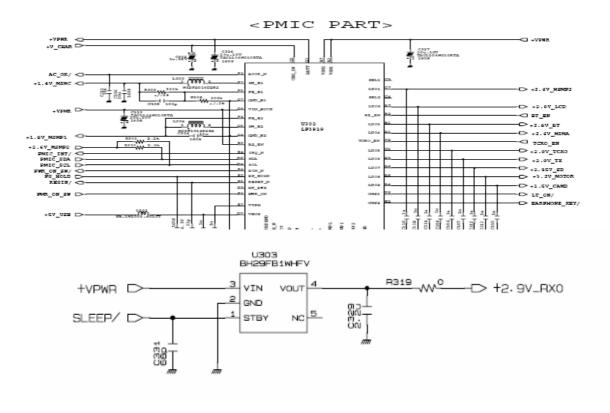
Test Point





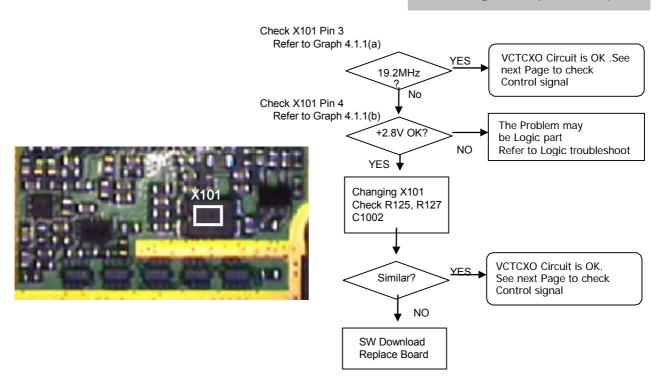
4.1.1.1 Checking DC Power supply Circuit (PMIC)

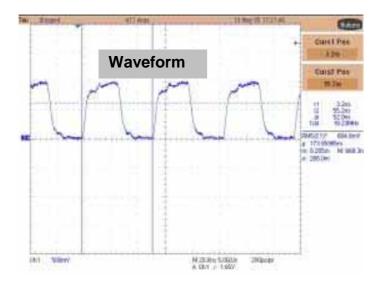


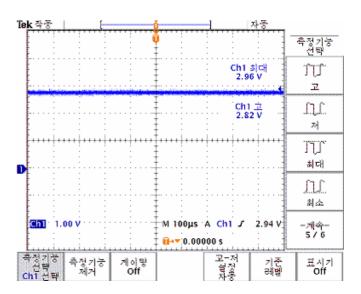


4.1.1.2 Checking VCTCXO Circuit

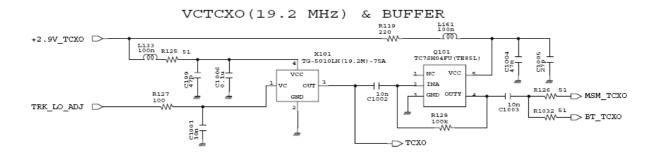
Checking Flow (VCTCXO)





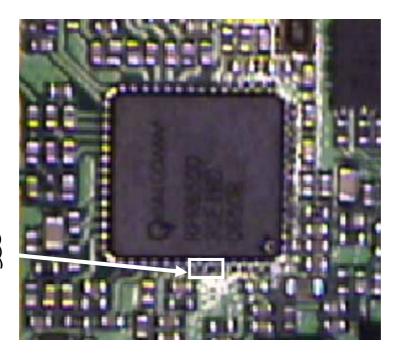


Graph Graph



4.1.1.3 Checking Control signal

Test Point



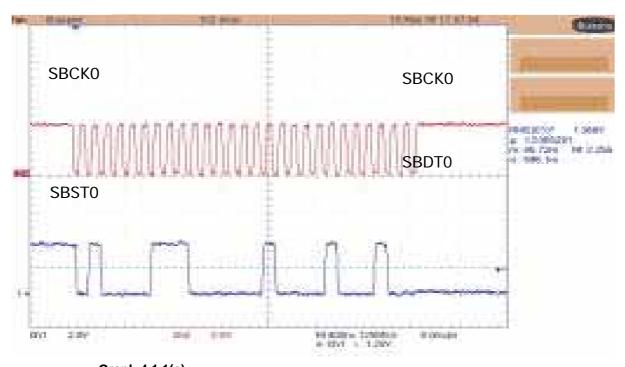
U105 Pin49 (SBST0) Pin50 (SBDT0) Pin51 (SBCK0)

Checking Flow

Check Pin 49(SBCK0), Pin 50(SBST0) Control Signal is Ok YES Similar? See next Page to Check RF signal path Pin 51(SBDT0) of U105 Check if there is Any Major Difference NO Refer to Graph 4.1.1(c,d) Download the SW Check Pin 49(SBCK0), Pin 50(SBST0) YES Pin 51(SBDT0) of U105 Check if there is Control Signal is Ok Similar? See next Page to Check RF signal path Any Major Difference Refer to Graph 4.1 .1(c,d) NO

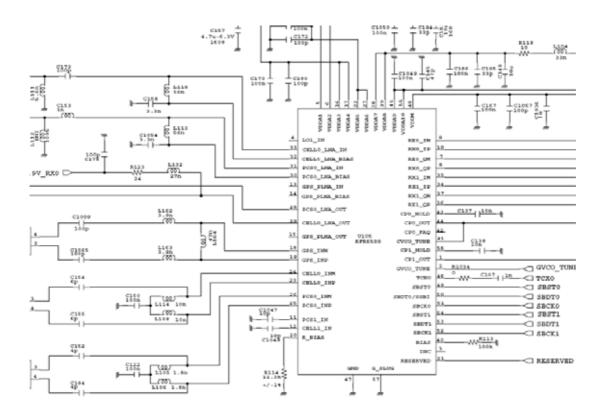
Replace Board

Waveform



Graph 4.1.1(c)

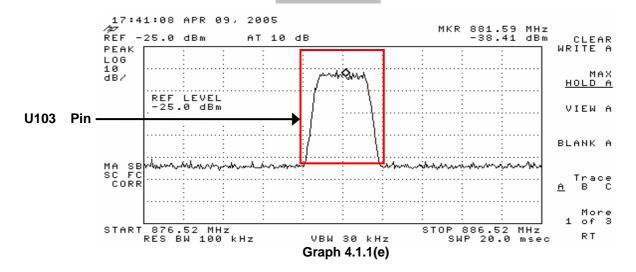
Graph 4.1.1(d)

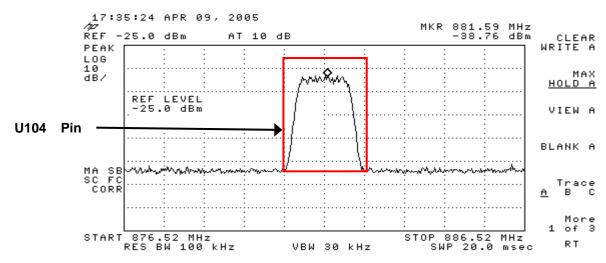


4.1.1.4 Checking RF Signal path (Mobile S/W, Triplexer, Duplexer)

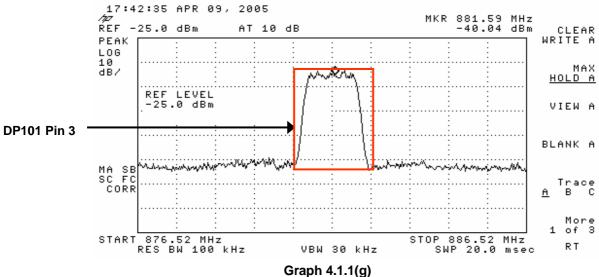
Test Point Checking Flow U103. Pin2 Check U103 Pin 2 Check if there is No Detected Signal? Changing U103 Any Major Difference DP101. Pin3 Refer to Graph 4.1.1(e) Yes No U104 Teterted Signal? Check C101 U104. Pin7 Yes C1063, L185 Check U104 Pin 7 No Check if there is Changing U104 Detected Signal? Any Major Difference Refer to Graph 4.1.1(f, Yes No Detected Signal? Check C1063&L185 Yes Check DP101 Pin 3 Check if there is No Changing DP101 Detected Signal? Any Major Difference C1034, L111 C173 Refer to Graph 4.1.1(g) Yes No Check C1034 & C173 Detected Signal? L111 Yes RF Signal Path is OK. See next Page to check RX I/Q data signal.

Waveform



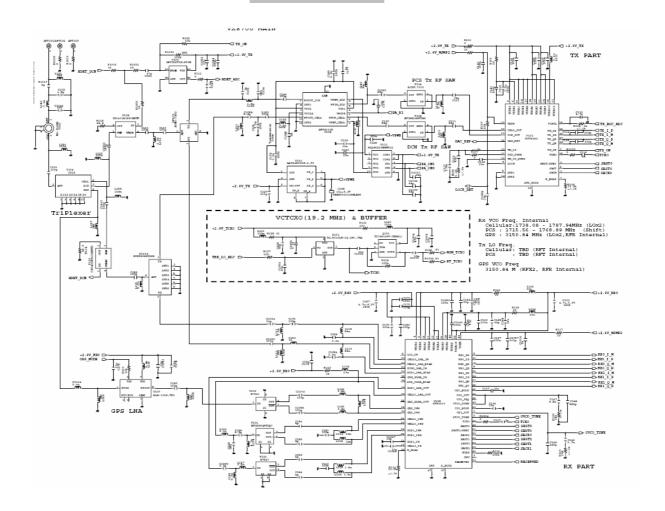






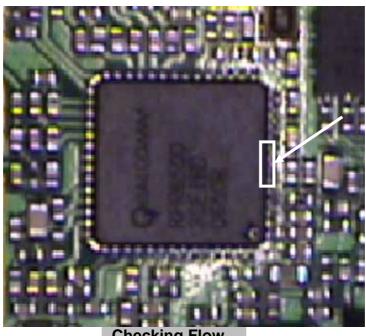
LG Electronics Inc.

Circuit

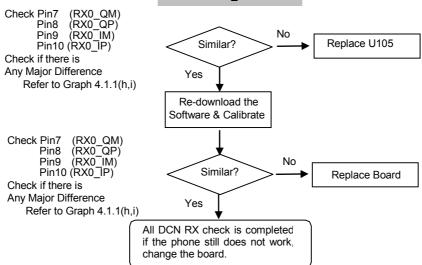


4.1.1.5 Checking Rx I/Q data

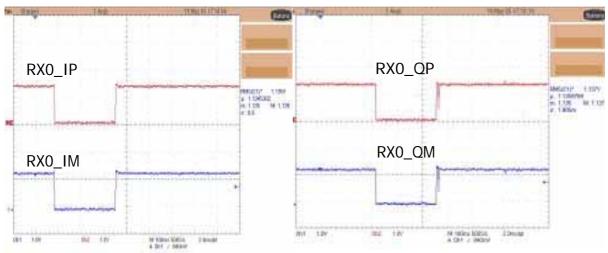
Test Point



Pin7 Pin8 Pin9 Pin7 (RX0_QM) Pin8 (RX0_QP) Pin9 (RX0_IM) Pin10 (RX0_IP) U105



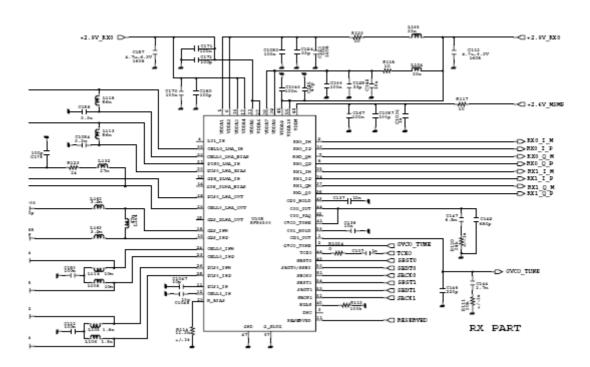
Waveform



Graph 4.1.1(h)

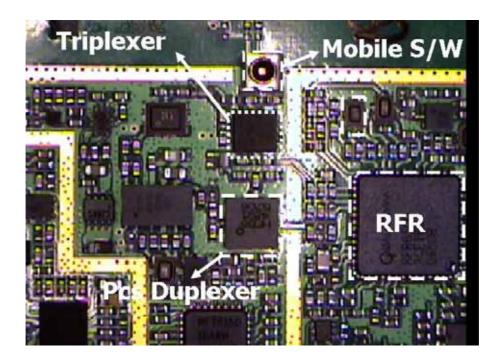
Graph 4.1.1(i)

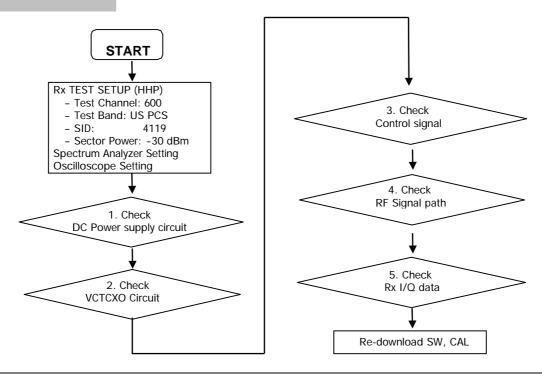
Circuit



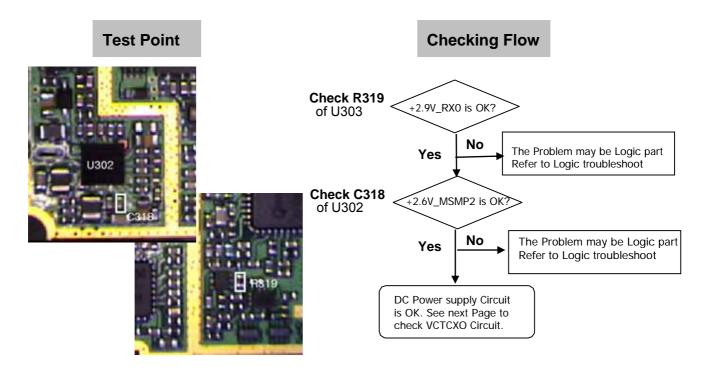
4.1.2 PCS RX

Test Point

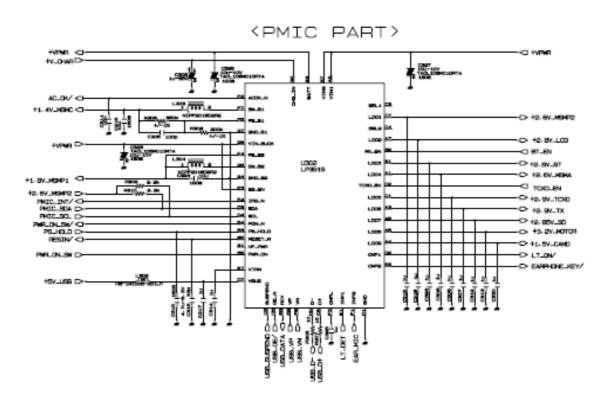




4.1.2.1 Checking DC Power supply Circuit (PMIC)





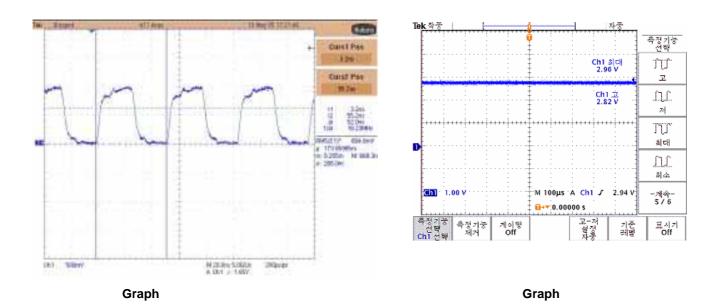


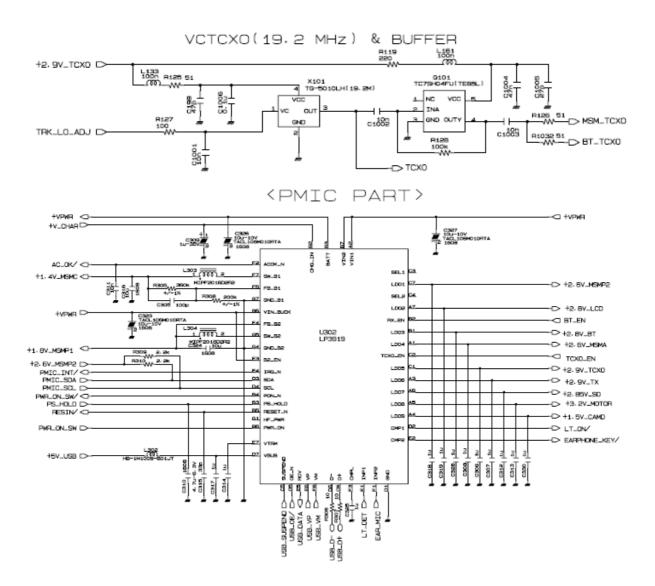
4.1.2.2 Checking VCTCXO Circuit

Test Point Checking Flow (VCTCXO) Check X101 Pin 3 Refer to Graph 4.1.2 (a)? VCTCXO Circuit is OK .See YES next Page to check Control signal. 19.2MHz? Check X101 Pin 4 Refer to Graph The Problem may 4.1.2 (b)? +2.9V OK be Logic part NO Refer to Logic troubleshoot YES Changing X101 Check C1001, C1002 C1006, R125 VCTCXO Circuit is OK. YES Similar? See next Page to check Control signal. NO SW Download

Replace Board

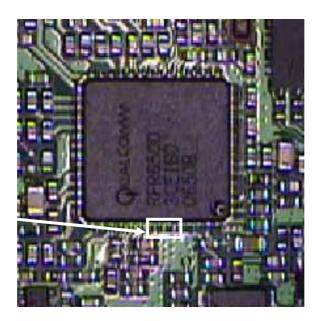
Waveform





4.1.2.3 Checking Control signal

Test Point

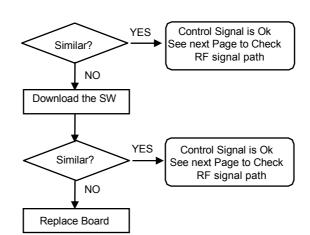


U105 Pin49 (SBST0) Pin50 (SBDT0) Pin51 (SBCK0)

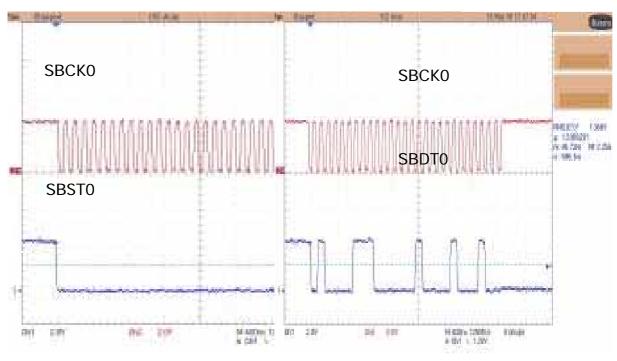
Checking Flow

Check Pin 49(SBCK0), Pin 50(SBST0) Pin 51(SBDT0) of U105 Check if there is Any Major Difference Refer to Graph 4.1.2(c,d)

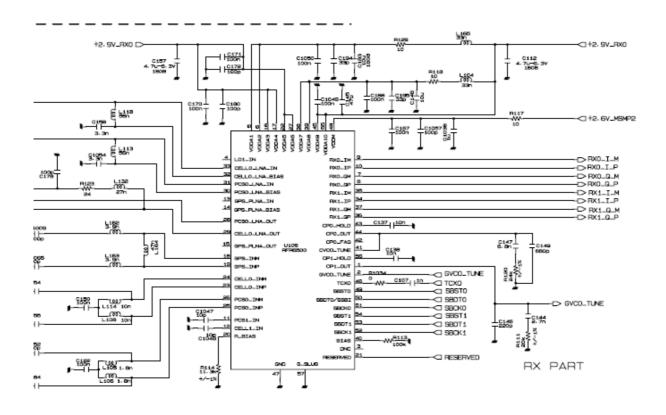
Check Pin 49(SBCK0), Pin 50(SBST0) Pin 51(SBDT0) of U105 Check if there is Any Major Difference Refer to Graph 4.1.2(c,d)



Waveform

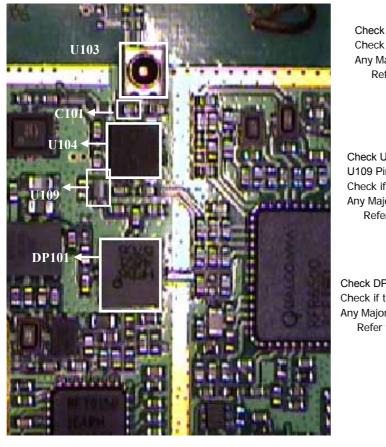


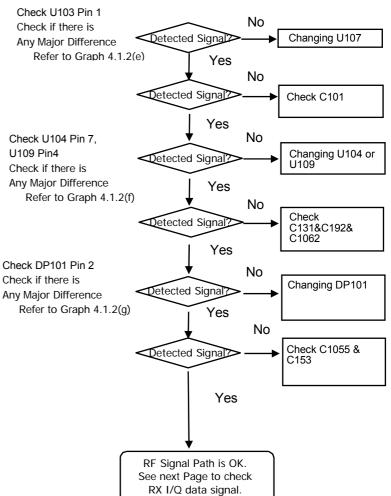
Graph 4.1.2(c) Graph 4.1.2(d)

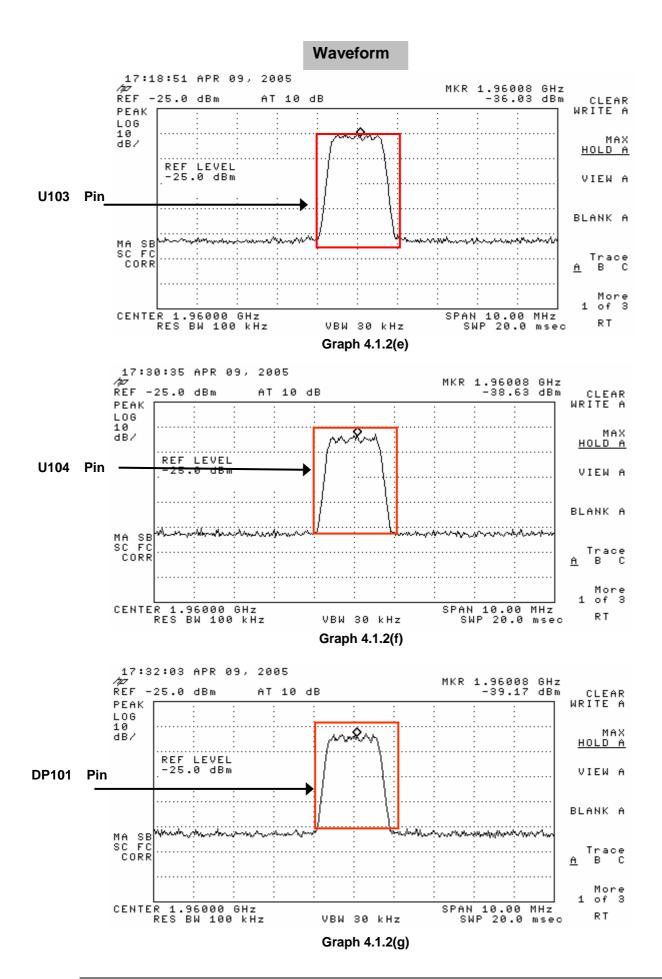


4.1.2.4 Checking RF Signal path (Mobile S/W, Triplexer, Duplexer)

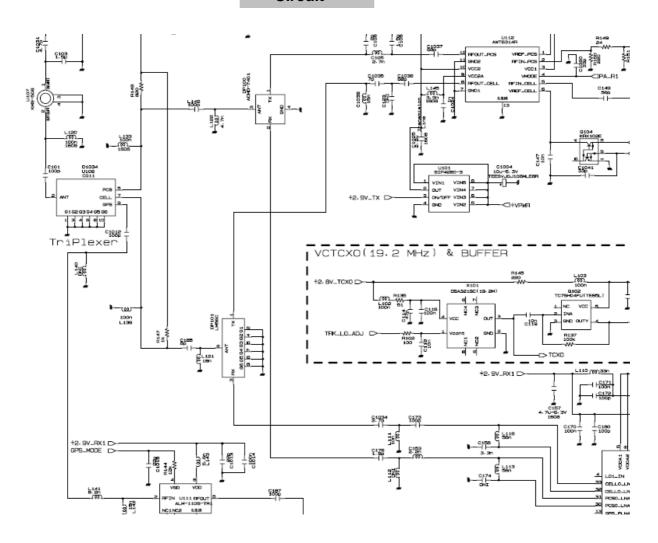
Test Point





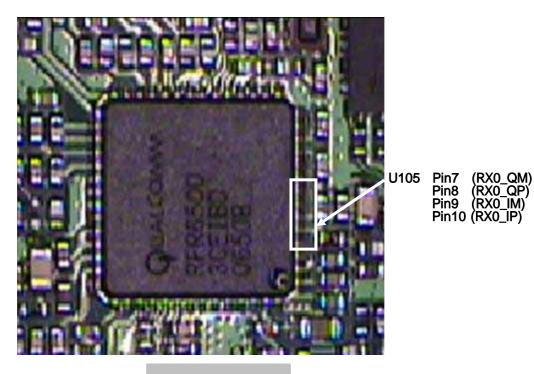


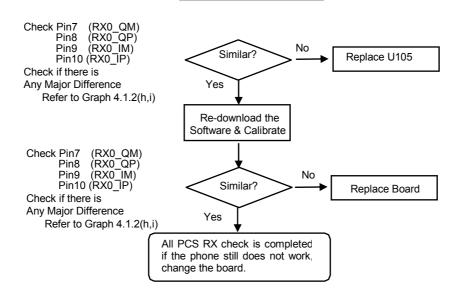
Circuit



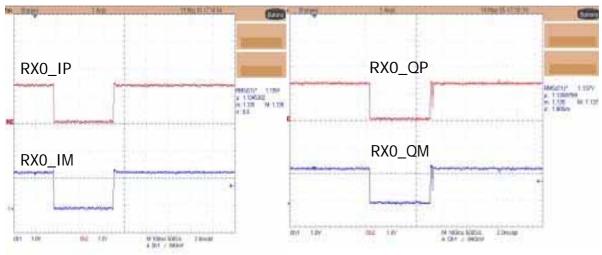
4.1.2.5 Checking Rx I/Q data

Test Point



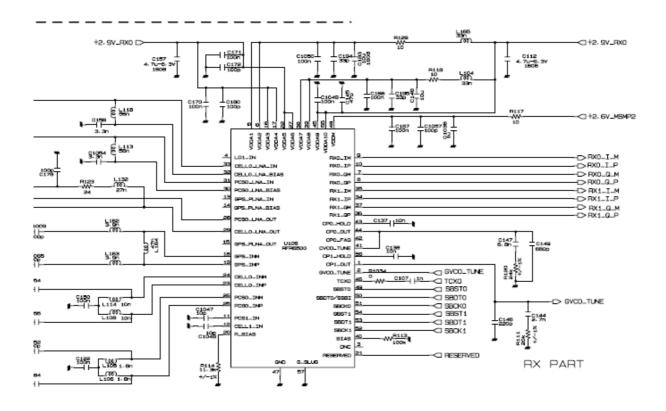


Waveform



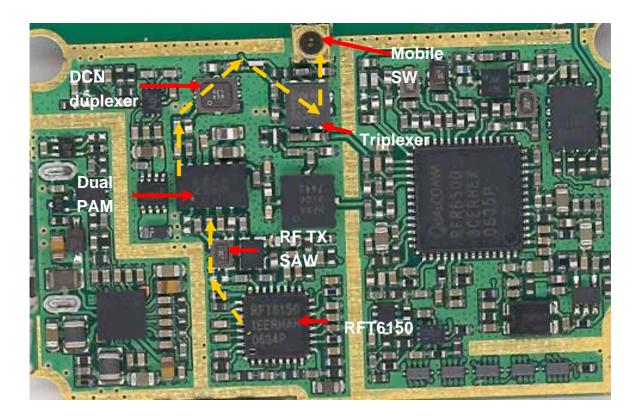
Graph 4.1.2(i)

Circuit

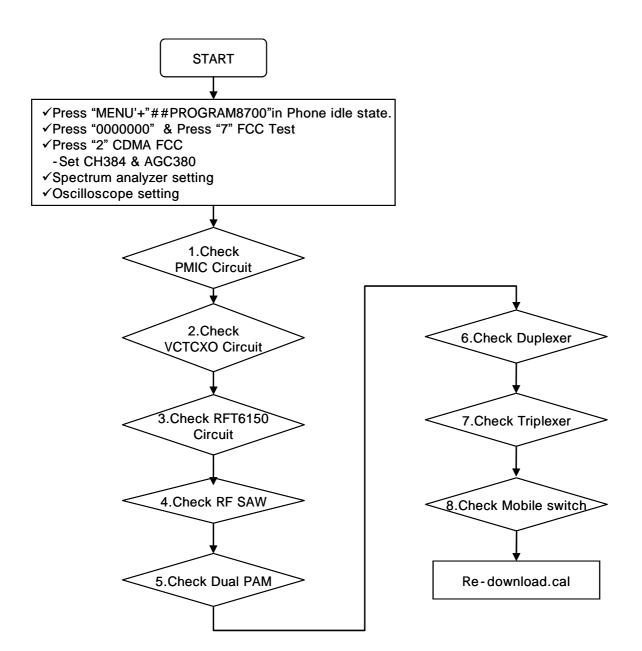


4.2 TX Part Trouble

4.2.1 DCN TX Trouble

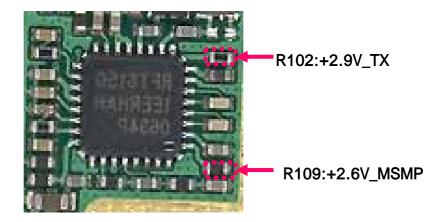


< PX8700 DCN TX Part >

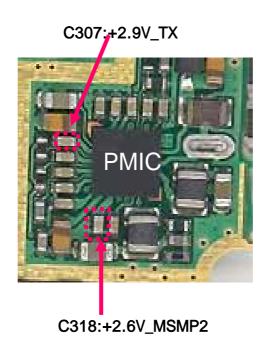


4.2.1.1. Check RFT Circuit

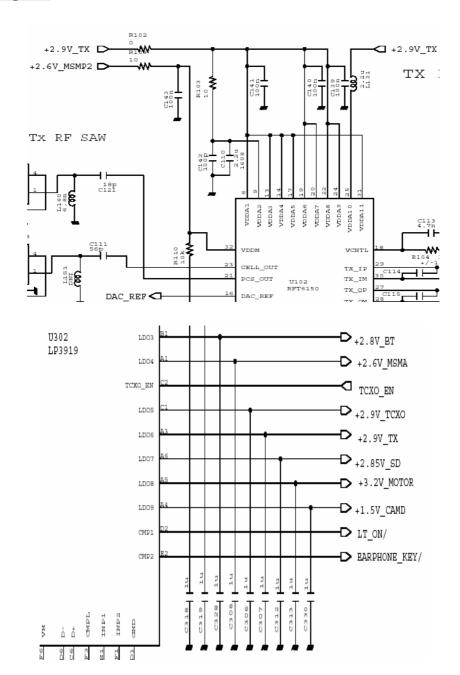
TEST POINT



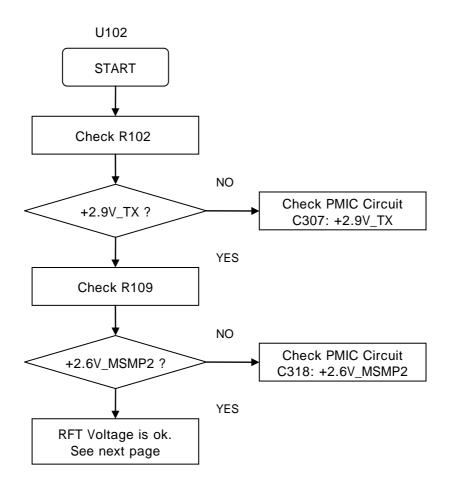
<RFT6150:+2.9V_TX, +2.6V_MSMP2>



< PMIC :+2.9V_TX, +2.6V_MSMP2 >



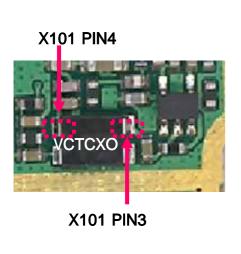
<RFT6150 & PMIC +2.9V_TX, +2.6V_MSMP2 circuit>

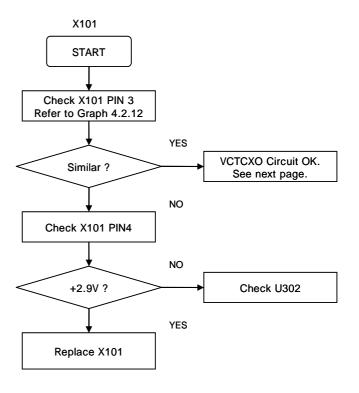


4.2.1.2. Check VCTCXO Circuit

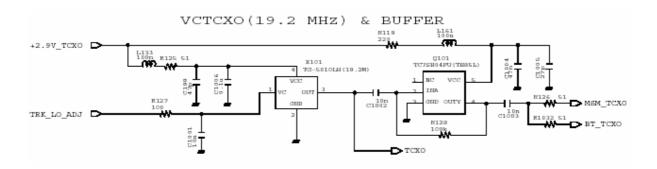
Test Point

Checking Flow

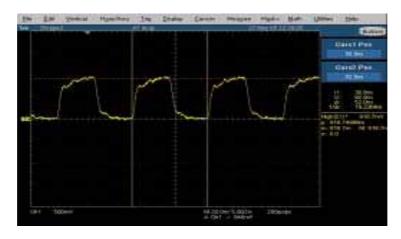




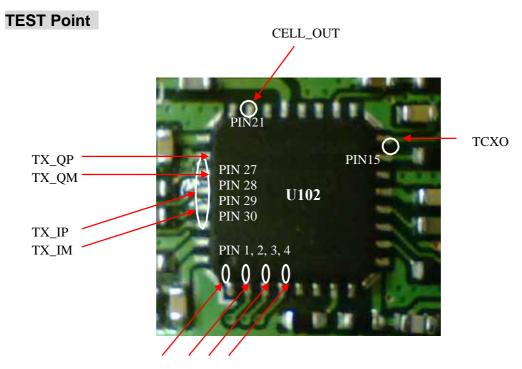
Circuit Diagram



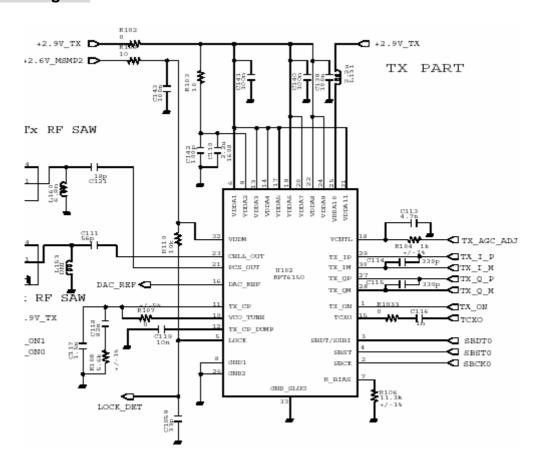
TCXO Waveform

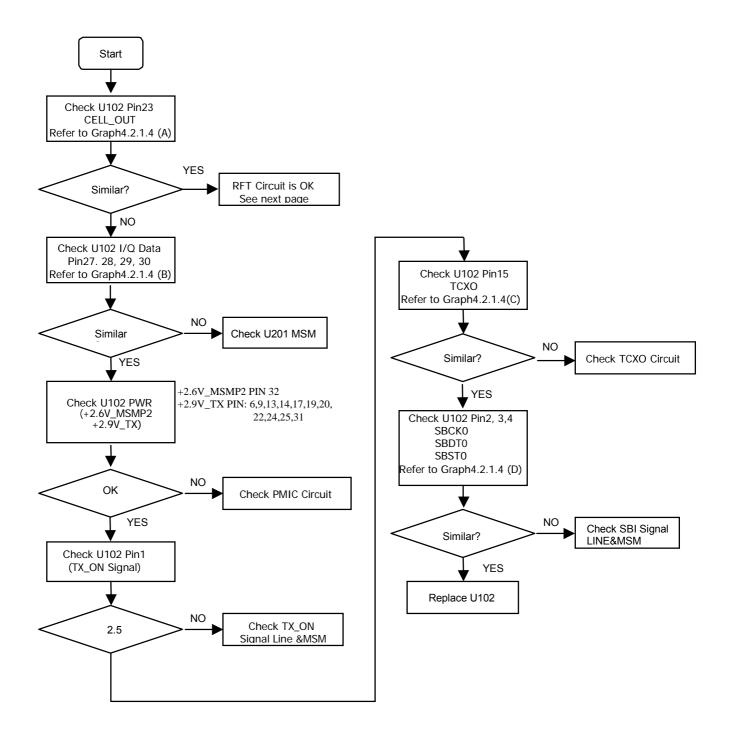


4.2.1.4. Check RFT Circuit

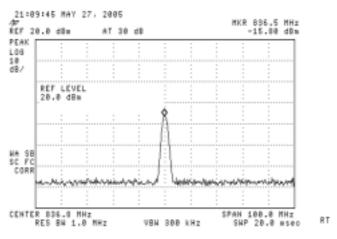


TX_ON, SBCK0, SBDT0, SBST0





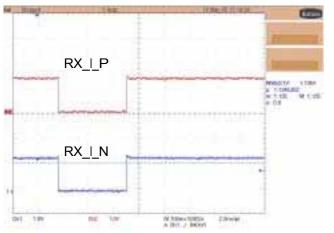
Waveform



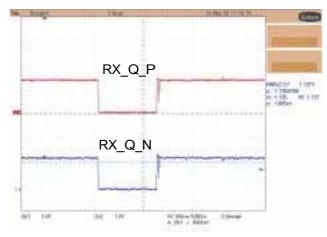


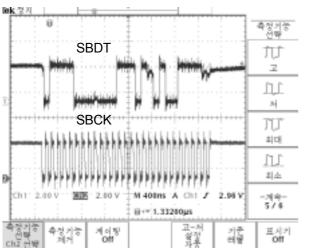


Graph 4.2.1.4(C)









Graph 4.2.1.4(D)



4.2.1.5. Check DCN RF TX SAW

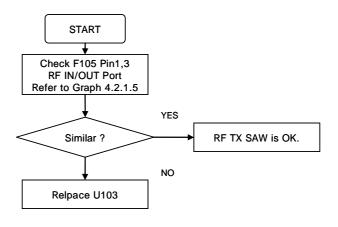
Test Point

PIN3 RF OUT

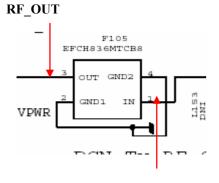


PIN1 RF IN

Checking Flow

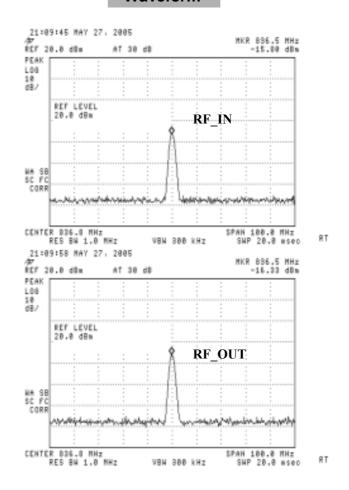


Circuit Diagram

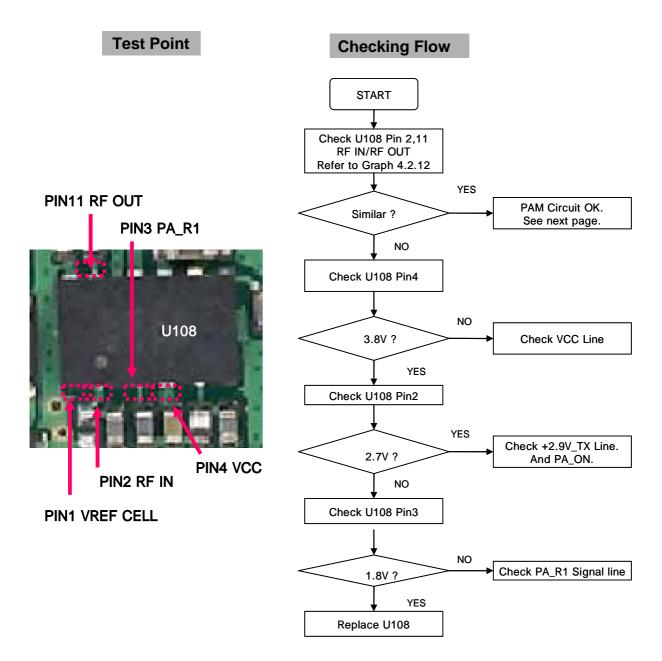


RF_IN

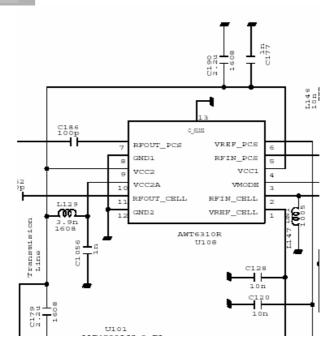
Waveform



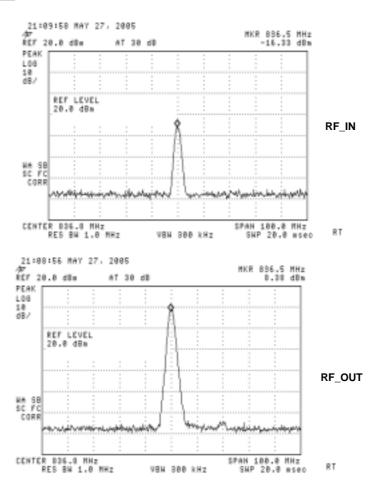
4.2.1.6. Check DCN PAM Circuit



Circuit Diagram



Waveform

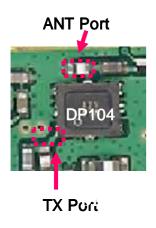


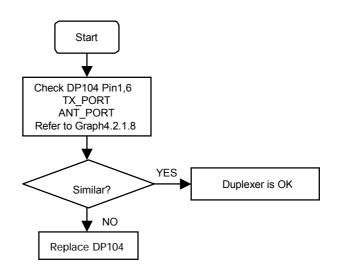
Graph 4.2.1.6

4.2.1.7. Check DCN Duplexer

Test Point

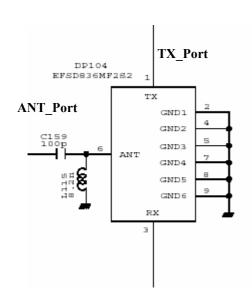
Checking Flow

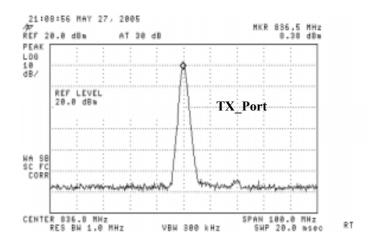


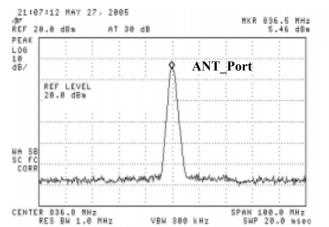


Circuit Diagram

Waveform







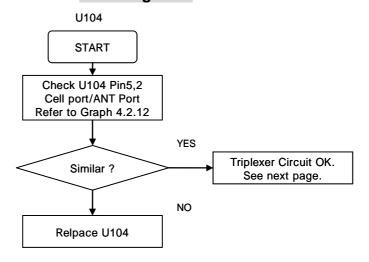
RT

4.2.1.8 Chcek Triplexer

Test Point

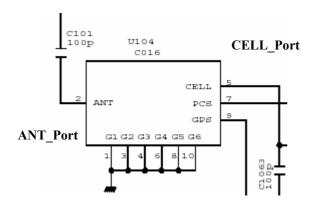
ANT Port

Checking Flow

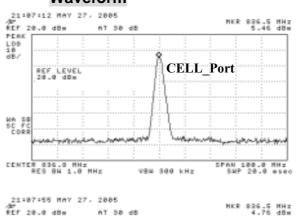


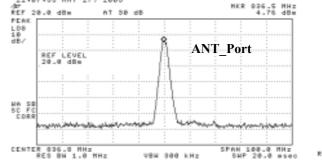
Circuit Diagram

Cell port



Waveform

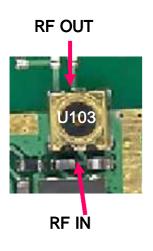


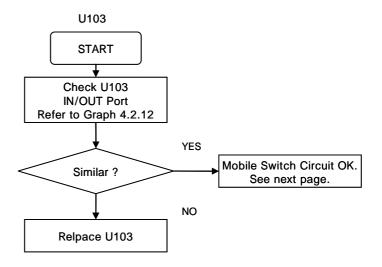


4.2.1.9 Chcek Mobile Switch

Test Point

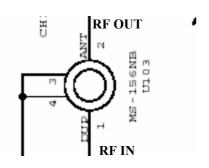
Checking Flow

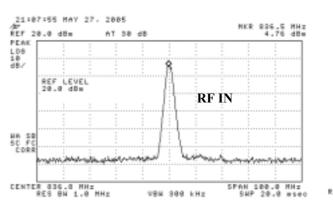


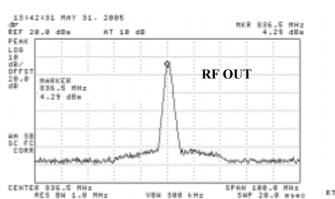


Circuit Diagram

Waveform



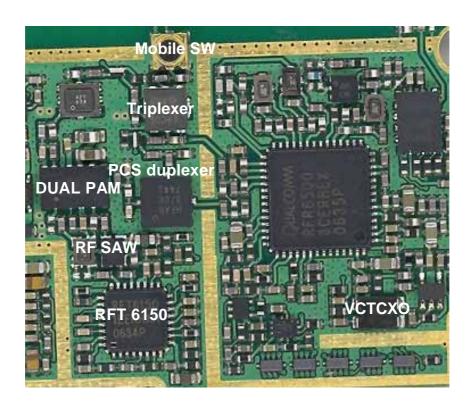


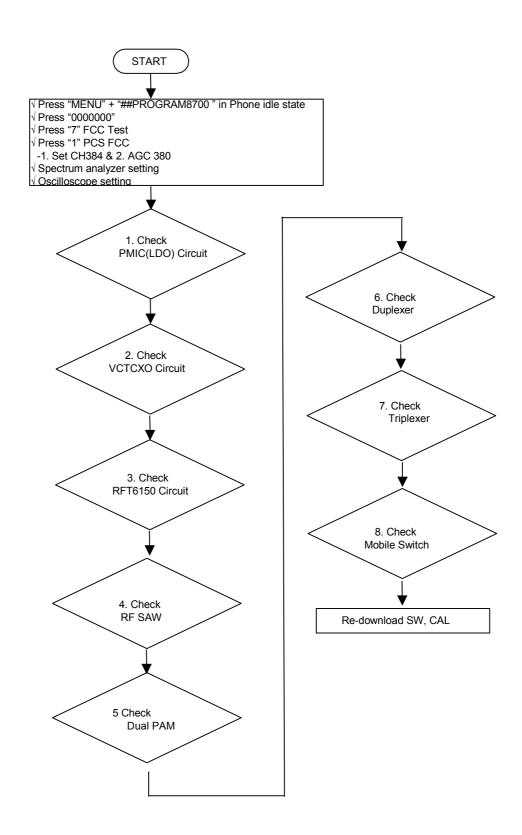


Graph 4.2.1.9

4.2.2 PCS TX Trouble

Test Point





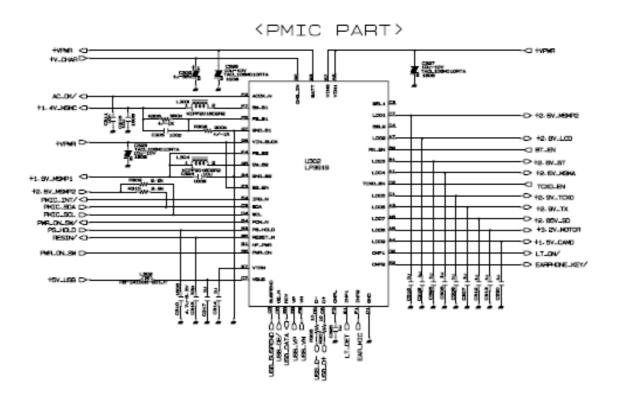
4.2.2.1. Check Regulator Circuit

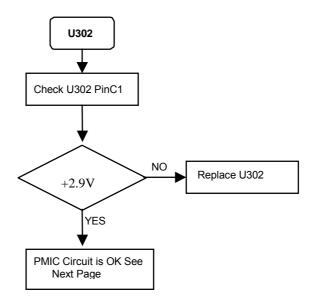
TEST POINT



<+2.9V_TCXO>

Circuit Diagram



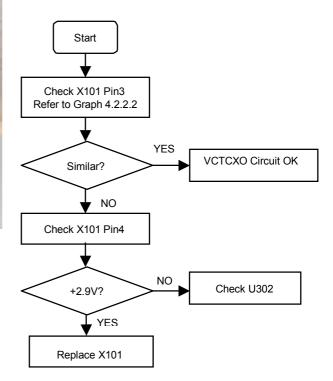


4.2.2.2. Check VCTCXO Circuit

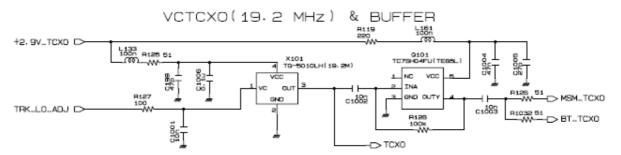
Test Point

+2.9V iTCXb Pin 4 X101 TCXO_OUT Pin 3

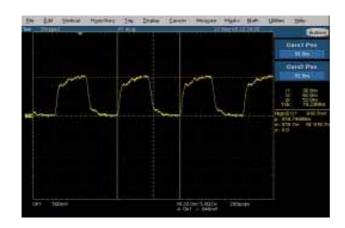
Checking Flow



Circuit Diagram



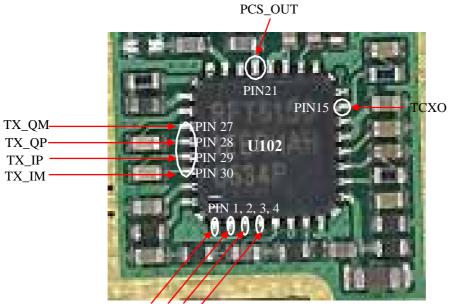
Waveform



Graph 4.2.2.2

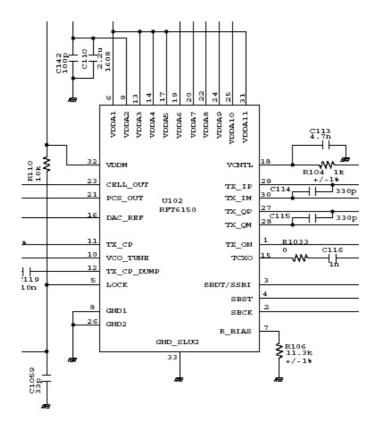
4.2.2.3. Check RFT6150 Circuit

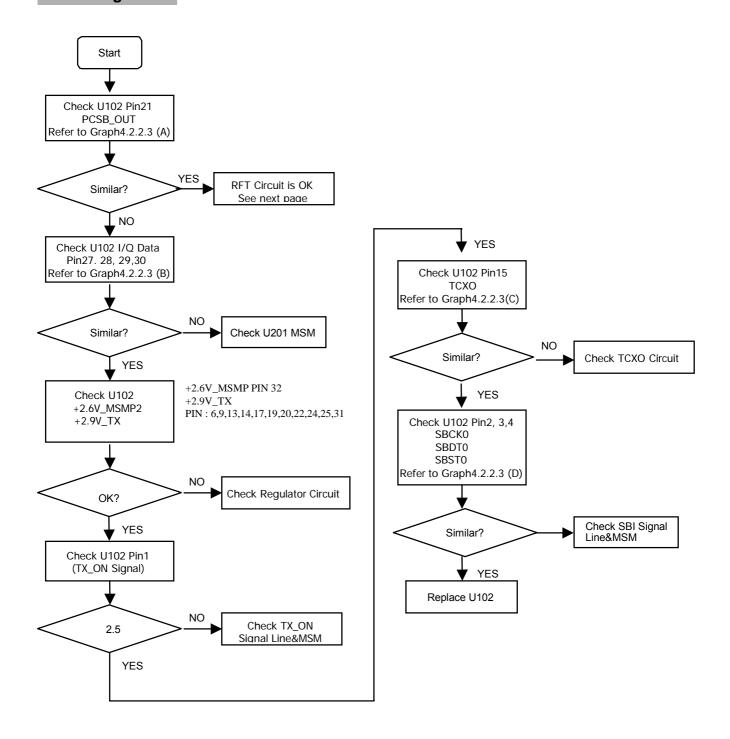
Test Point



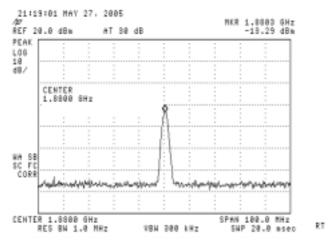
TX_ON, SBCK0, SBDT0, SBST0

Circuit Diagram





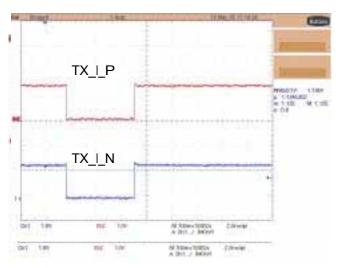
Waveform

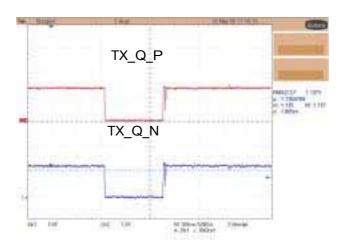




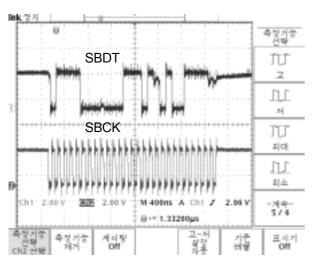
Graph 4.2.2.3(A)

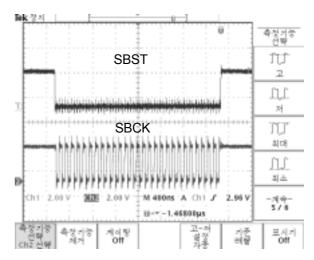
Graph 4.2.2.3(C)





Graph 4.2.2.3(B)



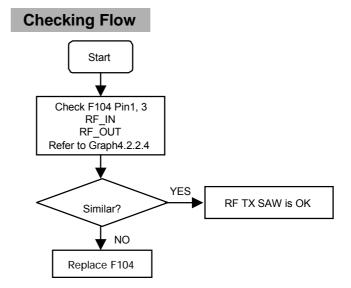


Graph 4.2.2.3(D)

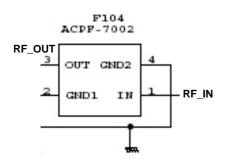
4.2.2.4. Check PCS RF TX SAW

Test Point

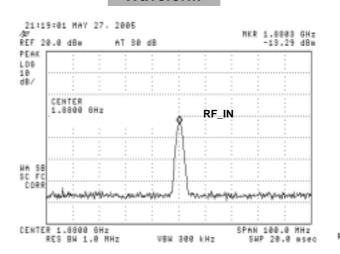


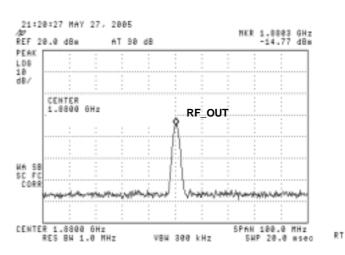


Circuit Diagram

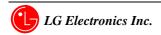


Waveform





Graph4.2.2.4

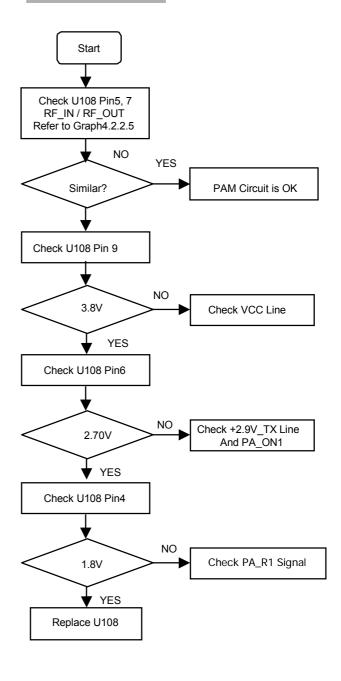


4.2.2.5. Check PCS PAM Circuit

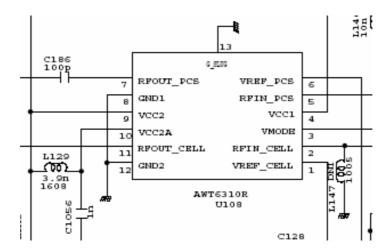
Test Point



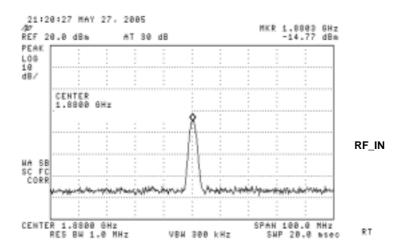
PA_R1 RF_IN VREF_PCS

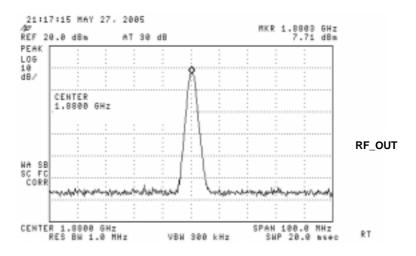


Circuit Diagram



Waveform

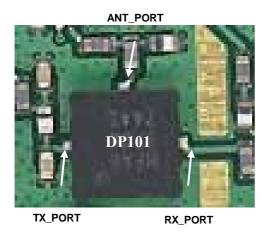




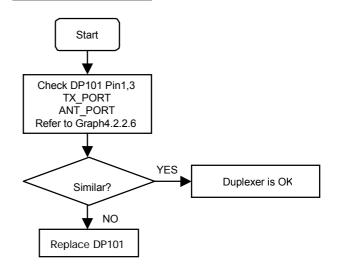
Graph 4.2.2.5

4.2.2.6. Check PCS Duplexer

Test Point

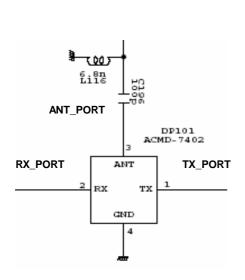


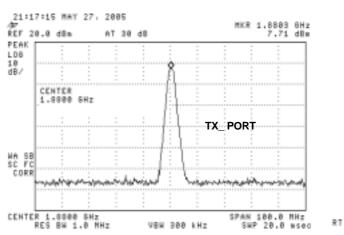
Checking Flow

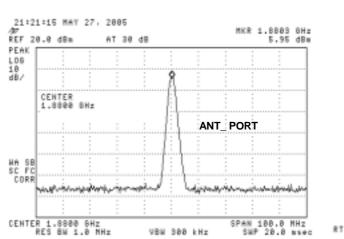




Waveform





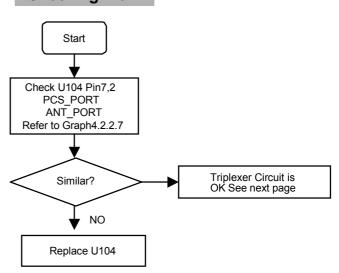


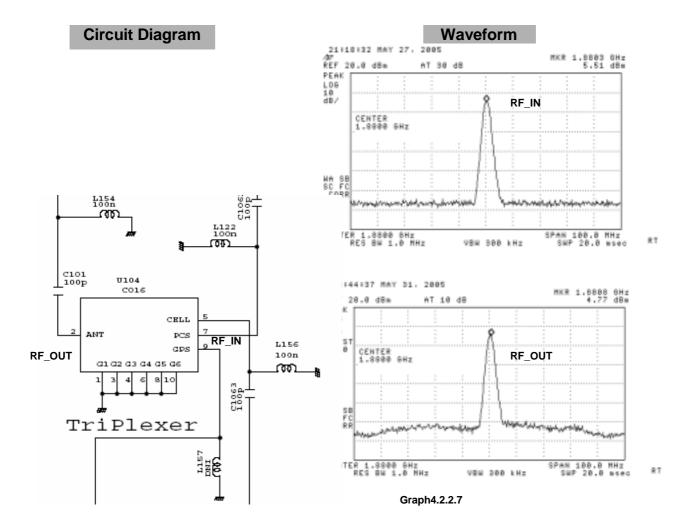
Graph4.2.2.6

4.2.2.7. Check Triplexer

Test Point

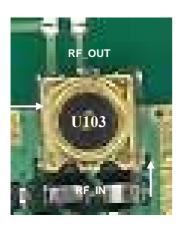
U104



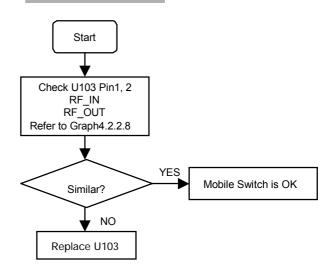


4.2.2.8. Check Mobile Switch

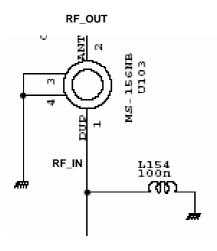
Test Point



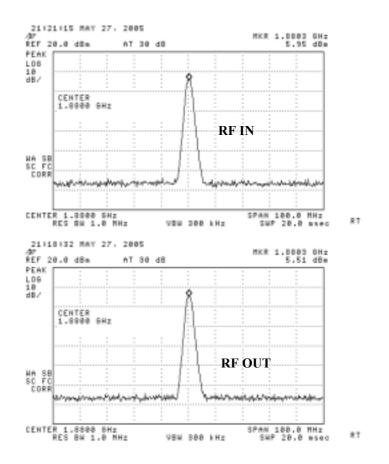
Checking Flow



Circuit Diagram



Waveform



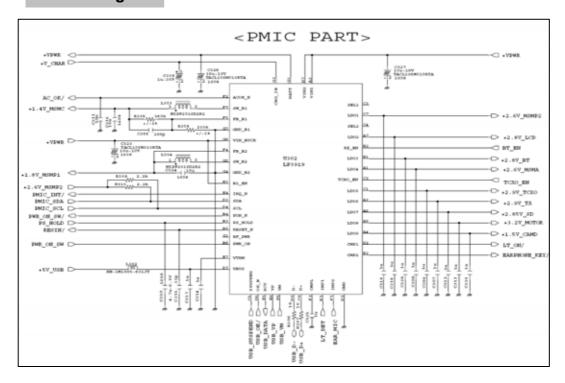
Graph 4.2.2.8

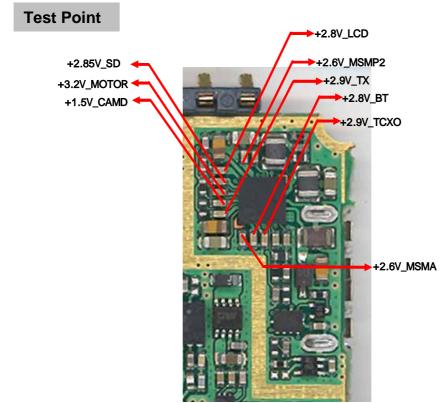
4.3 Logic Part Trouble

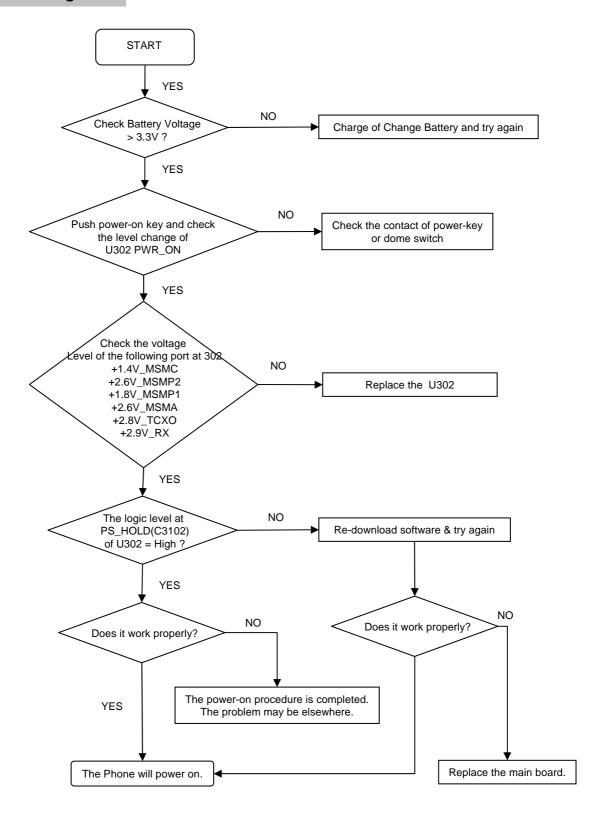
4.3.1 Power

4.3.1.1 Power-On Trouble

Circuit Diagram

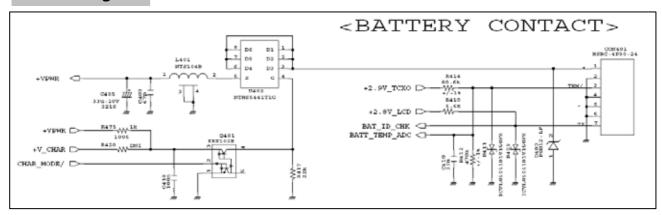


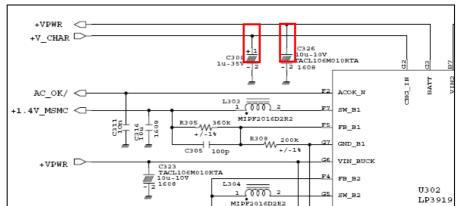




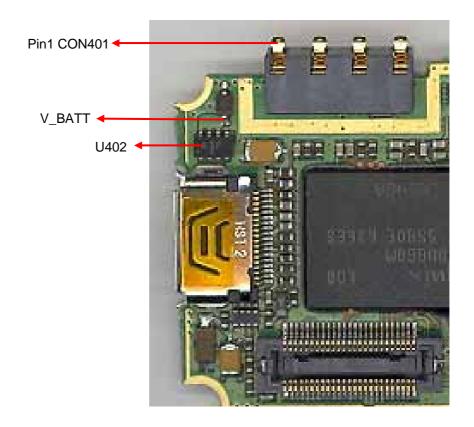
4.3.1.2 Charging Trouble

Circuit Diagram

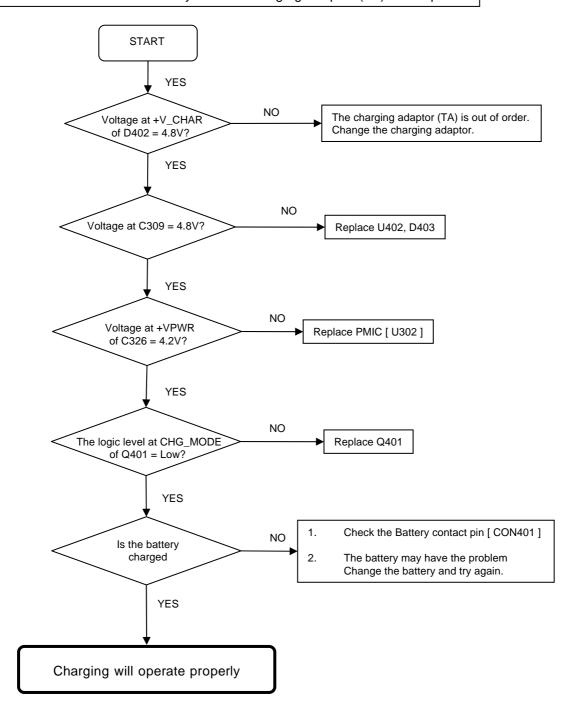




Test Points



SETTING: Connect the battery and the charging adaptor (TA) to the phone



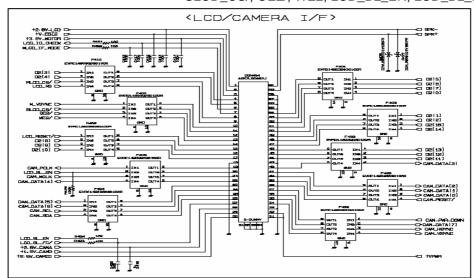
4.3.2 LCD

4.3.2.1 LCD Trouble

Circuit Diagram

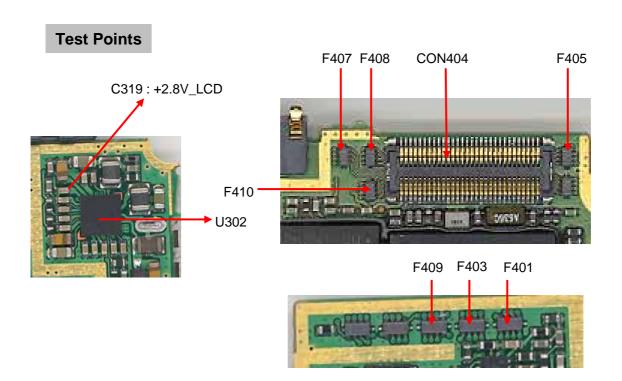
• LCD Control signals

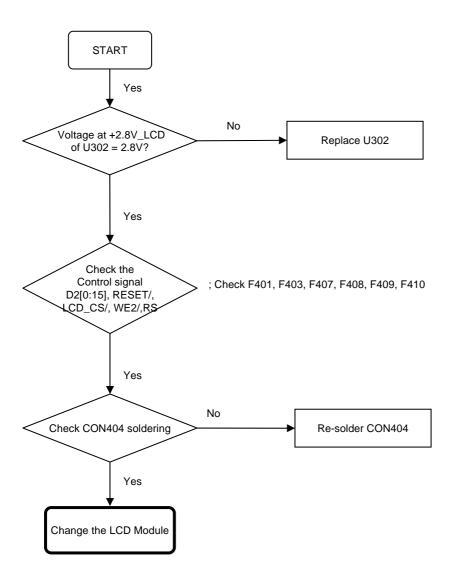
From MSM: D2[0:15], LCD_RESET/, SLCD_RESET/, MLCD_IF_MODE, LCD_RS, M_VSYNC, MLCD_CS/, SLCD_CS/, OE2/, WE2, LCD_BL_EN, LCD_BL_FC/



• Check point

- The assembly status of the LCD Module
- The status of Connector connection
- The Soldering of connector

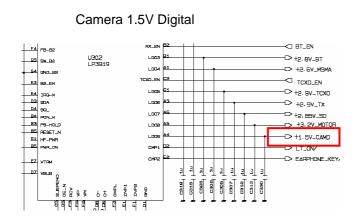


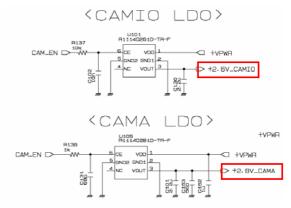


4.3.3 Camera

4.3.3.1 Camera Trouble

Circuit Diagram

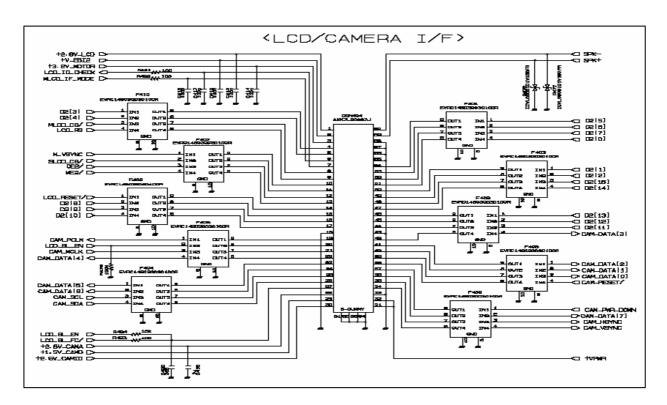




• Camera Control signals

From MSM: CAM_RESET/,CAM_MCLK, CAM_SCL, CAM_SDA,

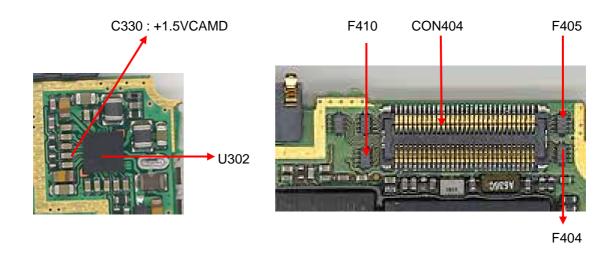
To MSM: CAM_PCLK, CAM_DATA[0:7], CAM_VSYNC, CAM_HSYNC

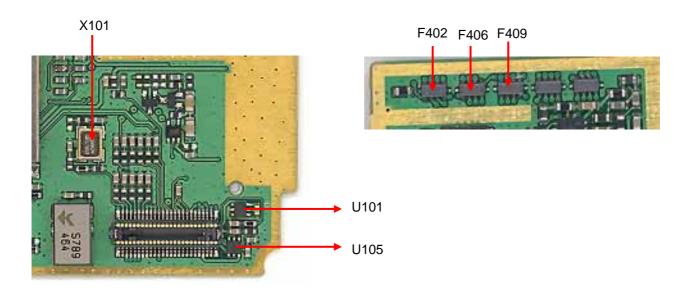


Test Points

• Check point

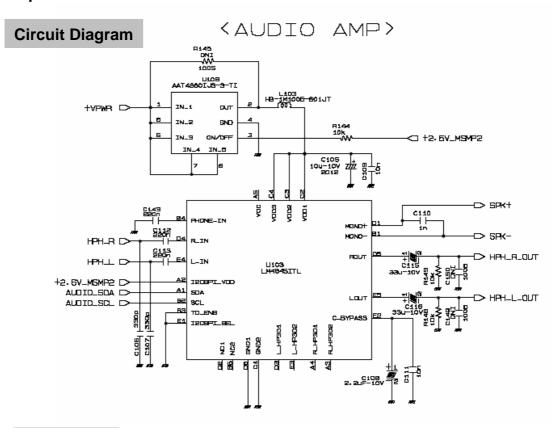
- The assembly status of the Camera Module
- The Soldering of connector



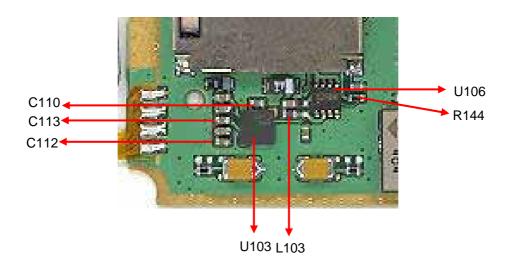


4.3.4 Audio

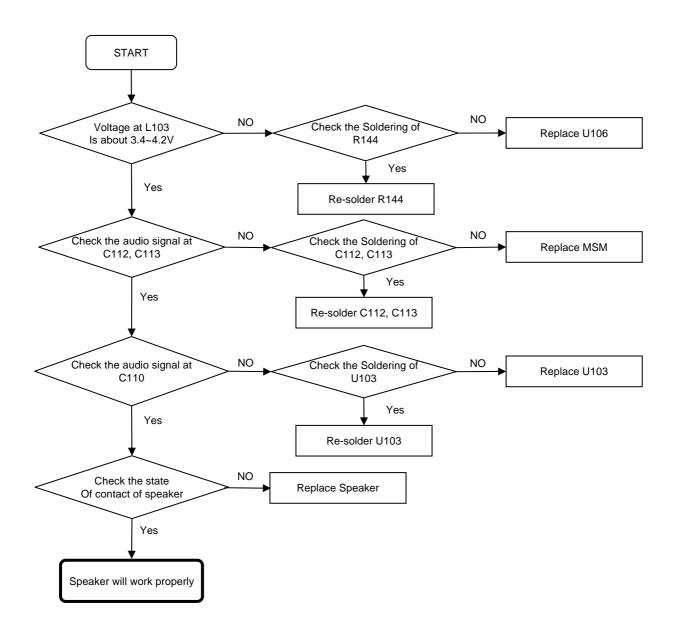
4.3.4.1 Speaker Trouble



Test Points

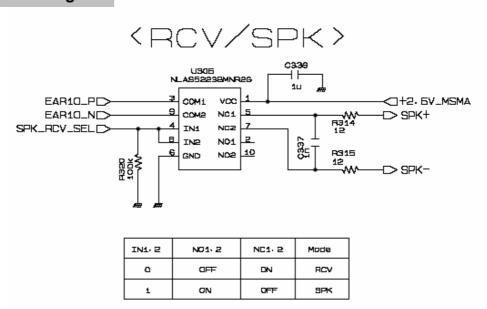


SETTING: "Melody on" at sounds of test menu.

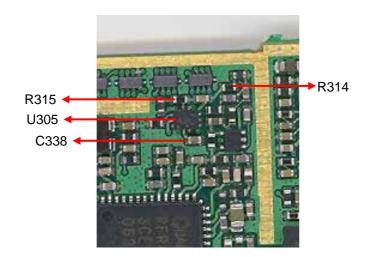


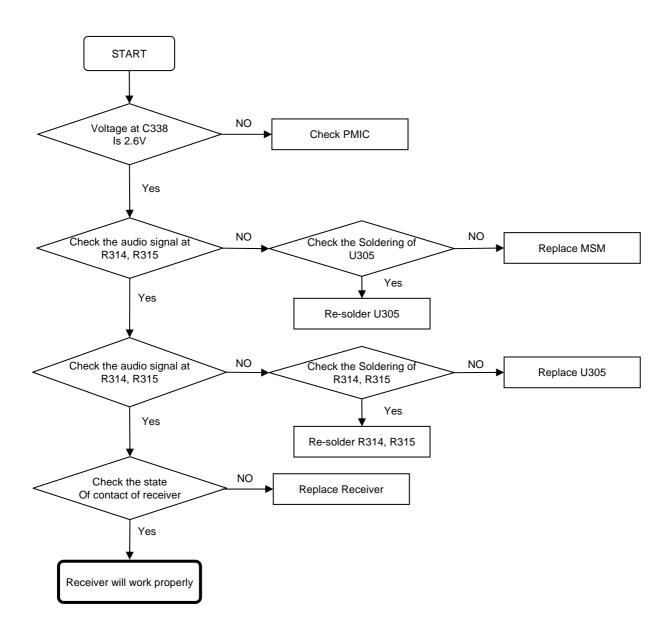
4.3.4.2 Receiver Trouble

Circuit Diagram



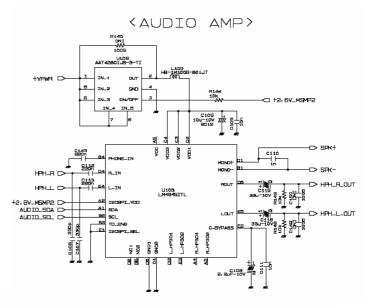
Test Points

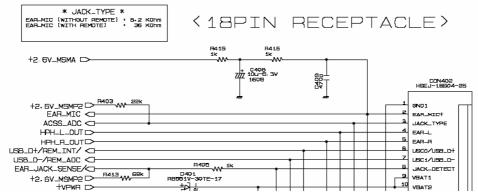




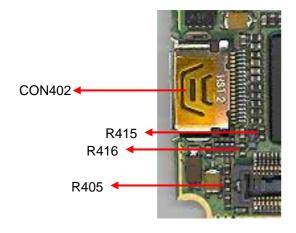
4.3.4.4 Headset Trouble

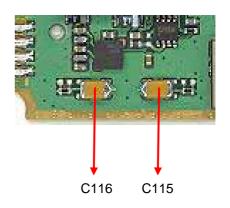
Circuit Diagram

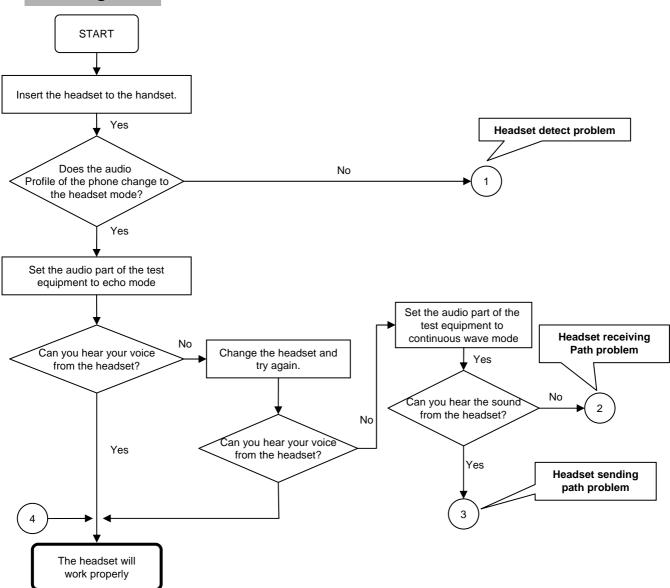




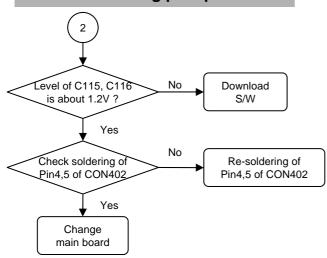
Test Points



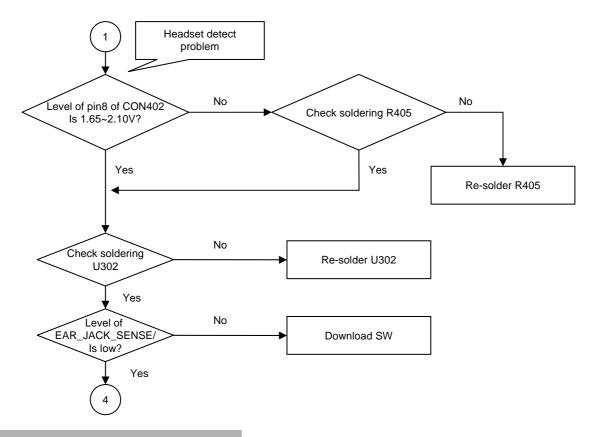




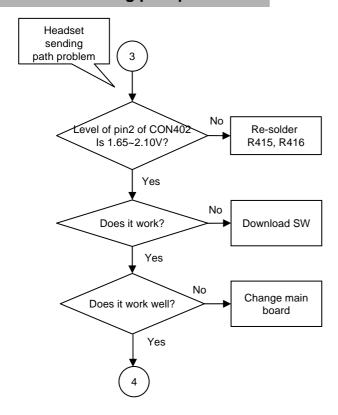
Headset receiving path problem



Headset detect problem

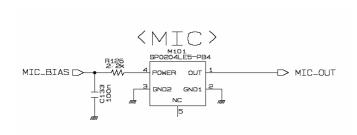


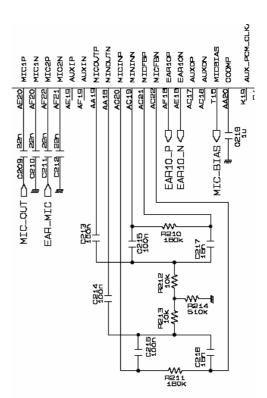
Headset sending path problem



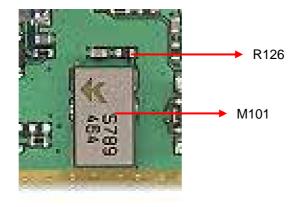
4.3.4.3 Mic Trouble

Circuit Diagram

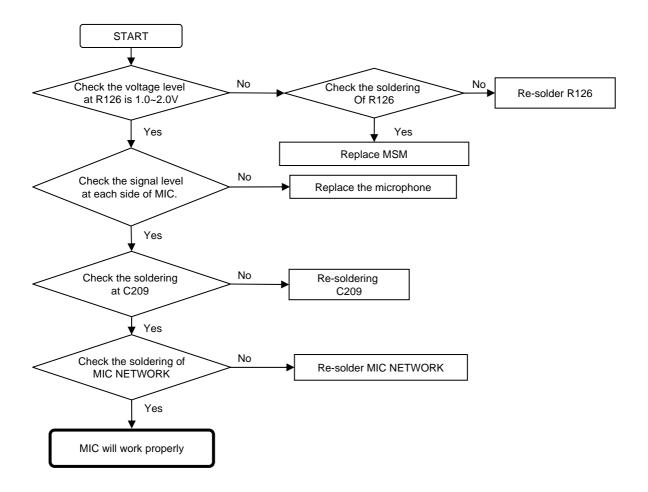


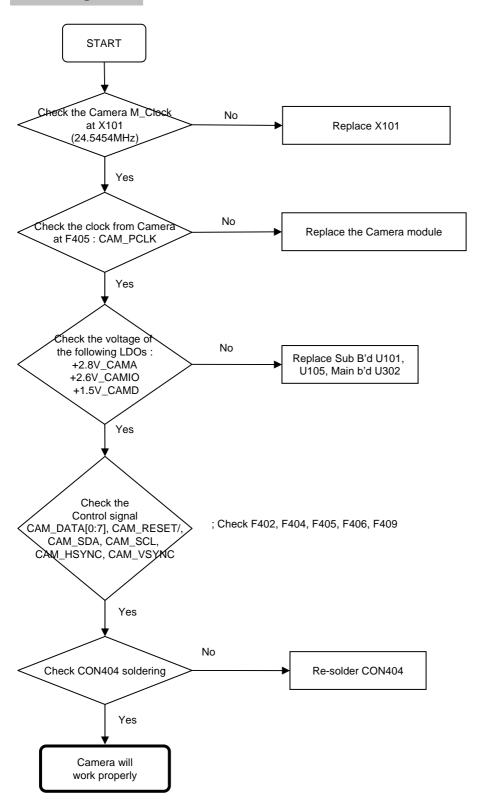


Test Points



SETTING: After initialize 5515C, Test Cellular

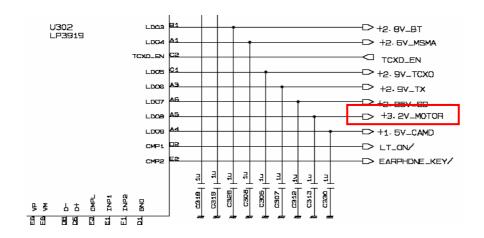




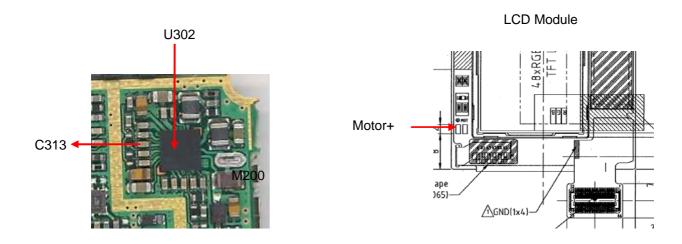
4.3.6 Vibrator, Micro SD Detect, and USB Interface

4.3.6.1 Vibrator

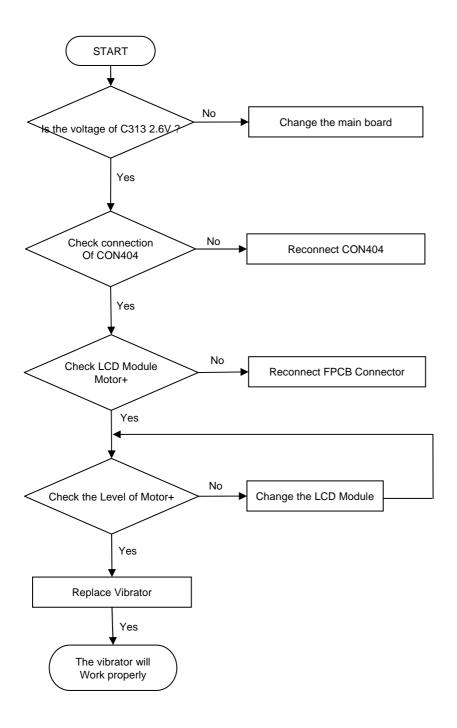
Circuit Diagram



Test Points

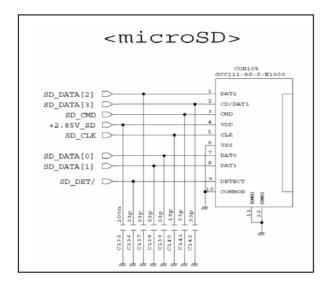


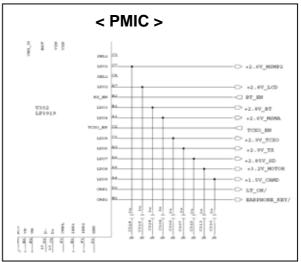
SETTING: "Vibrator on" at Sounds of test menu



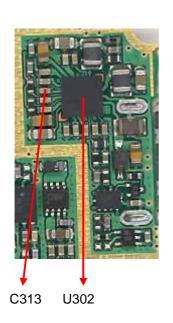
4.3.6.2 Micro SD Detect

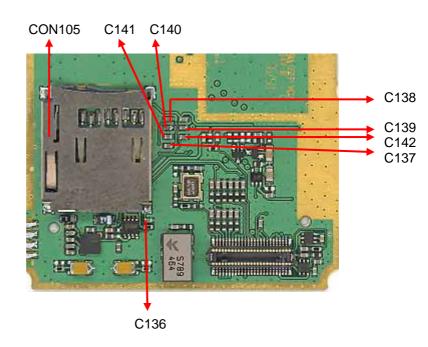
Circuit Diagram





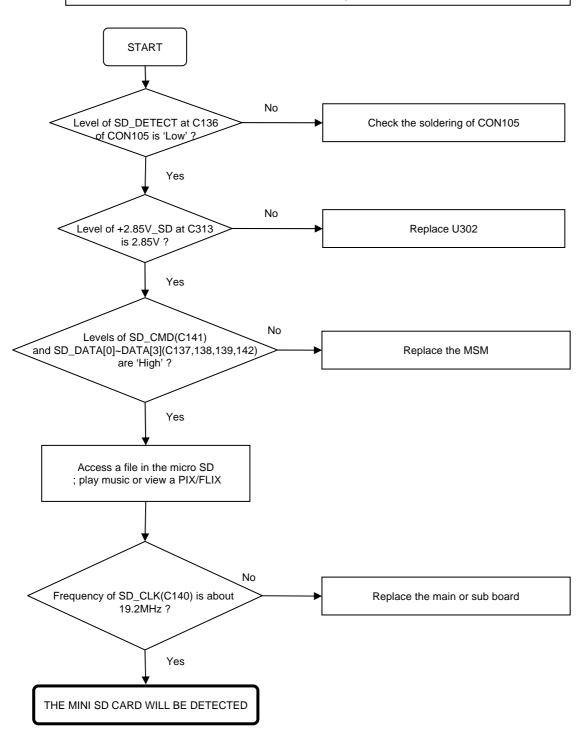
Test Points





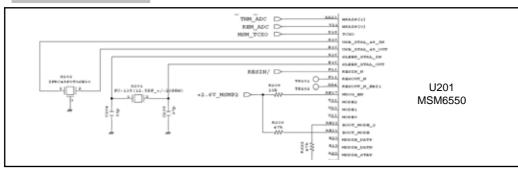
Checking Flow

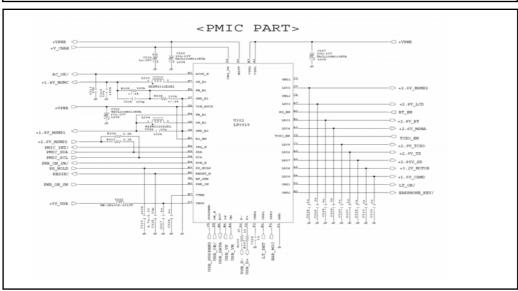
SETTING: Insert the mini SD card into the phone

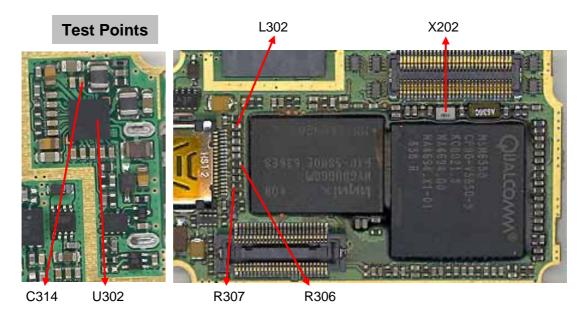


4.3.6.3 USB Interface

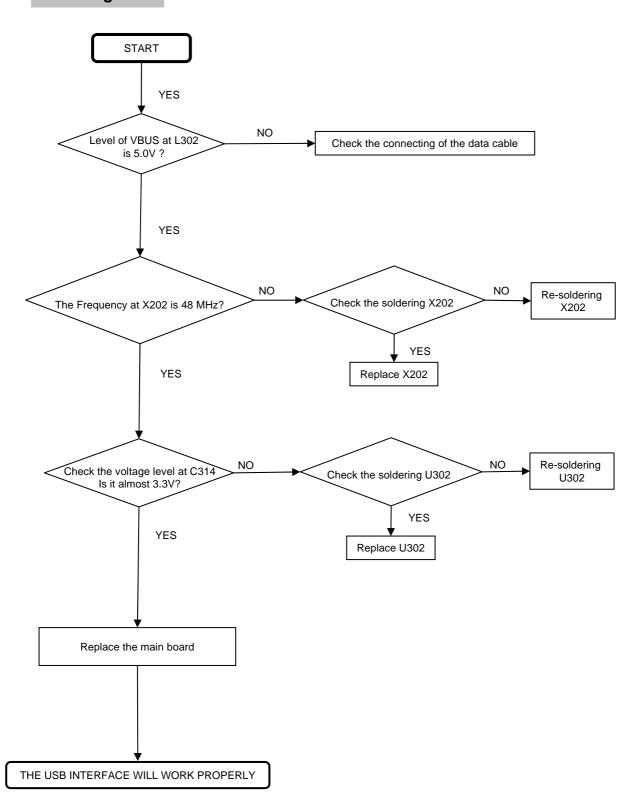
Circuit Diagram







Checking Flow



CHAPTER 5. Safety

IMPORTANT

Read This Information Before Using Your Hand-Held Portable Cellular Telephone

First introduction in 1984, the hand-held portable Cellular telephone is one of the most exciting and innovative electronic products ever developed.

With it you can stay in contact with your office, your home, emergency service, and others. For the safe and efficient operation of your phone, observe these guidelines.

Your Cellular phone is a radio transmitter and receiver. When it is ON, it receives and also sends out radio frequency (RF) energy. The phone operates in the frequency range of 824 MHz to 894 MHz and employs commonly used frequency modulation (FM) techniques. When you use your phone, the Cellular system handling your calls controls the power level at which your phone transmits. The power level can range from 0.006 of a watt to .6 of a watt.

Exposure to Radio Frequency Energy

In 1991 the Institute of Electrical and Electronics Engineers (IEEE), and in 1992 the American National Standards Institute (ANSI) updates the 1982 ANSI Standard for safety levels with respect to human exposure to RF energy. Over 120 scientists, engineers, and physicians from universities, government health agencies, and industry, after reviewing the available boy of research, developed this updated Standard. In March, 1993, the US Federal Communications Commission (FCC) proposed the adoption of this updated Standard.

The design of your phone complies with this updated Standard. Of course, if you want to limit RF exposure even further than the updated ANSI Standard, you may choose to control the duration of your calls and opration your phone in the most power efficient manner.

Efficient Phone Operation

For your phone to operate at the lowest power level, consistent with satisfactory call quality, please observe the following guidelines:

If your phone has an extendable antenna, extend it fully. Some models allow you to place a call with the antenna retracted. However, your phone operates more efficiently with the antenna fully extended.

Hold the phone as you would any other telephone. While speaking directly into the mouthpiece, position the antenna up and over your shoulder.

Do not hold the antenna when the phone is "IN USE". Holding the antenna affects call quality and may cause the phone to operated at a higher power level than needed.

Antenna Care and Replacement

Do not use the phone with a damaged antenna. If a damaged antenna comes into contact with skin, a minor bum may result. Replace a damaged antenna immediately. Consult your manual to see if you may change your antenna yourself. If so, use only a manufacture approves antenna. Otherwise, take your phone to a qualifies service center for repair.

Use only the supplied or approved antenna. Non-approved antennas, modifications, or attachments, could impair call quality, damage the phone, and violate FCC egulations.

Driving



Check the laws and regulations on the use of Cellular telephones in the areas where you drive. Always obey them. Also, when using your phone while driving, please:

Give full attention to the driving. Use hands-free operation, if available, and pull off the road and park before making or answering a call if driving conditions require.

Electronic Devices

Most modem electronic equipment is shielded from RF energy. However, RF energy from Cellular telephones may affect inadequately shielded electronic equipment.

RF energy may effect improperly installed or inadequately shielded electronic operating and entertainment system in motor vehicles. Check with the manufacturer or its representative to determine if these systems are adequately shielded from external RF energy. You should check with the manufacturer of any equipment that has been added to your vehicle.

Consult the manufacturer of any personal medical devices (such as pacemakers, hearing aids, etc.) to determine if they are adequately shielded from external RF energy.

Turn your phone OFF in health care facilities. When any regulations posted in the areas instruct you to do so. Hospitals or health care facilities may be using equipment that could be sensitive to external RF energy.

Aircraft

Turn your phone OFF before boarding any aircraft.

Use it on the ground only with crew permission. Do not use it in the air.

To prevent possible interference with aircraft systems, US Federal Aviation Administration (FAA) regulations require you to have permission from a crew member to use your phone while the plane is on the ground. Using your phone while the plane is in the air.

Children

Do not allow children to play with your phone. It is not a toy. Children could hurt themselves or others (by poking themselves or others in the eye with the antenna, for example). Children also could damage the phone, or make calls that increase your telephone bills.

Blasting Areas

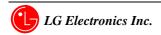
To avoid interfering with blasting operations, turn you unit OFF when in a "blasting area" or in areas posted "Turn off two-way radio". Construction crews often use remote control RF devices to set off explosives.

Potentially Explosive Atmospheres

Turn your phone OFF when in any area with a potentially explosive atmosphere. It is rare, but your phone or accessories could generate sparks. Sparks in such area could cause an explosion or fire resulting in bodily injury or even death.

Areas with a potentially explosive atmosphere are often, but not always, clearly marked. They include fueling areas such as gas station; below deck on boats; fuel or chemical transfer or storage facilities; areas where the air contains chemical or particles, such as grain, dust, or metal powders; and any other area where you would normally be advised to turn off your vehicle engine.

Do not transport or store flammable gas, liquid, or explosives in the compartment of your vehicle which contains your phone or accessories.



Vehicles using liquefied petroleum gas (such as propane or butane) must compl7y with the National Fire Protection Standard (NFPA-58). For a copy of this standard, contact the National Fire Protection Association, One Battery march Park, Quincy, MA 02269, Attn: Publication Sales Division.

Rule of Thumb: Using common sense at all times when handling, installing or using the phone. Any questions should be directed to you nearest Service Center or authorized service technician or electrician.

CHAPTER 6. Glossary

General Terms

Abbreviated Alert. An abbreviated alert is used to remind the mobile station user that previously selected alternative routing features are still active.

AC. See Authentication Center.

Access Attempt. A sequence of one or more access probe sequences on the Access Channel containing the same message. See also Access Probe and Access Probe Sequence.

Access Channel. A Reserve CDMA Channel used by mobile stations for communicating to the base station. The Access Channel is used for short signaling message exchanges such as call origination's, responses to pages, and registrations. The Access Channel is a slotted random access channel.

Access Channel Message. The information part of an access probe consisting of the message body, length field, and CRC.

Access Channel Message Capsule. An Access Channel message plus the padding.

Access Channel Preamble. The preamble of an access probe consisting of a sequence of all-zero frames that is sent at the 4800bps rate.

Access Channel Request Message. An Access Channel message that is autonomously generated by the mobile station. See also Access Channel Response Message.

Access Channel Response Message. A message on the Access Channel generated to reply to a message received from the base station.

Access Channel Slot. The assigned time interval for an access probe. An Access Channel slot consists of an integer number of frames. The transmission of an access probe is performed within the boundaries of an Access Channel slot.

Access Probe. One Access Channel transmission consisting of a preamble and a message. The transmission is an integer number of frames in length and transmits one Access Channel message. See also Access Probe Sequence and Access Attempt.

Access Probe Sequence. A sequence of one or more access probes on the Access Channel. The same Access Channel message is transmitted in every access probe of an access attempt. See also Access Probe and Access Attempt.

Acknowledgement. A Layer 2 response by the mobile station or the base station confirming that a signaling message was received correctly.

Action Time. The time at which the action implied by a message should take effect.

Active Set. The set of pilots associated with the CDMA Channels containing Forward Traffic Channels assigned to a particular mobile station.

Aging. A mechanism through which the mobile station maintains in its Neighbor Set the pilots that have been recently sent to it from the base station and the pilots whose handoff drop timers have recently expired.

A-key. A secret, 64-bit pattern stored in the mobile station. It is used to generate update the mobile station's Shared Secret Data. The A-key is used in the mobile station authentication process.

Analog Access Channel. An analog control channel used by a mobile station to access a system to obtain



service.

Analog Color-Code. An analog signal (see Supervisory Audio Tone) transmitted by a base station on an analog voice channel and used to detect capture of a mobile station by an interfering base station or the capture of a base station by an interfering mobile station.

Analog Control Channel. An analog channel used for the transmission of digital control information from a base station to a mobile station or from a mobile station to a base station.

Analog Paging Channel. A forward analog control channel that is used to page mobile stations and send orders. **Analog Voice Channel.** An analog channel on which a voice conversation occurs and on which brief digital messages may be sent from a base station to a mobile station or from a mobile station to a base station.

Authentication. A procedure used by a base station to validate a mobile station's identity.

Authentication Center (AC). An entity that manages the authentication information related to the mobile station.

Authentication Response (AUTHR). An 18-bit output of the authentication algorithm. It is used, for example, to validate mobile station registrations, origination and terminations. A method of registration in which the mobile station registers without an explicit command from the base station.

AWGN. Additive White Gaussian Noise.

Bad Frames. Frames classified as erasures (frame category 10) or 9600 bps frames, primary traffic only with bit errors (frame category 9). See also Good Frames.

Base Station. A station in the Domestic Public Cellular Radio Telecommunications Service, other than a mobile station, used for communicating with mobile stations. Depending upon the context, the term base station may refer to a cell, a sector within a cell, an MSC, or other part of the Cellular system. See also MSC.

Base Station Authentication Response (AUTHBS). An 18-bit pattern generated by the authentication algorithm. AUTHBS is used to confirm the validity of base station orders to update the Shared Secret Data.

Base Station Random Variable (RANDBS). A 32-bit random number generated by the mobile station for authenticating base station orders to update the Shared Secret Data.

BCH Code. See Bose-Chaudhuri-Hocquenghem Code.

Busy-Idle Bits. The portion of the data stream transmitted by a base station on a forward analog control channel that is used to indicate the current busy-idle status of the corresponding reverse analog control channel.

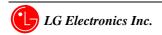
Call Disconnect. The process that releases the resources handling a particular call. The disconnect process beings either when the mobile station user indicates the end of the call by generating an on-hook condition or other call release mechanism, or when the base station initiates a release.

Call History Parameter(COUNT). A modulo-64 event counter maintained by the mobile station and Authentication Center that us used for clone detection.

Candidate Set. The set of pilots that have been received with sufficient strength by the mobile station to be successfully demodulated, but have not been placed in the Active Set by the base station. See also Active Set. Neighbor Set, and Remaining Set.

. See Code Division Multiple Access

CDMA Channel. The set of channels transmitted between the base station within a given CDMA frequency assignment. See also Forward CDMA Channel and Reverse CDMA Channel.



CDMA Channel Number. An 11-bit number corresponding to the center of the CDMA frequency assignment.

CDMA Frequency Assignment. A 1.23MHz segment of spectrum centered on one of the 30KHz channels of the existing analog system.

Code Channel. A subchannel of a Forward CDMA Channels. A Forward CDMA Channel contains 64 code channels. Code channel zero is assigned to the Pilot Channel. Code channels 1 through 7 may be assigned to the either Paging Channels or the Traffic Channels. Code Channel 32 may be assigned to either a Sync Channel or a Traffic Channel. The remaining code channels may be assigned to Traffic Channels.

Code Division Multiple Access (CDMA). A technique for spread-spectrum multiple-access digital communications that creates channels through the use of unique code sequences.

Code Symbol. The output of an error-correcting encoder. Information bits are input to the encoder and code symbols are output from the encoder. See Convolutional Code.

Continuous Transmission. A mode of operation in which Discontinuous Transmission is not permitted.

Control Mobile Attenuation Code(CMAC). A 3-bit field in the Control-Filler Message that specifies the maximum authorized power level for a mobile transmitting on an analog reverse control channels.

Convolution Code. A type of error-correcting code. A code symbol can be considered as the convolution of the input data sequence with the impulse response of a generator function.

CRC. See Cyclic Redundancy Code.

Cyclic Redundancy Code (CRC). A class of linear error detecting codes which generate parity check bits by finding the remainder of a polynomial division.

Data Burst Randomizer. The function that determines which power control groups within a frame are transmitted on the Reverse Traffic Channel when the data rate is lower than 9600 bps. The data burst randomizer determines, for each mobile station, the pseudo random position of the transmitted power control groups in the frame while guaranteeing that every modulation symbol is transmitted exactly once.

DBc. The ratio(in dB) of the sideband power of a signal, measured in a given bandwidth at a given frequency offset from the center frequency of the same signal, to the total inband power of the signal. For CDMA, the total inband power of the signal is measured in a 1.23MHz bandwidth around the center frequency of the CDMA signal.

DBm. A measure of power expressed in terms of its ration (in dB) to one milliwatt.

DBm/Hz. A measure of power spectral density. DBm/Hz is the power in one Hertz of bandwidth. Where power is expressed in units of dBm.

DBW. A measure of power expressed in terns of its ration (in dB) to one Watt.

Dedicated Control Channel. An analog conrtol channel used for the transmisson of digital control information from either a base station or a mobile station.

Deinterleaving. The process of unpermuting the symbols that were permuted by the interleaver..

Deinterleavering is performed on reveived symbols prior to decoding.

Digital Color Code(DCC). A digital signal transmitted by a base station on a forward analog control channel that is used to detect capture of a base station by an interfering mobile station.

Dim-and-Burst. A frame in which primary traffic is multiplexed with either secondary traffic or signaling traffic.

Discontinuous Transmission (DTX). A mode of operation in which a mobile station transmitter



autonomously switches between two transmitter power levels while the mobile station is in the conversation state on an analog voice channel.

Distance-Based Registration. An autonomous registration method in which the mobile station registers whenever it enters a cell whose distance from the cell in which the mobile station last registered exceeds a given threshold.

DTMF. See Dual Tone Multifrequency.

Dual-Tone Multifrequency(DTMF). Signaling by the simultaneous transmission of two tones, one from a group of low frequencies and another from a group of high frequencies. Each group of frequecies consists of four frequencies.

Eb. The energy of an information bit.

Ec/I0. The ratio in (dB) between the pilot energy accumulated over one PN chip period(Ec) to the power spectral density in the received bandwidth(Io).

Effective Radiated Power (ERP). The transmitted power multiplied by the antenna gain referenced to a half wave dipole.

Electronic Serial Number(ESN). A 32-bit number assigned by the mobile station manufacturer, uniquely identifying the mobile station equipment.

Encoder Tail Bits. A fixed sequence of bits added to the end of a block of data to reset the convolutional encoder to a known state.

ERP. See Effective Radiated Power.

ESN. See Electronic Serial Number.

Extended Protocol. An optional expansion of the signaling message between the base station and mobile station to allow for the addition of new system features and operational capabilities.

Fade Timer. A timer kept by the mobile station as a measure of Forward Traffic Channel continuity. If the Fade timer expires, the mobile station drops the call.

Flash. An indication sent on an analog voice channel or CDMA Traffic Channel indicating that the user Directed the mobile station to invoke special processing.

Foreign NID Roamer. A mobile station operating in the same system (SID) but a different network (NID)Form the one in which service was subscribed. See also Foreign SID Roamer and Roamer.

Foreign SID Roamer. A mobile station operating in a system (SID) other than the one from which service was subscribed. See also Foreign NID Roamer and Roamer.

Forward Analog Control Channel (FOCC). An analog voice channel used from a base station to a mobile station.

Forward Analog Voice Channel (FVC). An analog voice channel used from a base station to a mobile station.

Forward CDMA Channel. A CDMA Channel form a base station to mobile stations. The Forward CDMA Channel contains one or more code channels that are transmitted on a CDMA frequency assignment using a Particular pilot PN offset. The code channels are associated with the Pilot Channel, Sync Channel, Paging Channels, and Traffic Channels. The Forward CDMA Channel always carries a Pilot Channel and may carry up to one Sync Channel, up to seven Paging Channels, and up to 63 Traffic Channels, as long as the total number of channels, including the Pilot Channel, is no greater than 64.



Forward Traffic Channel. A code channel used to transport user and signaling traffic from the base station to the mobile station.

A basic timing interval in the system. For the Access Channel, Paging Channel, and Traffic Channel, a frame is 20 ms long. For the Sync Channel, a frame is 26.666...ms long.

Frame Category. A classification of a received Traffic Channel frame based upon transmission data rate, the Frame contents (primary traffic, secondary traffic, or signaling traffic), and whether there are detected error in the frame.

Frame Offset. A time skewing of Traffic Channel frames from System Time in integer multiples of 1.25 ms. The maximum frame offset is 18..75 ms..

Frame Quality Indicator. The CRC check applied to 9600 bps and 4800 bps Traffic Channel frames.

Global Positioning System (GPS). A US government satellite system that provides location and time Information to users. See Navstar GPS Space segment / Navigation User interfaces ICD-GPS-200 for Specifications.

Half Frame. A 10 ms interval on the paging Channel. Two half frames comprise a frame, the first half frame begins at the same time as the frame.

Handoff. The of transferring communication with a station mobile station from one base station to another.

Hard Handoff. A handoff characterized by a temporary disconnection of the Traffic Channel. Hard handoffs Occur when the mobile station is transferred between disjoint Active Sets, the CDMA frequency assignment changes, the frame offset changes, or the mobile station is directed from a CDMA Traffic Channel to an analog voice channel, See also Soft Handoff.

Hash Function. A function used by the mobile station to select one out of N available resource. The hash function distributes the available resources uniformly among a random sample of mobile stations.

HLR. See Home Location Register.

Home Location Register (HLR). The location register to which a MIN is assigned for record purposes such as subscriber information.

Home System. The Cellular system in which the mobile station subscribes for service.

Idle Handoff. The act of transferring reception of the Paging Channel from one bass station to another, when the mobile station is in the *Mobile Station Idle State*.

Implicit Registration. A registrationachieved by a successful transmission of an origination or page response on the Access Channel.

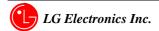
Interleaving. The process of permuting a sequence of symbols.

kHz. Kilohertz (10³ Hertz).

ksps. Kilo-symbols per second (10^3 symbols per second).

Layer 1. See Physical Layer.

Layer 2. Layer 2 provides for the correct transmission and reception of signaling messages, including partial



duplicate detection. See also Layering and Layer 3.

Layer 3. Layer 3 provides the control of the Cellular telephone systems. Signaling messages originate and terminate at layer 3. See also Layering and Layer 2.

Local Control. An optional mobile station feature used to perform manufacturer-specific functions.

A PN sequence with period 24²-1 that is used for scrambling on the Forward CDMA Channel and spreading on the Reverse CDMA Channel. The long code uniquely identifies a mobile station on both the Reverse Traffic Channel and the Forward Traffic Channel. The long code provides limited privacy. The long code also separates multiple Access Channels on the same CDMA channel. See also Public Long Code and Private Long Code.

Long Code Mask. A 42-bit binary number that creates the unique identity of the long code. See also Public Long Code, Private Long Code, Public Long Code Mask, and Private Long Code Mask.

LSB. Least significant bit.

Maximal Length Sequence (m-Sequence). A binary sequence of period 2n-1, n a positive integer, with no internal periodicities. A maximal length sequence can be generated by a tapped n-bit shift register with linear feedback.

Mcps. Megachips per second (10^6 chips per second).

Mean Input Power. The total received calorimetric power measured in a specified bandwidth at the antenna connector, including all internal and external signal and noise sources.

Mean Output Power. The total transmitted calorimetric power measured in a specified bandwidth at the antenna connector when the transmitter is active.

Message. A data structure that conveys control information or application information. A message consists of a length field (MSG_LENGTH), a message body (the part conveying the information), and a CRC.

Message Body. The part of the message contained between the length field (MSG_LENGTH) and the CRC field.

Message Capsule. A sequence of bits comprising a single message and padding. The padding always follows the message and may be of zero length.

Message CRC. The CRC associated with a message. See also Cyclic Redundancy Check.

Message Field. A basic named element in a message. A message field may consist of zero or more bits.

Message Record. An entry in a message consisting of one or more field that repeats in the message.

MHz. Megahertz.(10⁶ Herz)

MIN. See Mobile Station Identification Number.

Mobile Protocol Capability Indicator (MPCI). A 2-bit field used to indicate mobile station's capabilities.

Mobile Station. A station in the Domestic Public Cellular Radio Telecommunications Service intended to be used while in motion or during halts at unspecified points. Mobile station include portable units (e.g., handheld personal units) and units installed in vehicles.

Mobile Station Class. Mobile station classes define mobile station characteristics such as slotted operation and



transmission power.

Mobile Station Identification Number (MIN). The 34-bit number that is a digital representation of the 10-digit directory telephone number assigned to a mobile station.

Mobile Station Originated Call. A call originating from a mobile station.

Mobile Station Terminated Call. A call received by a mobile station (not to be confused with a disconnect or call release).

Mobile Switching Center (MSC). A configuration of equipment that provides Cellular radiotelephone service. Also called the Mobile Telephone Switching Office (MTSO)

Modulation Symbol. The output of the data modulator before spreading. On the Reverse Traffic Channel, 64-ary orthogonal modulation is used and six code symbol (when the data rate is 9600bps) or each repeated code symbol (when the data rate is less than 9600bps) is one modulation symbol.

Ms. Millisecond.

MSB. Most significant bit.

MSC. See Mobile Switching Center.

Multiplex Option. The ability of the multiplex sublayer and lower layer to be tailored to provide special capabilities. A multiplex option defines such characteristics as the frame format and the rate decision rules. See also Multiplex Sublayer.

Multiplex Sublayer. One of the conceptual layers of the system that multiplexes and demultiplexes primary traffic, secondary traffic, and signaling traffic.

NAM. See Number Assignment Module.

Narrow Analog. A type of voice channel that uses 10kHz channel spacing and subaudible signaling.

Neighbor Set. The set of pilots associated with the CDMA Channel that are probable candidates for handoff. Normally, the Neighbor Set consists of the pilots associated with CDMA Channel that cover geographical areas near the mobile station. See also Active Set, Candidate Set, and Remaining Set.

- A network is a subset of a Cellular system, such as an area-wide Cellular network, a private group of base stations, or a group of base stations set up to handle a special requirement. A network can be as small or as large as needed, as long as it is fully contained within a system. See also System.

Network Identification (NID). A number that uniquely identifies a network within a Cellular system. See also System Identification.

NID. See Network Identification.

Non-Autonomous Registration. A registration method in which the base station initiates registration. See also Autonomous Registration.

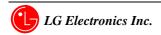
Non-Slotted Mode. An operation mode of the mobile station in which the mobile station continuously monitors the Paging Channel when in the Mobile Station Idle State.

Ns. Nanosecond.

NULL. Not having any value.

Null Traffic Channel Data. One or more frames of 16 '1's followed by eight '0's sent at the 1200bps rate. Null Traffic Channel data is sent when no service option is active and no signaling message is being sent. Null Traffic Channel data serves to maintain the connectivity between the mobile station and the base station.

Number Assignment Module (NAM). A set of MIN-related parameters stored in the mobile station.



Numeric Information. Numeric information consists of parameters that appear as numeric fields in message exchanged by the base station and the mobile station and information used to describe the operation of the mobile station.

OLC. See Overload Class (CDMA) or Overload Control (analog).

Optional Field. A field defined within a message structure that is optionally to the message recipient.

Order. A type of message that contains control codes for either the mobile station or the base station.

Ordered Registration. A registration method in which the base station orders the mobile station to send registration related parameters.

Overhead Message. A message sent by the base station on the Paging Channel to communicate base-station-specific and system-wide information to mobile station.

Overload Class. The means used to control system access by mobile stations, typically in emergency or other overload conditions. Mobile station are assigned one (or more) of sixteen overload classed, Access to the CDMA system can then be controlled on a per class basis by persistence values transmitted by the base station.

Overload Control (OLC). A means reverse analog control channel accesses by mobile stations. Mobile station are assigned one(or more) of sixteen control levels. Access is selectively restricted by a base station setting one or more OLC bits in the Overload Control Global Action Message.

Packet. The unit of information exchanged between the service option applications of the base station and the mobile station.

Padding. A sequence of bits used to fill from the end of a message to the end of a message capsule, typically to the end of the frame or half frame. All bits in the padding are '0'.

Paging. The act of seeking a mobile station when a call has been placed to that mobile station.

Paging Channel (Analog). See Analog Paging Channel.

Paging Channel (CDMA). A code channel in a Forward CDMA Channel used for transmission of control information and pages from a base station to a mobile station.

Paging Channel Slot. An 80ms interval on the Paging Channel. Mobile station operating in the slotted mode are assigned specific slots in which day monitor messages from the base station.

Parameter-Change Registration. A registration method in which the mobile station registers when certain of its stored parameters change.

Parity Check Bits. Bits added to a sequence of information bits to provide error detection, correction, or both. **Persistence.** A probability measure used by the mobile station to determine if it should transmit in a given Access Channel Slot.

Physical Layer. The part of the communication protocol between the mobile station and the base station that is responsible for the transmission and reception of data. The physical layer in the transmitting station is presented a frame by the multiplex sublayer and transforms it into an over-the-air waveform. The physical layer in the receiving station transforms the waveform back into a frame and presents it to the multiplex sublayer above it. **Pilot Channel.** An unmodulated, direct-sequence spread spectrum signal transmitted continuously by each

Pilot Channel. An unmodulated, direct-sequence spread spectrum signal transmitted continuously by each CDMA base station. The Pilot Channel allows a mobile station to acquire the timing of the Forward CDMA Channel, provides a phase reference for coherent demodulation, and provides a means for signal strength comparisons between base station for determining when to handoff.

Pilot PN Sequence. A pair of modified maximal length PN sequences with period 2¹⁵ used to spread the



Foward CDMA Channel and the Reserve CDMA Channel. Different base station are identified by different pilot PN sequence offsets.

Pilot PN Sequence Offset Index. The PN offset in units of 64 PN chips of a pilot, relative to the zero offset pilot PN sequence.

PN Chip. One bit in the PN sequence.

PN Sequence. Pseudonoise sequence. A periodic binary sequence.

Power Control Bit. A bit sent in every 1.25ms interval on the Forward Traffic Channel to signal the mobile station to increase or decrease its transmit power.

Power Control Group. A 1.25ms interval on the Forward Traffic Channel and the Reverse Traffic Channel. See also Power Control Bit.

Power-Down Registration. Au autonomous registration method in which the mobile station registers on power up.

PPM. Parts per million.

Preamble. See Access Channel Preamble and Traffic Channel Preamble.

Primary CDMA Channel. A CDMA Channel at a pre-assigned frequency assignment used by the mobile station for initial acquisition. See also Secondary CDMA Channel.

Primary Paging Channel (CDMA). The default code channel (code channel 1) assigned for paging on a CDMA Channel.

Primary Traffic. The main traffic stream carried between the mobile station and the base station, supporting the active promaty service option, on the Traffic Channel. See also Secondary Traffic, Signaling Traffic, and Servic3e Option.

Private Long Code. The long code characterized by the private long code mask. See also Long Code.

Private Long Code Mask. The long code mask used to form the private long code. See also Public Long Code Mask and Long Code.

Public Long Code. The long code characterized by the public long code mask.

Public Long Code Mask. The long code mask used to form the private long code. The mask contains the ESN of the mobile station. See also Private Long Code Mask and Long Code.

Punctured Code. An error-correcting code generated from another error-correcting code by deleting (i.e., puncturing) code symbols from the code output.

Quick Repeats. Additional transmissions of identical copies of a message within a short interval to increase the probability that the message is received correctly.

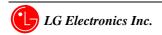
Receive Objective Loudness Rating (ROLR). A perceptually weighted transducer gain of telephone receivers relating electrical excitation from a reference generator to sound pressure at the earphone. The receive objective loudness tating is normally specified in dB relative to one Pascal per millivolt. See IEEE Standard 269-1992, IEEE Standard 661-1979, CCITT Recommendation P.76, and CCITT Recommendation P.79.

Registration. The process by which a mobile station identifies its location and parameters to a base station.

Registration Zone. A collection of one or more base stations treated as a unit when determining whether a mobile station should perform zone-based registration.

Release. A process that the mobile station and base station use to inform each other of call disconnect.

The set of all allowable pilot offsets as determined by PILOT_INC, excluding the pilot offsets of the pilots in



the Active Set, Candidate Set, and Neighbor Set. See also Active Set, Candidate Set, and Neighbor Set.

Request. A layer 3 message generated by either the mobile station or the base station to retrieve information, ask for service, or command an action.

Response. A layer 3 message generated as a result of another message, typically a request.

Reverse Analog Control (RECC). The analog control channel used from a mobile station to a base station.

Reverse Analog Voice Channel (RVC). The analog voice channel used from a mobile station to a base station.

Reverse CDMA Channel. The CDMA Channel from the mobile station to the base station. From the base station's perspective, the Reverse CDMA Channel is the sum of all mobile station transmissions on a CDMA frequency assignment.

Reverse Traffic Channel. A Reverse CDMA Channel used to transport user and signaling traffic from a single mobile station to one or more base stations.

Roamer. A mobile station operating in a Cellular system (or network) other than the one from which service was subscribed. See also Foreign NID Roamer and Foreign SID Roamer.

ROLR. See Receive Objective Loudness Rating.

SAT. See Supervisory Audio Tone.

Scan of Channels. The procedure by which a mobile station examines the signal strength of each forward analog control channel.

SCI. Synchronized Capsule Indicator bit.

Search Window. The range of PN sequence offsets that a mobile station searches for a pilot.

Secondary CDMA Channel. A CDMA Channel at a preassigned frequency assignment used by the mobile station for initial acquisition. See also Primary CDMA Channel.

Secondary Traffic. An additional traffic stream that can be carried between the mobile station and the base station on the Traffic Channel. See also Primary Traffic and Signaling Traffic.

Seizure Precursor. The initial digital sequence transmitted by a mobile station to a base station on a reverse analog control channel.

Seizure Option. A service capability of the system. Service options may be applications such as voice, data, or facsimile.

Shard Secret Data (SSD). A 128-bit pattern stored in the mobile station (in semi-permanent memory) and known by the base station. SSD is a concatenation of two 64-bit subsets: SSD_A, which is used to support the authentication procedures and SSD_B, which serves as one of the inputs to the process generating the encryption mask and private long code.

Short Message Services (SMS). A suite of services which include SMS Text Delivery, Digital Paging (i.e., Call Back Number – CBN), and Voice Mail Notification (VMN).

SID. See System Identification.

Signaling Tone. A 10kHz tone transmitted by a mobile station on an analog voice channel to: 1) confirm orders, 2)signal flash requests, and 3) signal release requests.

Signal Traffic. Control message that are carried between the mobile station and base station on the Traffic Channel. See also Primary Traffic and Secondary Traffic.

Slot Cycle. A periodic interval at which a mobile station operating in the slotted monitors the Paging Channel. **Slotted Mode.** An operation mode of the mobile station in which the mobile station monitors only selected slots

on the Paging Channel when in the Mobile Station Idle State.

Soft Handoff. A handoff occurring while the mobile station is in the Mobile Station Control on the Traffic Channel State. This handoff is characterized by commencing communications with a new base station on the same CDMA frequency assignment before terminating communications with the old base station. See also Hard Handoff.

SOM. Start-of-Message Bit.

SPS. Symbols per second.

- An identification of certain characteristics of a mobile station. Classes are defined in Table 2.3.3-1. Status Information. The following status information is used to describe mobile station operation when using the analog system.
- Serving-System Status. Indicates whether a mobile station is turned to channels associated with System A
 or System B.
- First Registration ID Status. A status variable used by the mobile station in association with its processing of received Registration ID messages.
- First Location Area ID Status. A status variable used by the mobile station in association with its
 processing of received Location Area ID messages.
- Location Registration ID Status. A status variable used by the mobile station in association with its processing of power-up registration and location-based registration.
- First Idle ID Status. A status variable used by the mobile station in association with its processing of the Idle Task.
- Local Control Status. Indicates whether a mobile station must respond to local control messages.
- Roam Status. Indicates whether a mobile station is in its home system.
- Termination Status. Indicates whether a mobile station must terminate the call when it is on an analog voice channel.

Supervisory Audio Tone (SAT). One of three tones in the 6 kHz region that is transmitted on the forward analog voice channel by a base station and transponder on the reverse analog voice channel by as mobile station.

Supplementary Digital Color Code (SDCC1, SDCC2). Additional bits assigned to increase the number of color codes from four to sixty four, transmitted on the forward analog control channel.

Symbol. See Code Symbol and Modulation Symbol.

Sync Channel. Code channel 32 in the Forward CDMA Channel which transports the synchronization message to the mobile station.

Sync Channel Superframe. An 80ms interval consisting of three Sync Channel frames (each 26.666...ms in length).

System. A system is a Cellular telephone service that covers a geographic area such as a city. Metropolitan region, country, or group of countries. See also Network.

System Time. The time reference used by the system. System Time is synchronous to UTC time(except for leap seconds) and used the same time origin as GPS time. Offset by the propagation delay from the base station to the mobile station. See also Universal coordinated Time.

Timer-Based Registration. A registration method in which the mobile station registers whenever a counter reaches a predetermined value. The counter is incremented an average of once per 80 ms period.

Time Reference. A reference established by the mobile station that is synchronous with the earliest arriving multipath component used for demodulation.

TOLR. See Transmit Objective Loudness Rating.

Traffic Channel. A communication path between a mobile station and base station used for user and signaling traffic. The term Traffic Channel implies a Forward Traffic Channel and Reverse Traffic Channel pair. See also Forward Traffic Channel and Reverse Traffic Channel.

Traffic Channel Preamble. A sequence of all-zero frames that is sent at the 9600 bps rate by the mobile station on the Reverse Traffic Channel. The Traffic Channel preamble is sent during initialization of the Traffic Channel.

Transmit Objective Loudness Rating(TOLR). A perceptually weighted transducer gain of telephone transmitters relation sound pressure at the microphone to voltage at a reference electrical termination. It is normally specified in dB relative to one millivolt per Pascal. See IEEE Standard 269-1992, IEEE Standard 661-1979, CCITT Recommendation P.76, and CCITT Recommendation. P.79

Unique Challenge-Response Procedure. An exchange of information between a mobile station and a base station for the purpose of confirming the mobile station's identity. The procedure is initiated by the base station and is characterized by the use of a challenge-specific random number(i.e., RANDU) instead of the random variable broadcast globally(RAND).

Unique Random Variable(RANDU). A 24-bit random number generated by the base station in support of the Unique Challenge-Response procedure.

Universal Coordinated Time(UTC). An internationally agreed-upon time scale maintained by the Bureau International de l'Heure(BIH) used as the time reference by nearly all commonly available time and frequency distribution systems i.e., WWW, WWVH, LORAN-C, Transit, Omega, and GPS.

UTC. Universal Temps Coordine. See Universal Coordinated Time.

Voice Channel. See Analog Voice Channel.

Voice Mobile Attenuation Code(VMAC). A 3-bit field in the Extended Address Word commanding the initial mobile power level when assigning a mobile station to an analog voice channel.

Voice Privacy. The process by which user voice transmitted over a CDMA Traffic Channel is a afforded a modest degree of protection against eavesdropping over the air.

Walsh Chip. The shortest identifiable component of a Walsh function. There are 2^N Walsh chips in one Walsh function where N is the order of the Walsh function. On the Forward CDMA channel one Walsh chip equals 1/1.2288MHz, or 813.802...ns. On the Reverse CDMA Channel, one Walsh chip equals 4/1.2288MHz, or $3.255...\mu s$.

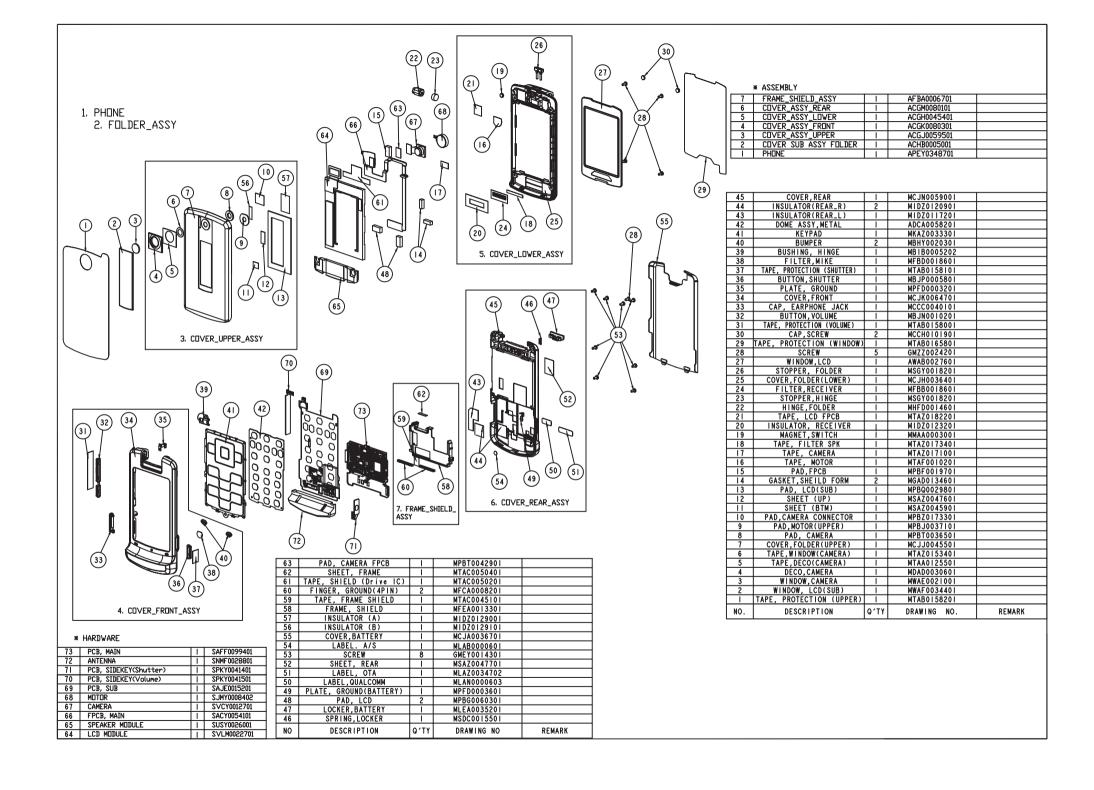
Walsh Function. One of 2^N time orthogonal binary functions (note that the functions are orthogonal after mapping '0' to 1 and '1' to -1).

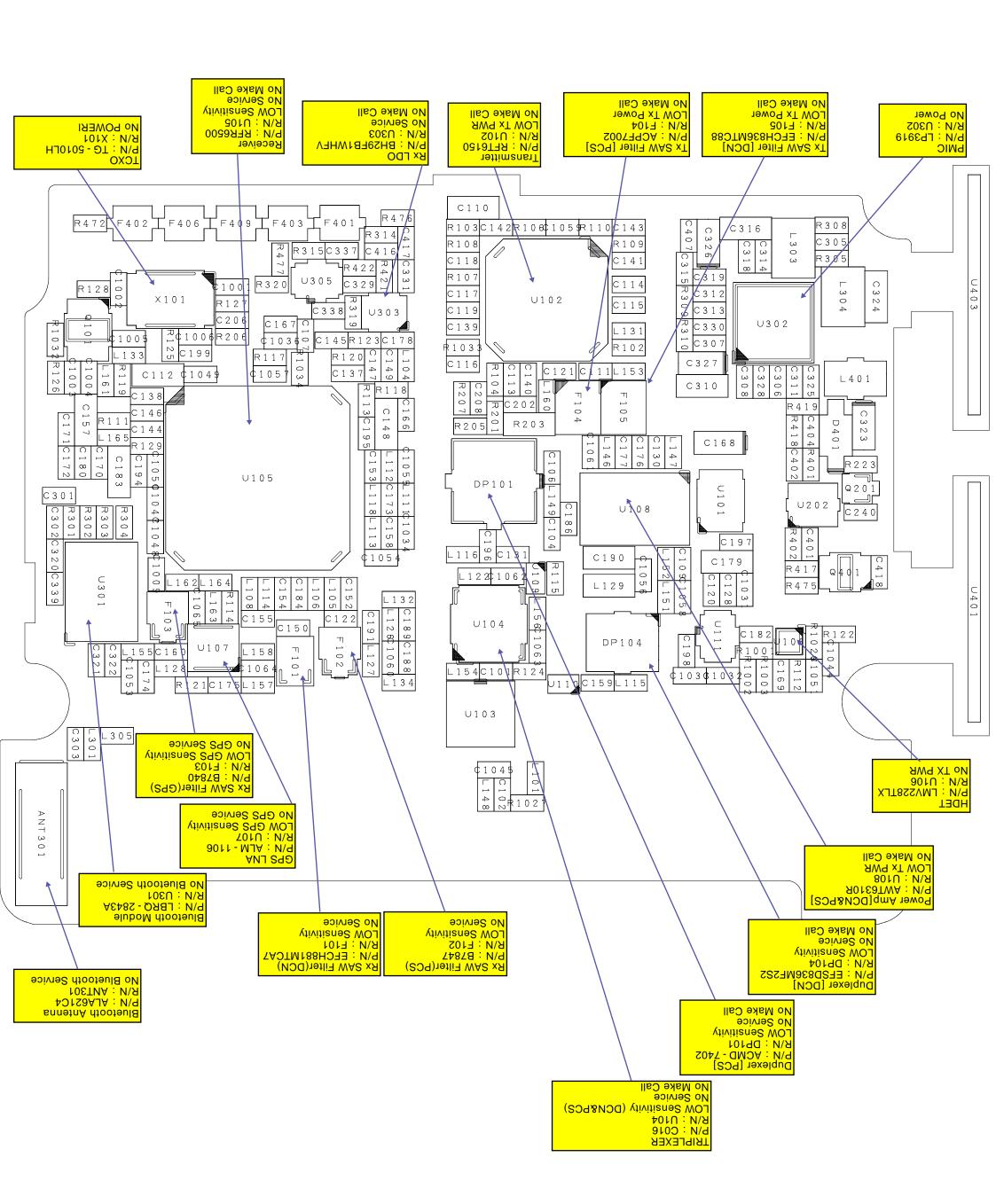
Zone-Based Registration. An autonomous registration method in which the mobile station registers whenever it enters a zone that is not in the mobile station's zone list.

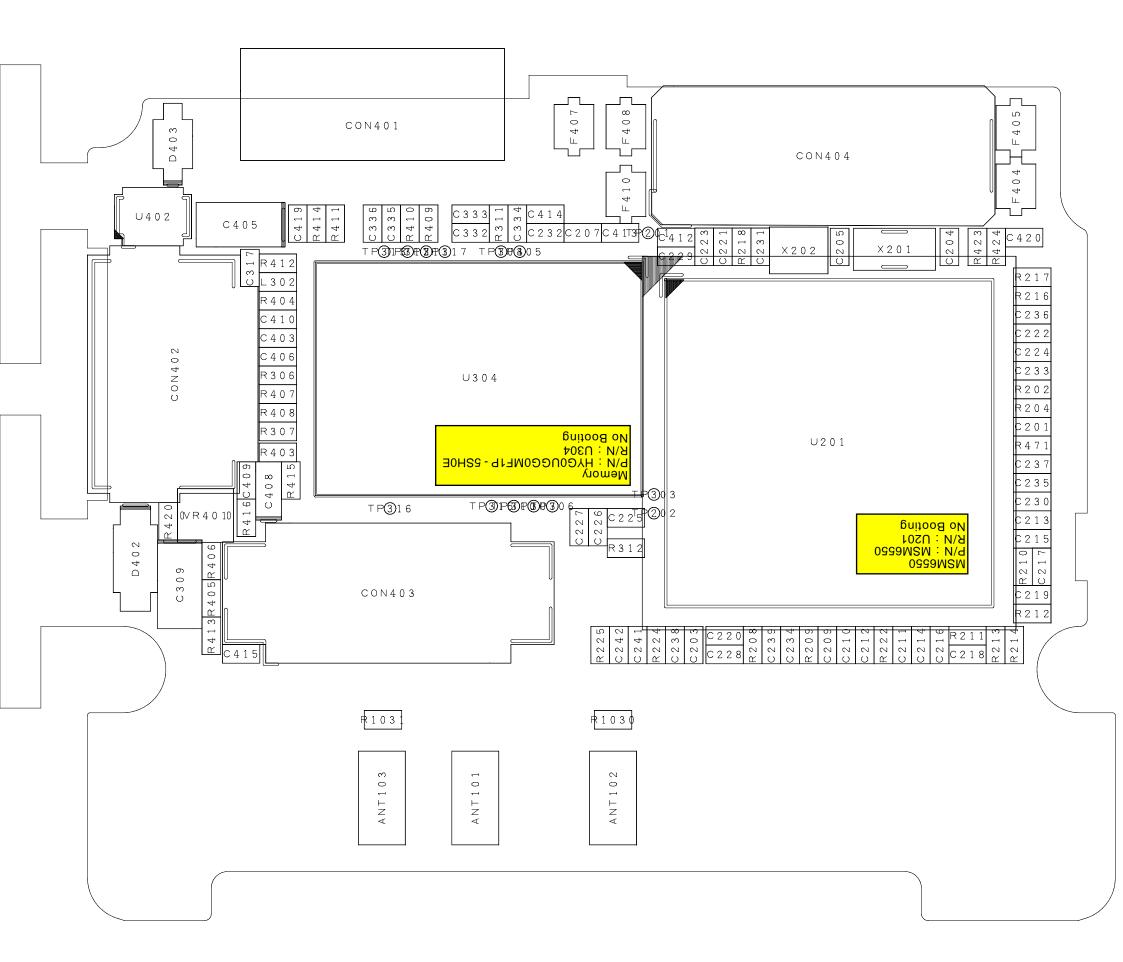
μs. Microsecond

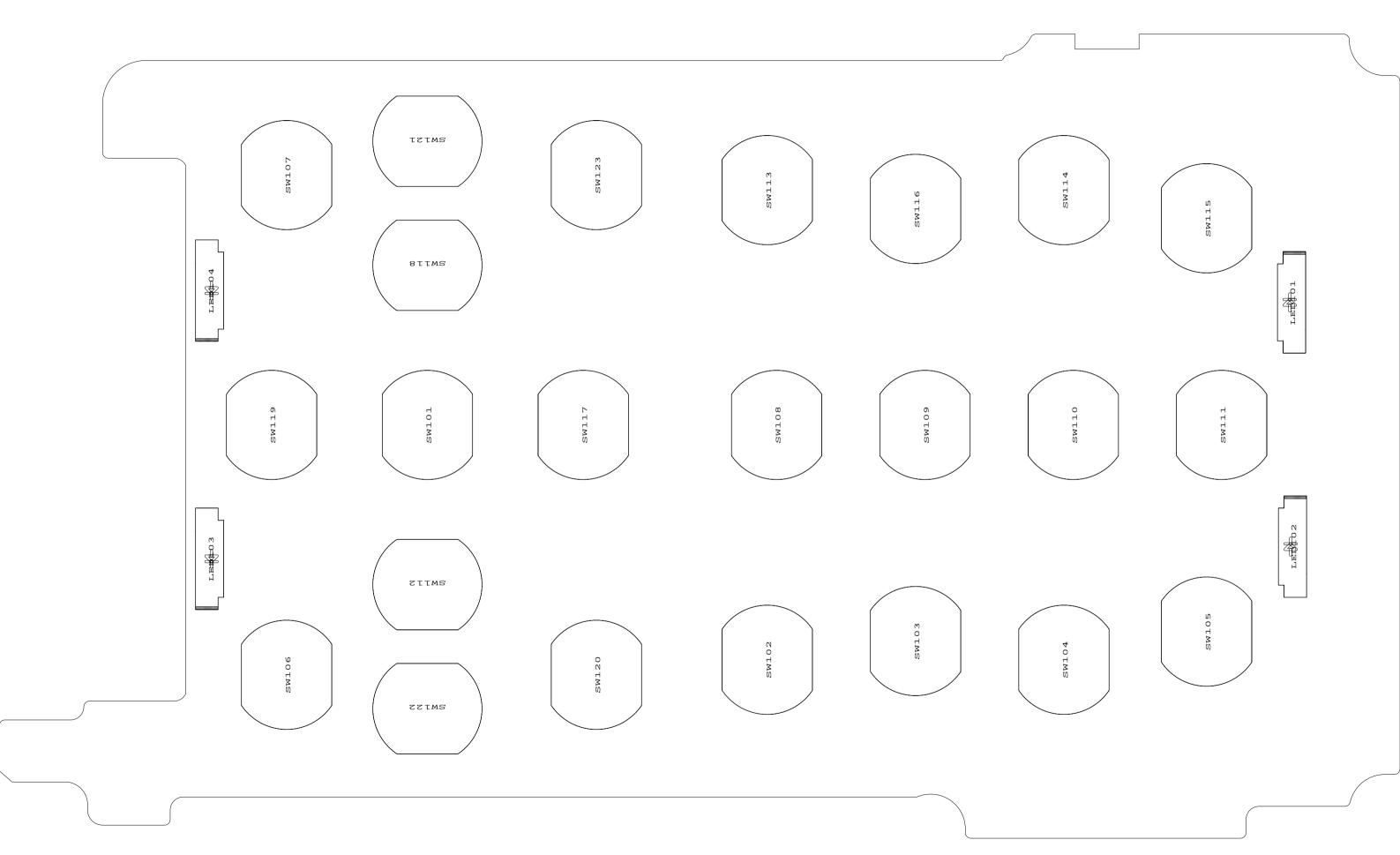
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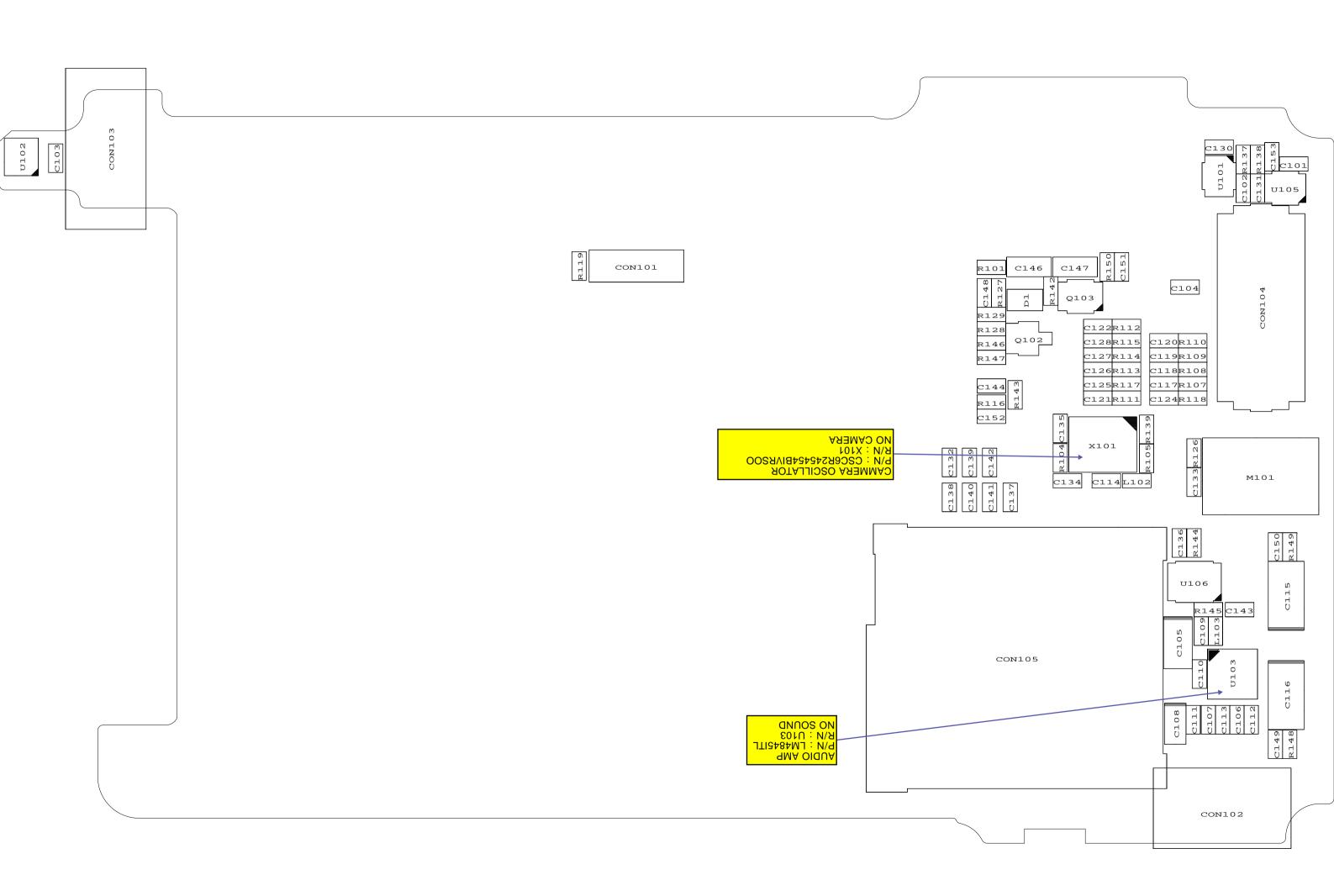
- 1. Assembly and Disassembly Diagram
- 2. Block & Circuit Diagram
- 3. Component List
 - 3.1 Accessories
 - 3.2 Board
 - 3.3 Mechanical Part
 - 3.4 The Top of the Main_PCB
 - 3.5 The Bottom of the Main_PCB
 - 3.6 The Top of the SUB_PCB
 - 3.7 The Bottom of the SUB_PCB

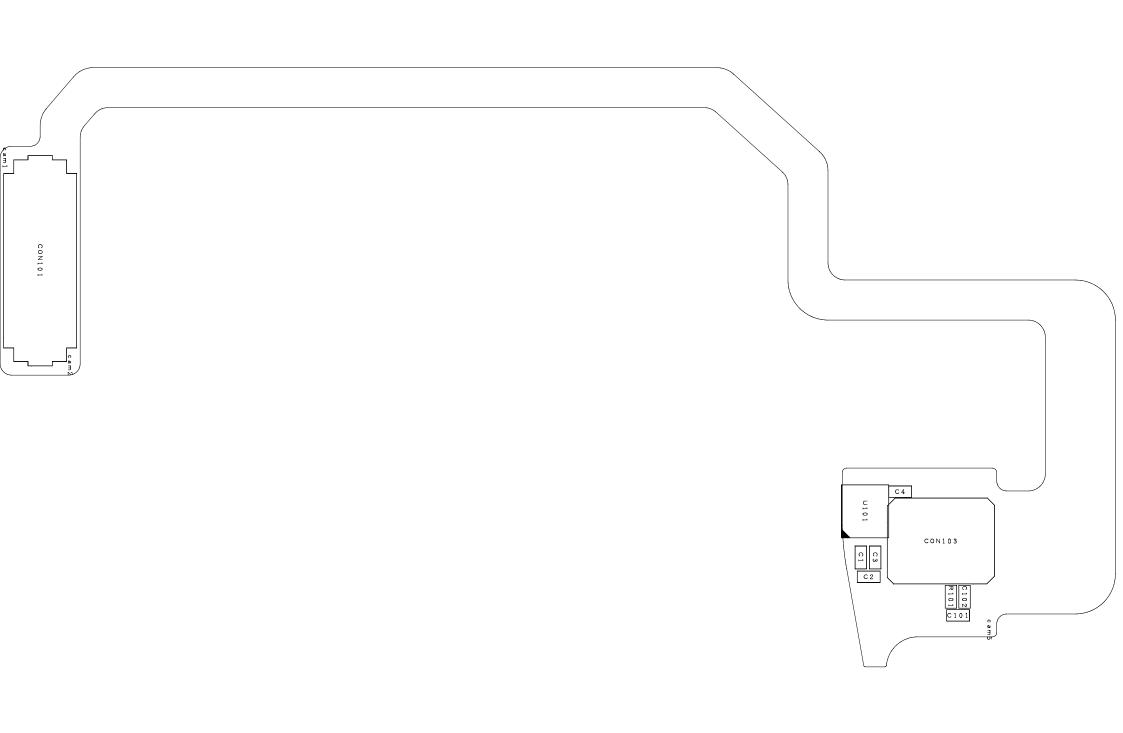


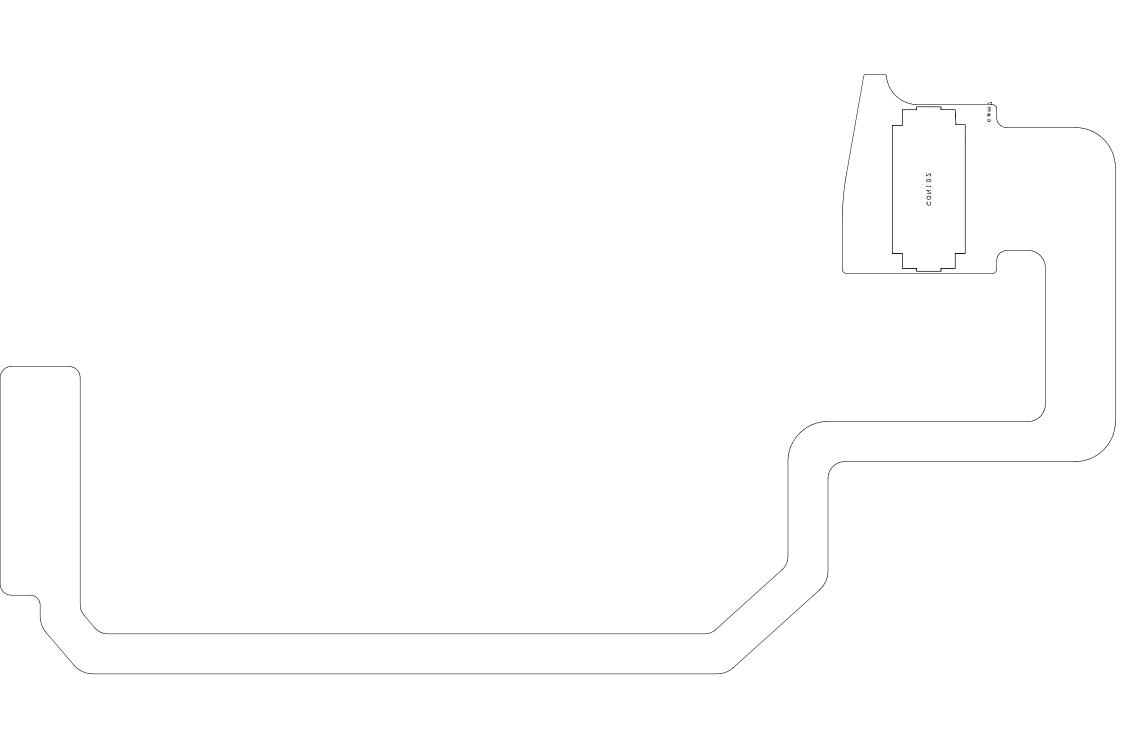








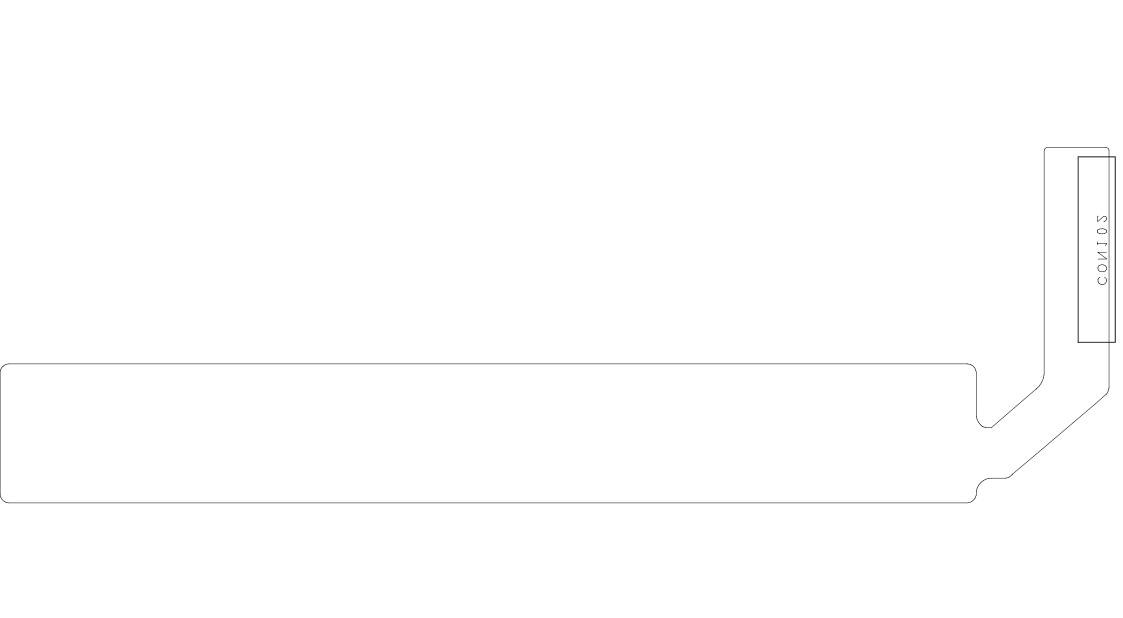


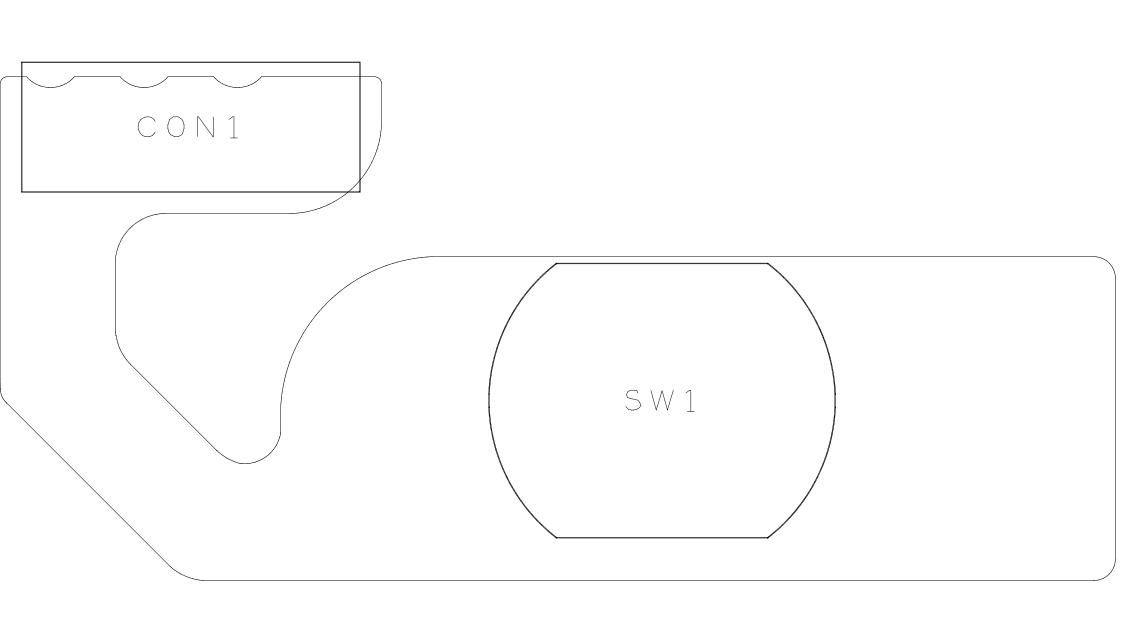


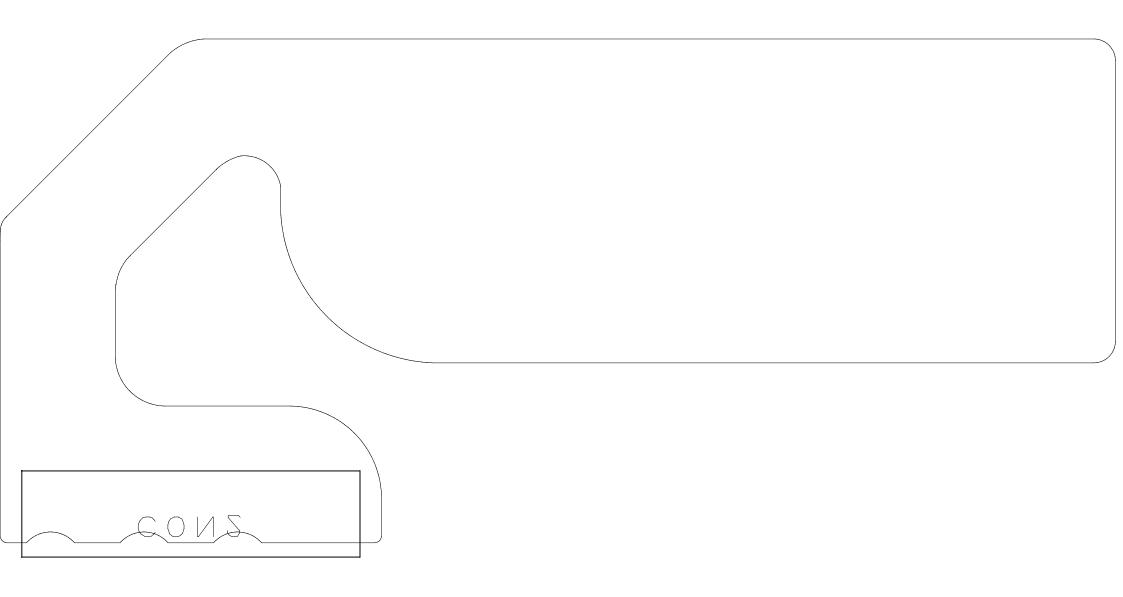
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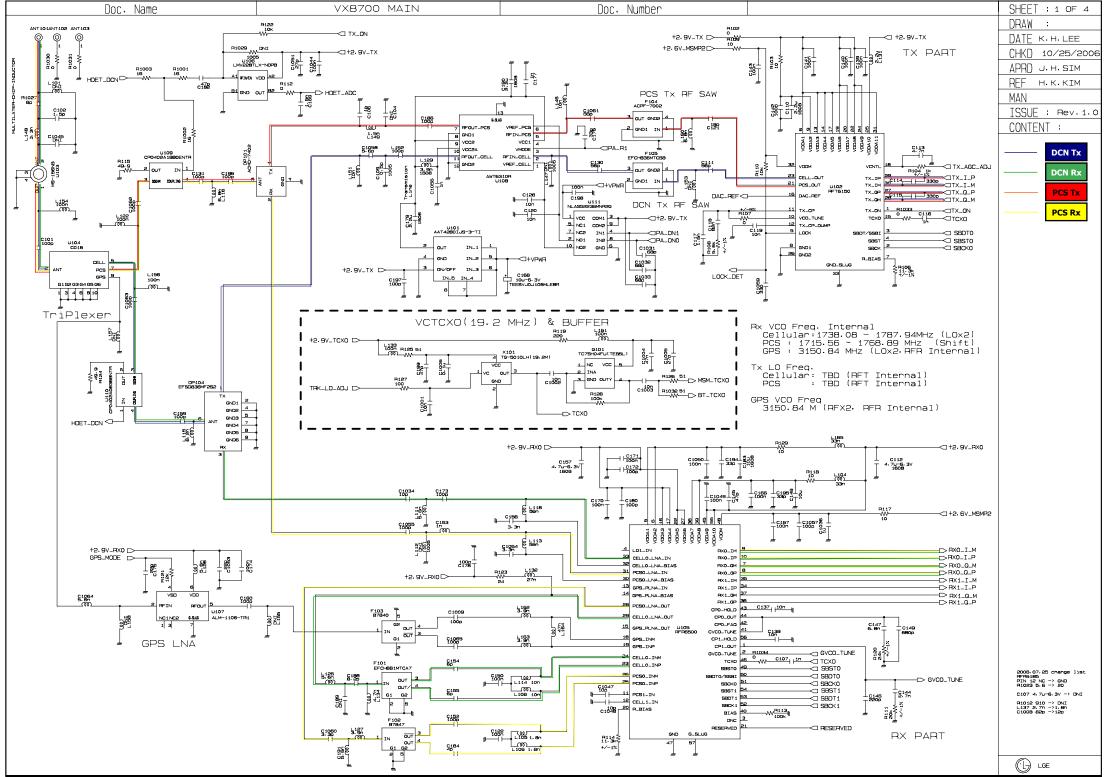
SW103 SW102

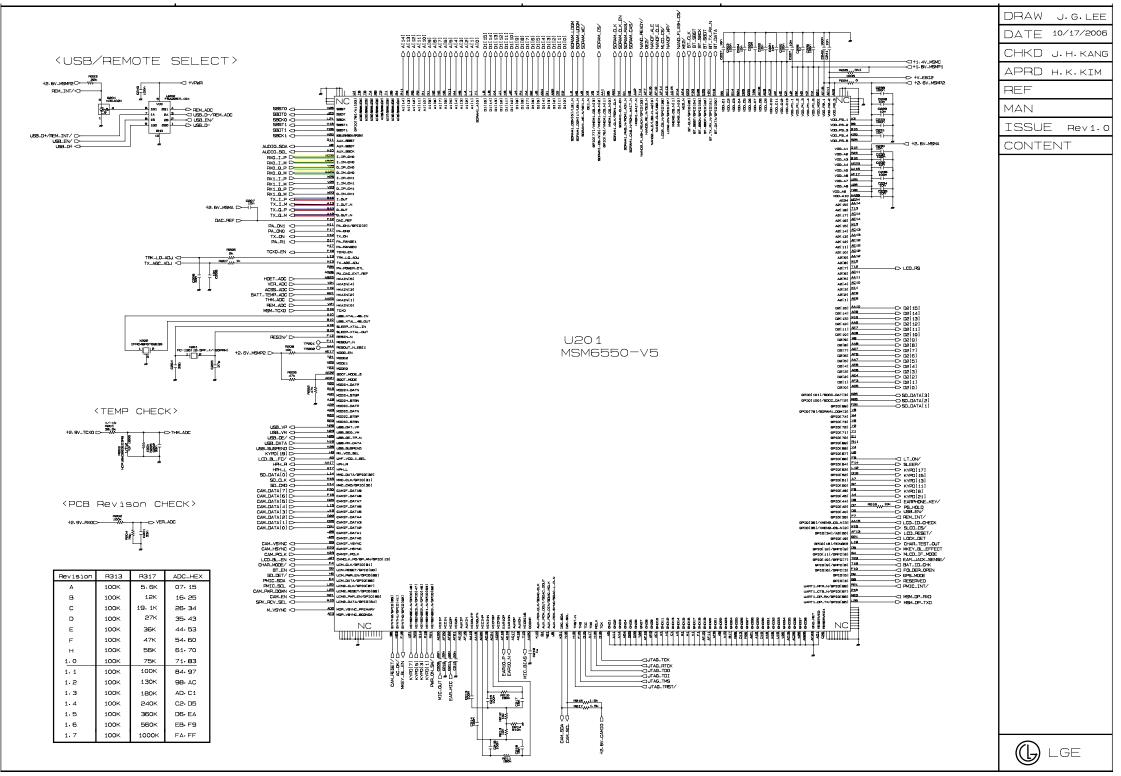
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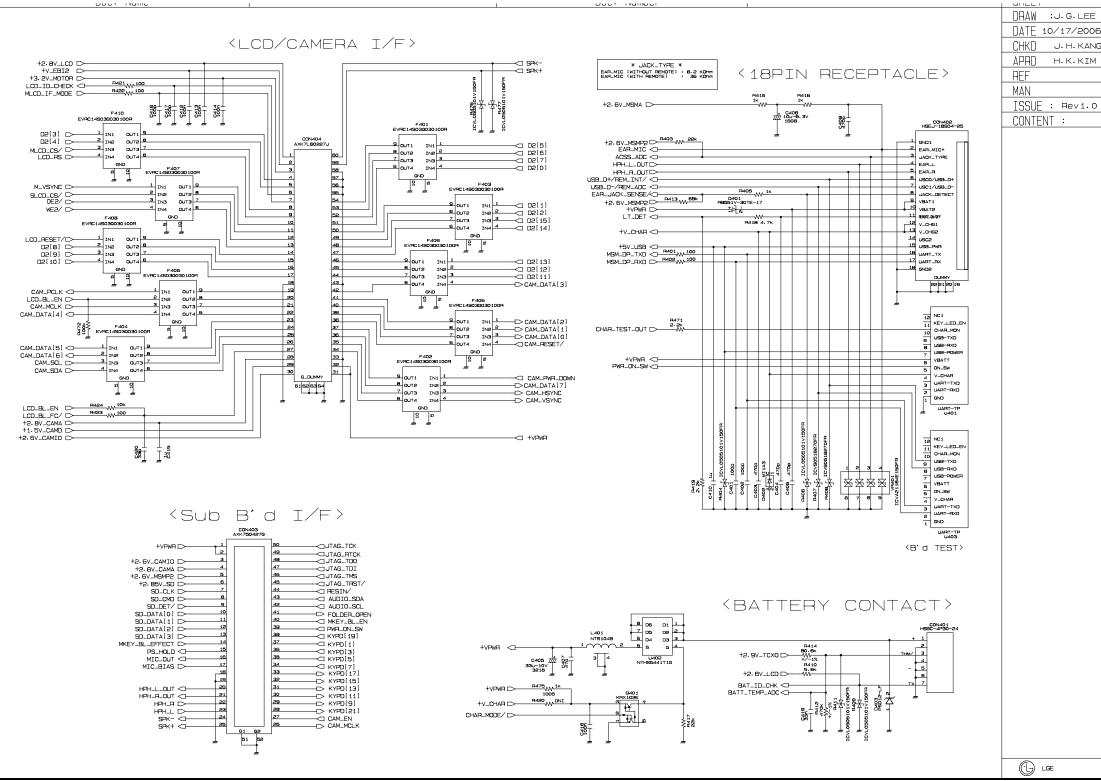


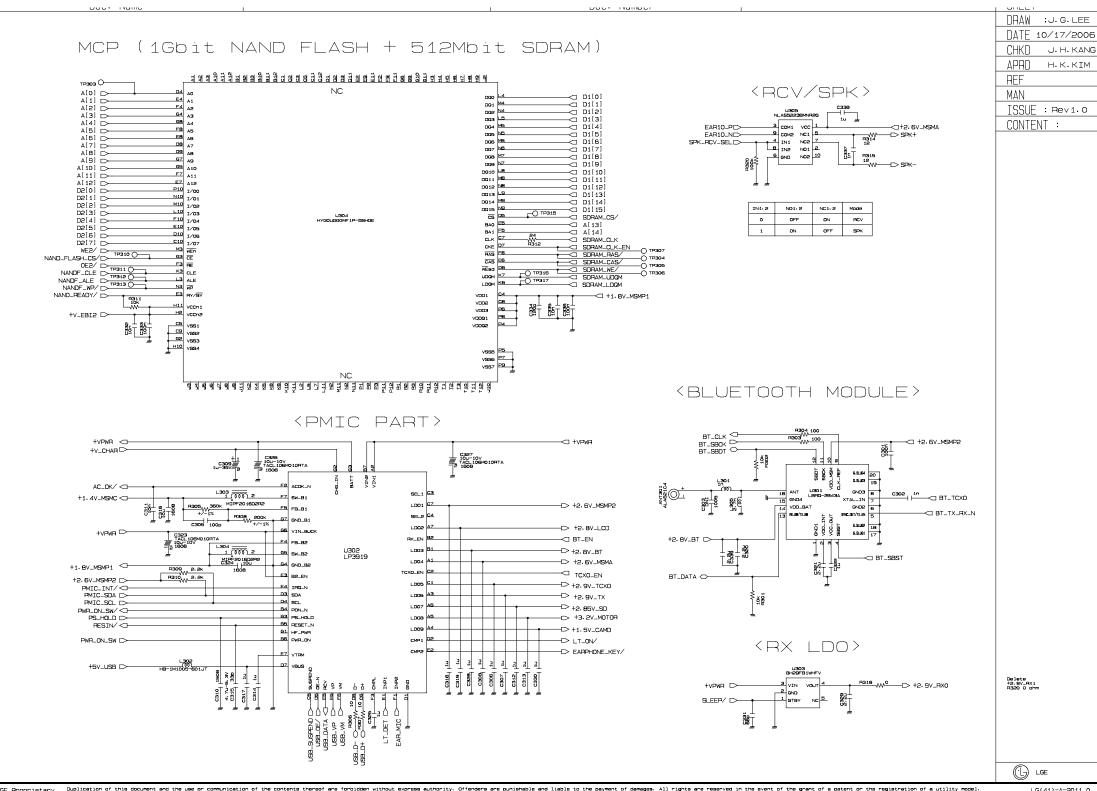


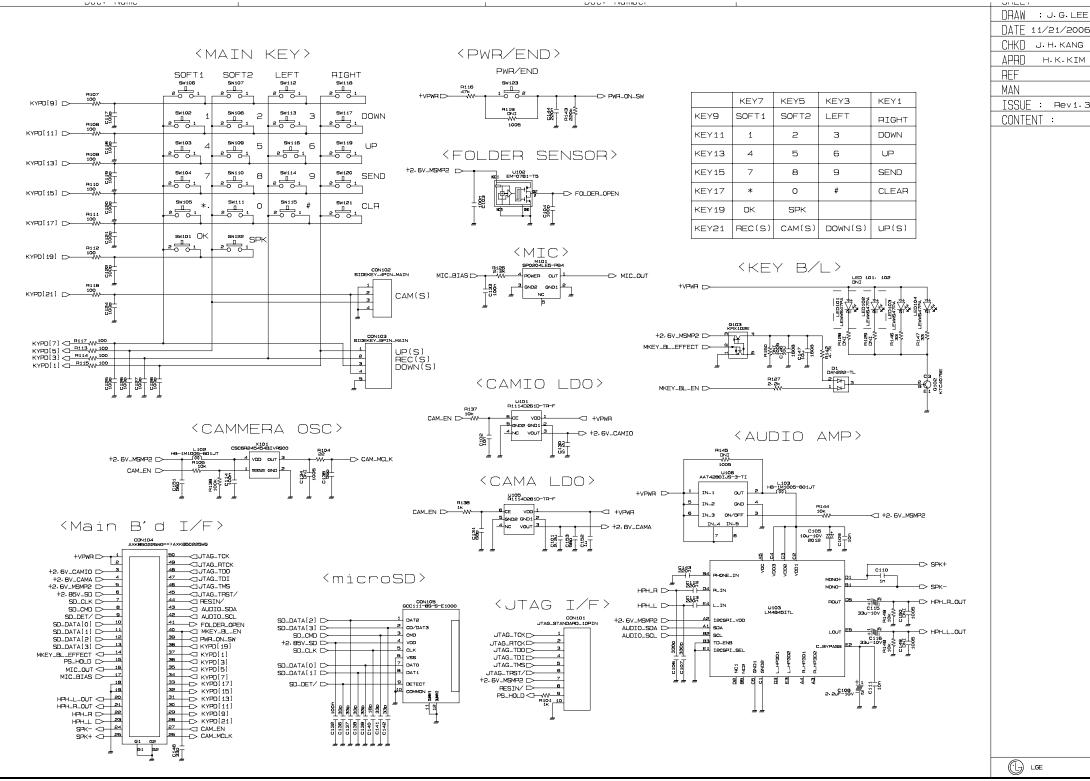


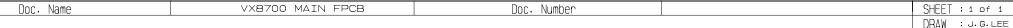










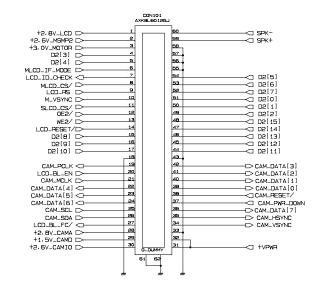


DATE 12/12/2006 CHKD J. H. KANG APRD H.K.KIM REF

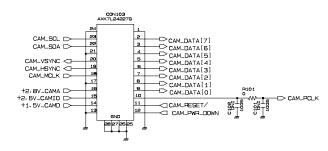
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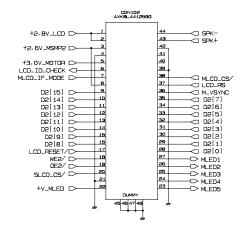
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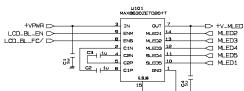
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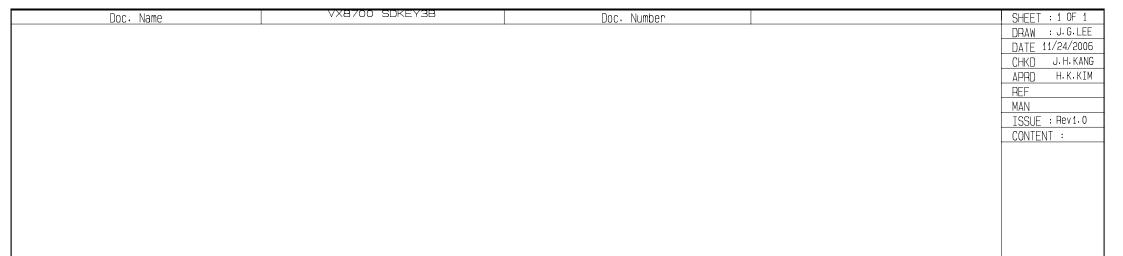


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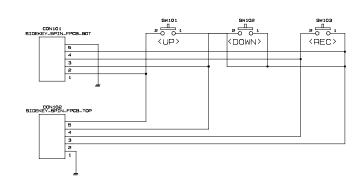


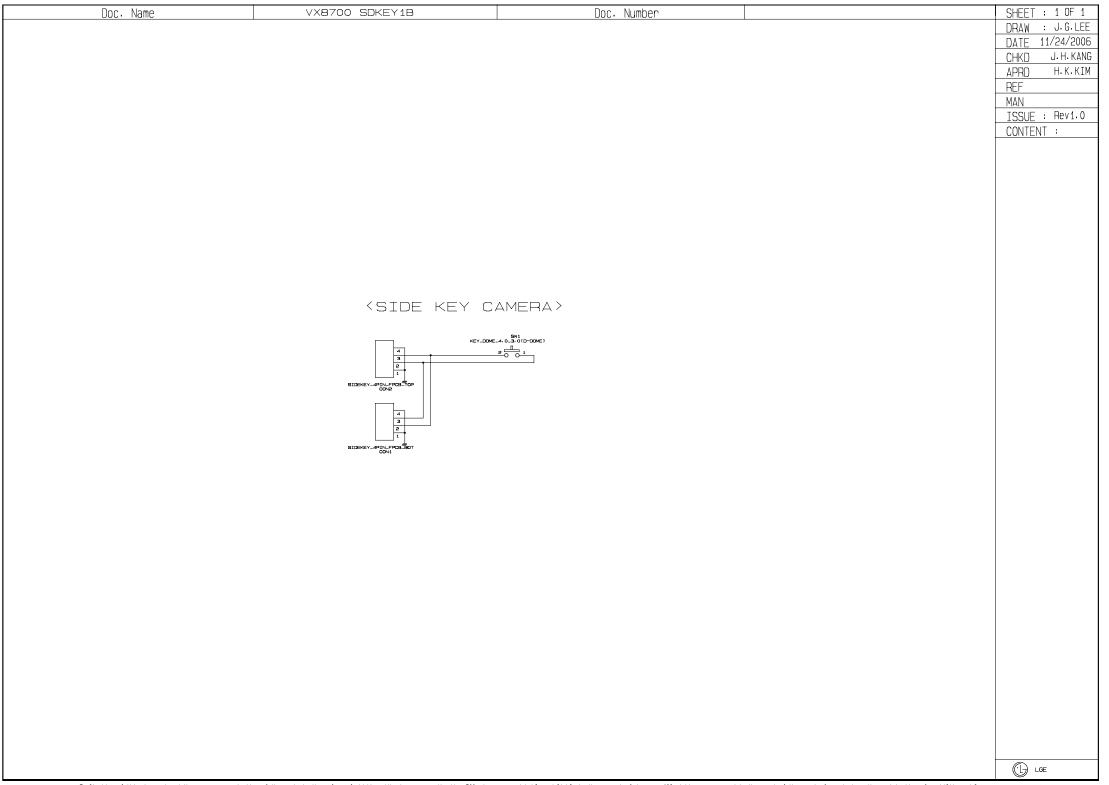






<SIDE KEY>





D-1. Accessories

| Description | LG Part No | Q'ty | Remarks |
|---------------------------|-------------|------|---------|
| TA | SSAD0020901 | 1 | BASIC |
| Battery(Standard) | SBPL0085801 | 1 | BASIC |
| Pouch | MPAC0004208 | 1 | BASIC |
| MLA (Multi Link Adaptor) | SGDY0010801 | 1 | BASIC |
| Battery(Extended) | SBPL0087901 | 1 | OPTION |
| Cigarette Lighter Adapter | SGCC0002912 | 1 | OPTION |
| Headset | SGEY0005516 | 1 | OPTION |
| USB Data Cable | SGDY0010602 | 1 | OPTION |

D-2. PCB

| Description | LG Part No | Q'ty | Remarks |
|-----------------------|-------------|------|---------|
| PCB(MAIN:RF,PMIC,MSM) | SPFY0137301 | 1 | |
| PCB(SUB PCB) | SPJY0034604 | 1 | |
| FLEXIBLE PCB(SIDE) | SPKY0041501 | 1 | |
| FLEXIBLE PCB(SIDE) | SPKY0041401 | 1 | |
| FLEXIBLE PCB(LCD) | SPCY0091803 | 1 | |

D-3. Mechanical Parts

| Design No | LG Part No | Description | QTY | Remarks |
|-----------|------------------|----------------------------|-----|---------|
| 1 | MTAB0158201 | TAPE, PROTECTION (UPPER) | 1 | |
| 2 | MWAF0034401 | WINDOW, LCD(SUB) | 1 | |
| 3 | MWAE0021001 | WINDOW,CAMERA | 1 1 | |
| 4 | MDAD0026101 | DECO,CAMERA | 1 | |
| 5 | MTAA0125501 | TAPE,DECO(CAMERA) | 1 | |
| 6 | MTAZ0153401 | TAPE,WINDOW(CAMERA) | 1 | |
| 7 | MCJJ0045501 | COVER,FOLDER(UPPER) | 1 | |
| 8 | MPBT0036501 | PAD, CAMERA | 1 | |
| 9 | MPBJ0037101 | PAD,MOTOR(UPPER) | 1 | |
| 10 | MPBZ0173301 | PAD,CAMERA CONNECTOR | 1 | |
| 11 | MSAZ0045901 | SHEET (BTM) | 1 | |
| 12 | MSAZ0047601 | SHEET (UP) | 1 | |
| 13 | MPBQ0029801 | PAD, LCD(SUB) | 1 | |
| 14 | MGAD0134601 | GASKET,SHEILD FORM | 2 | |
| 15 | MPBF0019701 | PAD,FPCB | 1 | |
| 16 | MTAF0010201 | TAPE, MOTOR | 1 | |
| 17 | MTAZ0171001 | TAPE, CAMERA | 1 | |
| 18 | MTAZ0173401 | TAPE, FILTER SPK | 1 | |
| 19 | MMAA0003001 | MAGNET,SWITCH | 1 | |
| 20 | MIDZ0123201 | INSULATOR, RECEIVER | 1 | |
| 21 | MTAZ0182201 | TAPE, LCD FPCB | 1 | |
| 22 | MHFD0014601 | HINGE,FOLDER | 1 | |
| 23 | MSGY0018201 | STOPPER,HINGE | 1 | |
| 24 | MFBB0018601 | FILTER,RECEIVER | 1 | |
| 25 | MCJH0036401 | COVER,FOLDER(LOWER) | 1 | |
| 26 | MSGY0018201 | STOPPER, FOLDER | 1 | |
| 27 | MWAC0072301 | WINDOW,LCD | 1 | |
| 28 | GMZZ0017701 | SCREW | 5 | |
| 29 | MTAB0165801 | TAPE, PROTECTION (WINDOW) | 1 | |
| 30 | MCCH0101901 | CAP.SCREW | 2 | |
| 31 | MTAB0158001 | TAPE, PROTECTION (VOLUME) | 1 | |
| 32 | MBJN0010201 | BUTTON, VOLUME | 1 | |
| 33 | MCCC0040101 | CAP, EARPHONE JACK | 1 | |
| 34 | MCJK0064701 | COVER,FRONT | 1 | |
| 35 | MPFD0003201 | PLATE, GROUND | 1 | |
| 36 | MBJP0005801 | BUTTON,SHUTTER | 1 | |
| 37 | MTAB0158101 | TAPE, PROTECTION (SHUTTER) | 1 | |
| 38 | MFBD0018601 | FILTER,MIKE | 1 | |
| 39 | MBIB0005202 | BUSHING, HINGE | 1 | |
| 40 | MBHY0020301 | BUMPER | 2 | |
| 41 | MKAZ0033301 | KEYPAD | 1 | |
| 42 | ADCA0058201 | DOME ASSY,METAL | 1 | |
| 43 | MIDZ0117201 | INSULATOR(REAR_L) | 1 | |
| 44 | MIDZ0177201 | INSULATOR(REAR_R) | 2 | |
| 45 | MCJN0059001 | COVER,REAR | 1 | |
| 46 | MSDC0015501 | SPRING,LOCKER | 1 | |
| 47 | MLEA0035201 | LOCKER,BATTERY | 1 | |
| 48 | MPBG0060301 | PAD, LCD | 2 | |
| 49 | MPFD0003601 | PLATE, GROUND(BATTERY) | 1 | |
| 50 | MLAN0000603 | LABEL,QUALCOMM | 1 | |
| 51 | MLAZ0034702 | LABEL, OTA | 1 | |
| 52 | MSAZ0047701 | SHEET, REAR | 1 | |
| 53 | GMEY0014301 | SCREW | 8 | |
| JJ | ONIE 1 00 1700 1 | | J | |

| 54 | MLAB0000601 | LABEL. A/S | 1 | |
|----|-------------|----------------------|---|--|
| 55 | MCJA0036701 | COVER,BATTERY | 1 | |
| 56 | MIDZ0129101 | INSULATOR (B) | 1 | |
| 57 | MIDZ0129001 | INSULATOR (A) | 1 | |
| 58 | MFEA0013301 | FRAME, SHIELD | 1 | |
| 59 | MTAC0045101 | TAPE, FRAME SHIELD | 1 | |
| 60 | MFCA0008201 | FINGER, GROUND(4PIN) | 2 | |

D-4. MAIN PCB BOT

| Ref No | LG Part No | Value | Description | QTY |
|--------------|----------------------------|--|--|-----|
| C201 | ECCH0000161 | 33 nF,16V,K,X7R,HD,1005,R/TP | CAP,CERAMIC,CHIP | 1 |
| C203 | ECCH0002001 | 100000 pF,6.3V ,K ,B ,HD ,1005 ,R/TP | CAP,CERAMIC,CHIP | 1 |
| C204 | ECZH0000830 | 33 pF,50V ,J ,NPO ,TC ,1005 ,R/TP | CAP,CHIP,MAKER | 1 |
| C205 | ECZH0000826 | 27 pF,50V ,J ,NPO ,TC ,1005 ,R/TP | CAP,CHIP,MAKER | 1 |
| C207 | ECCH0000155 | 10 nF,16V,K,X7R,HD,1005,R/TP | CAP,CERAMIC,CHIP | 1 |
| C209 | ECCH0000179 | 22 nF,16V ,K ,X5R ,HD ,1005 ,R/TP | CAP,CERAMIC,CHIP | 1 |
| C210 | ECCH0000179 | 22 nF,16V ,K ,X5R ,HD ,1005 ,R/TP | CAP,CERAMIC,CHIP | 1 |
| C211 | ECCH0000179 | 22 nF,16V ,K ,X5R ,HD ,1005 ,R/TP | CAP,CERAMIC,CHIP | 1 |
| C212 | ECCH0000179 | 22 nF,16V ,K ,X5R ,HD ,1005 ,R/TP | CAP,CERAMIC,CHIP | 1 |
| C213 | ECCH0002001 | 100000 pF,6.3V ,K ,B ,HD ,1005 ,R/TP | CAP,CERAMIC,CHIP | 1 |
| C214 | ECCH0002001 | 100000 pF,6.3V ,K ,B ,HD ,1005 ,R/TP | CAP,CERAMIC,CHIP | 1 |
| C215 | ECCH0002001 | 100000 pF,6.3V ,K ,B ,HD ,1005 ,R/TP | CAP,CERAMIC,CHIP | 1 |
| C216 | ECCH0002001 | 100000 pF,6.3V ,K ,B ,HD ,1005 ,R/TP | CAP,CERAMIC,CHIP | 1 |
| C217 | ECCH0000157 | 15 nF,16V,K,X7R,HD,1005,R/TP | CAP,CERAMIC,CHIP | 1 |
| C218 | ECCH0000157 | 15 nF,16V,K,X7R,HD,1005,R/TP | CAP,CERAMIC,CHIP | 1 |
| C219 | ECCH0004904 | 1 uF,6.3V ,K ,X5R ,TC ,1005 ,R/TP | CAP,CERAMIC,CHIP | 1 |
| C220 | ECCH0001301 | 100000 pF,6.3V ,K ,B ,HD ,1005 ,R/TP | CAP,CERAMIC,CHIP | 1 |
| C221 | ECCH0002301 | 10 nF,16V,K,X7R,HD,1005,R/TP | CAP, CERAMIC, CHIP | 1 |
| C222 | ECCH0000155 | 10 nF,16V,K,X7R,HD,1005,R/TP | CAP,CERAMIC,CHIP | 1 |
| C223 | ECCH0000155 | 10 nF,16V,K,X7R,HD,1005,R/TP | CAP, CERAMIC, CHIP | 1 |
| C224 | ECCH0000155 | 10 nF,16V,K,X7R,HD,1005,R/TP | CAP, CERAMIC, CHIP | 1 |
| C225 | ECCH0002001 | 100000 pF,6.3V ,K ,B ,HD ,1005 ,R/TP | CAP,CERAMIC,CHIP | 1 |
| C226 | ECCH0004904 | 1 uF,6.3V ,K ,X5R ,TC ,1005 ,R/TP | CAP, CERAMIC, CHIP | 1 |
| C227 | ECCH0004304 | 10 nF,16V,K,X7R,HD,1005,R/TP | CAP,CERAMIC,CHIP | 1 |
| C228 | ECCH0000155 | 10 nF,16V,K,X7R,HD,1005,R/TP | CAP,CERAMIC,CHIP | 1 |
| C229 | ECCH0000133 | 10 nF,16V,K,X7R,HD,1005,R/TP | CAP,CERAMIC,CHIP | 1 |
| C230 | ECCH0000155 | 10 nF,16V,K,X7R,HD,1005,R/TP | CAP,CERAMIC,CHIP | 1 |
| C230 | ECCH0000155 | 10 nF,16V,K,X7R,HD,1005,R/TP | CAP,CERAMIC,CHIP | 1 |
| C232 | ECCH0000155 | 10 nF,16V,K,X7R,HD,1005,R/TP | CAP,CERAMIC,CHIP | 1 |
| C232 | ECCH0002001 | 100000 pF,6.3V ,K ,B ,HD ,1005 ,R/TP | CAP,CERAMIC,CHIP | 1 |
| C234 | ECCH0002001 | 10 nF,16V,K,X7R,HD,1005,R/TP | CAP,CERAMIC,CHIP | 1 |
| C235 | ECCH0002001 | 100000 pF,6.3V ,K ,B ,HD ,1005 ,R/TP | CAP,CERAMIC,CHIP | 1 |
| C236 | ECCH0002001 | 100000 pF,6.3V ,K ,B ,HD ,1003 ,R/TP | CAP,CERAMIC,CHIP | 1 |
| C237 | ECCH0002001 | 10 nF,16V,K,X7R,HD,1005,R/TP | CAP,CERAMIC,CHIP | 1 |
| C238 | ECCH0002001 | 100000 pF,6.3V ,K ,B ,HD ,1005 ,R/TP | CAP,CERAMIC,CHIP | 1 |
| C238 | ECCH0002001 | 10 nF,16V,K,X7R,HD,1005,R/TP | | _ |
| C239 C241 | ECCH0000155 | 10 nF,16V,K,X7R,HD,1005,R/TP | CAP,CERAMIC,CHIP CAP,CERAMIC,CHIP | 1 |
| C241 | | | | 1 |
| C309 | ECCH0002001 ECTZ0000407 | 100000 pF,6.3V ,K ,B ,HD ,1005 ,R/TP | CAP,CERAMIC,CHIP CAP,TANTAL,CHIP,MA | |
| C309 C317 | | 1 uF,35V ,M ,STD ,3216 ,R/TP 1 uF,10V ,K ,X5R ,TC ,1005 ,R/TP | CAP, CHIP, MAKER | 1 |
| C332 | ECZH0001215 ECCH0000155 | | | 1 |
| C333 | | 10 nF,16V,K,X7R,HD,1005,R/TP | CAP, CERAMIC, CHIP | 1 |
| C334 | ECCH0002001 | 100000 pF,6.3V ,K ,B ,HD ,1005 ,R/TP | CAP, CERAMIC, CHIP | 1 |
| | ECCH0000129 | 120 pF,50V,J,NP0,TC,1005,R/TP | CAP, CERAMIC, CHIP | 1 |
| C335 | ECCH0000155 | 10 nF,16V,K,X7R,HD,1005,R/TP | CAP, CERAMIC, CHIP | 1 |
| C336 | ECCH0002001 | 100000 pF,6.3V ,K ,B ,HD ,1005 ,R/TP | CAP,CERAMIC,CHIP | 1 |
| C403 | ECZH0001121 | 470 pF,50V ,K ,X7R ,HD ,1005 ,R/TP | CAP, CHIP, MAKER | 1 |
| C405 | ECTZ0004206 | 33 uF,10V ,M ,L_ESR ,3216 ,R/TP | CAP, TANTAL, CHIP, MA | 1 |
| C406 | ECZH0001121 | 470 pF,50V ,K ,X7R ,HD ,1005 ,R/TP | CAP, CHIP, MAKER | 1 |
| C408 | ECTH0003701 | 10 uF,6.3V ,M ,L_ESR ,1608 ,R/TP | CAP, TANTAL, CHIP | 1 |
| C409 | ECZH0001121 | 470 pF,50V ,K ,X7R ,HD ,1005 ,R/TP | CAP, CHIP, MAKER | |
| C410 | ECZH0001215 | 1 uF,10V ,K ,X5R ,TC ,1005 ,R/TP | CAP, CHIP, MAKER | 1 |
| C412 | ECZH0003202 | 1 uF,6.3V ,Z ,Y5V ,HD ,1005 ,R/TP | CAP,CHIP,MAKER | |
| C413 | ECZH0003202 | 1 uF,6.3V ,Z ,Y5V ,HD ,1005 ,R/TP | CAP,CHIP,MAKER | 1 |
| C414 | ECCH0002001 | 100000 pF,6.3V ,K ,B ,HD ,1005 ,R/TP | CAP, CERAMIC, CHIP | 1 |
| C415 | ECCH0004904 | 1 uF,6.3V ,K ,X5R ,TC ,1005 ,R/TP | CAP,CERAMIC,CHIP | 1 |
| C419 | ECCH0000161 | 33 nF,16V,K,X7R,HD,1005,R/TP | CAP,CERAMIC,CHIP | 1 |
| C420 | ECZH0000830 | 33 pF,50V ,J ,NP0 ,TC ,1005 ,R/TP | CAP,CHIP,MAKER | 1 |

| CON401 | ENZY0018201 | 4 PIN,3.0 mm,ETC , ,Hard Pack Vertical | CONNECTOR,ETC | 1 |
|--------------|----------------------------|--|----------------------------------|---|
| CON402 | ENRY0006001 | 18 PIN,0.4 mm,ETC , ,H=2.5 | CONNECTOR,I/O | 1 |
| CON403 | ENBY0040901 | 50 PIN, mm,ETC , , ,; , ,0.40MM ,STRAIGHT ,FEMALE ,SMD ,R/TP ,3.5 , | CONNECTOR,BOARD | 1 |
| CON404 | ENBY0020402 | 60 PIN, 0.4 mm, STRAIGHT, AU, STACKING HEIGHT 0.9 / SOCKET FOR KEYPAD TO | - | 1 |
| D402 | EDSY0010701 | 3.6*1.6*1.1 ,30 V,12 A,R/TP ,Schottky Barrier Diode | DIODE,SWITCHING | 1 |
| D403 | EDTY0008602 | SOD-323 ,13.3 V,400 W,R/TP ,PB-FREE | DIODE,TVS | 1 |
| F404 | SFEY0013201 | SMD ,1608 ,EMI-ESD Filter, 4ch, 14V, 15pF, 100ohm | FILTER,EMI/POWER | 1 |
| F405 | SFEY0013201 | SMD ,1608 ,EMI-ESD Filter, 4ch, 14V, 15pF, 100ohm | FILTER,EMI/POWER | 1 |
| F407 | SFEY0013201 | SMD ,1608 ,EMI-ESD Filter, 4ch, 14V, 15pF, 100ohm | FILTER,EMI/POWER | 1 |
| F408 | SFEY0013201 | SMD ,1608 ,EMI-ESD Filter, 4ch, 14V, 15pF, 100ohm | FILTER,EMI/POWER | 1 |
| F410 | SFEY0013201 | SMD ,1608 ,EMI-ESD Filter, 4ch, 14V, 15pF, 100ohm | FILTER,EMI/POWER | 1 |
| L302 | SFBH0000903 | 600 ohm,1005 , | FILTER,BEAD,CHIP | 1 |
| R1030 | ERHZ0000401 | 0 ohm,1/16W ,J ,1005 ,R/TP | RES,CHIP,MAKER | 1 |
| R1031 | ERHZ0000401 | 0 ohm,1/16W ,J ,1005 ,R/TP | RES,CHIP,MAKER | 1 |
| R202 | ERHZ0000204 | 100 Kohm,1/16W ,F ,1005 ,R/TP | RES,CHIP,MAKER | 1 |
| R204 | ERHZ0000315 | 75 Kohm,1/16W ,F ,1005 ,R/TP | RES,CHIP,MAKER | 1 |
| R208 | ERHZ0000405 | 10 Kohm,1/16W ,J ,1005 ,R/TP | RES,CHIP,MAKER | 1 |
| R209 | ERHZ0000486 | 47 Kohm,1/16W ,J ,1005 ,R/TP | RES,CHIP,MAKER | 1 |
| R210 | ERHZ0000231 | 180 Kohm,1/16W ,F ,1005 ,R/TP | RES,CHIP,MAKER | 1 |
| R211 | ERHZ0000231 | 180 Kohm,1/16W ,F ,1005 ,R/TP | RES,CHIP,MAKER | 1 |
| R212 | ERHZ0000231 | 10 Kohm,1/16W ,F ,1005 ,R/TP | RES,CHIP,MAKER | 1 |
| R213 | ERHZ0000203 | 10 Kohm,1/16W ,F ,1005 ,R/TP | RES,CHIP,MAKER | 1 |
| R214 | ERHZ0000296 | 510 Kohm,1/16W ,F ,1005 ,R/TP | RES,CHIP,MAKER | 1 |
| R214 | ERHZ0000529 | 1.5 Kohm,1/16W ,J ,1005 ,R/TP | RES,CHIP,MAKER | 1 |
| R217 | ERHZ0000529 | 1.5 Kohm,1/16W ,J ,1005 ,R/TP | RES,CHIP,MAKER | 1 |
| R217 | ERHZ0000405 | 10 Kohm,1/16W ,J ,1005 ,R/TP | RES,CHIP,MAKER | 1 |
| R222 | ERHZ0000486 | 47 Kohm,1/16W ,J ,1005 ,R/TP | RES,CHIP,MAKER | 1 |
| R224 | ERHZ0000401 | 0 ohm,1/16W ,J ,1005 ,R/TP | RES,CHIP,MAKER | 1 |
| R306 | ERHZ0000401 | 10 ohm,1/16W ,J ,1005 ,R/TP | RES,CHIP,MAKER | 1 |
| R307 | ERHZ0000402 | 10 ohm,1/16W ,J ,1005 ,R/TP | RES,CHIP,MAKER | 1 |
| R311 | ERHZ0000402 | 10 Kohm,1/16W ,J ,1005 ,R/TP | RES,CHIP,MAKER | 1 |
| R312 | ERHZ0000403 | 24 ohm,1/16W ,F ,1005 ,R/TP | RES,CHIP,MAKER | 1 |
| R403 | ERHZ0000323 | 22 Kohm,1/16W ,F ,1005 ,R/TP | RES,CHIP,MAKER | 1 |
| R403 | SEVY0003601 | 5.6 V, ,SMD ,100pF, 1005 | VARISTOR | 1 |
| R404 R405 | ERHZ0000404 | 1 Kohm,1/16W ,J ,1005 ,R/TP | RES,CHIP,MAKER | 1 |
| R405 R406 | 1 | 5.6 V, ,SMD ,100pF, 1005 | VARISTOR | 1 |
| R406 R407 | SEVY0003601 SEVY0005403 | 18 V,30%, SMD ,27pF,1005 | | 1 |
| R407 R408 | SEVY0005403 | 18 V,30%, SMD ,27pF,1005 | VARISTOR VARISTOR | 1 |
| R408 R409 | SEVY0003403 | 5.6 V, SMD ,100pF, 1005 | VARISTOR | 1 |
| R409 R410 | ERHZ0000499 | | | 1 |
| R410 R411 | SEVY0003601 | 5600 ohm,1/16W ,J ,1005 ,R/TP 5.6 V, ,SMD ,100pF, 1005 | RES,CHIP,MAKER VARISTOR | 1 |
| R411 R412 | | | | 1 |
| R412 R413 | ERHZ0000288 | 470 Kohm, 1/16W, F, 1005, R/TP | RES,CHIP,MAKER | 1 |
| R413 R414 | ERHZ0000312 | 68 Kohm,1/16W ,F ,1005 ,R/TP 80.6 Kohm,1/16W ,F ,1005 ,R/TP | RES,CHIP,MAKER RES,CHIP,MAKER | 1 |
| | ERHZ0000318 | | | 1 |
| R415 | ERHZ0000404 | 1 Kohm,1/16W ,J ,1005 ,R/TP | RES,CHIP,MAKER | 1 |
| R416 | ERHZ0000404 | 1 Kohm,1/16W ,J ,1005 ,R/TP | RES,CHIP,MAKER | 1 |
| R423 | ERHY0003301 | 100 ohm,1/16W ,J ,1005 ,R/TP | RES,CHIP | 1 |
| R424 | ERHZ0000405 | 10 Kohm,1/16W ,J ,1005 ,R/TP | RES,CHIP,MAKER | 1 |
| R471 | ERHZ0000243 | 2200 ohm,1/16W ,F ,1005 ,R/TP | RES,CHIP,MAKER | 1 |
| U201 | EUSY0216903 | CSP ,409 PIN,R/TP ,CDMA EVDO BASE BAND | IC | 1 |
| U304 | EUSY0259903 | Memory, 1GND(70nm)+512SD(90nm), 2.8V ,149 PIN,R/TP ,10X14X1.4 | IC | 1 |
| U402 | EQFP0006301 | chipFET ,1.3 W,-20 V,3.9 A,R/TP ,8 PIN (Pb-free) | TR,FET,P-CHANNEL | 1 |
| VR401 | SEVY0006203 | 18 V, ,SMD ,PB-FREE(4 CH) | VARISTOR | 1 |
| X201 | EXXY0018701 | 32.768 KHz,20 PPM,12.5 pF,70 Kohm,SMD ,3.2*1.5*0.9 , | X-TAL | I |

D-5. MAIN PCB TOP

| Ref No | LG Part No | Value | Description | QTY |
|----------------------|----------------------------|---|-----------------------------------|-----|
| ANT301 | | 2.5 ,-1.5 dB,B/T Chip_6x2 | ANTENNA,MOBILE,FIXED | 1 |
| C1001 | | 10 nF,16V,K,X7R,HD,1005,R/TP | CAP,CERAMIC,CHIP | 1 |
| C1002 | ECCH0000155 | 10 nF,16V,K,X7R,HD,1005,R/TP | CAP,CERAMIC,CHIP | 1 |
| C1003 | ECCH0000155 | 10 nF,16V,K,X7R,HD,1005,R/TP | CAP,CERAMIC,CHIP | 1 |
| C1004 | | 47000 pF,10V ,K ,B ,HD ,1005 ,R/TP | CAP,CERAMIC,CHIP | 1 |
| C1005 | | 27 pF,50V ,J ,NPO ,TC ,1005 ,R/TP | CAP,CHIP,MAKER | 1 |
| C1006 | | 0.1 uF,10V ,K ,X5R ,HD ,1005 ,R/TP | CAP,CERAMIC,CHIP | 1 |
| C1009 | | 100 pF,50V ,J ,NPO ,TC ,1005 ,R/TP | CAP,CHIP,MAKER | 1 |
| C101 | | 100 pF,50V ,J ,NPO ,TC ,1005 ,R/TP | CAP, CHIP, MAKER | 1 |
| C102 C1031 | | 1.5 pF,50V ,C ,NPO ,TC ,1005 ,R/TP | CAP,CHIP,MAKER CAP.CHIP.MAKER | 1 |
| C1031 | | 68 pF,50V ,J ,NPO ,TC ,1005 ,R/TP 68 pF,50V ,J ,NPO ,TC ,1005 ,R/TP | CAP,CHIP,MAKER | 1 |
| C1032 | | 68 pF,50V ,J ,NPO ,TC ,1005 ,R/TP | CAP,CHIP,MAKER | 1 |
| C1033 | | 10 pF,50V,D,NP0,TC,1005,R/TP | CAP, CERAMIC, CHIP | 1 |
| C1034 | | 1 uF,6.3V ,K ,XSR ,TC ,1005 ,R/TP | CAP, CERAMIC, CHIP | 1 |
| C1044 | | 100000 pF,6.3V ,K ,B ,HD ,1005 ,R/TP | CAP,CERAMIC,CHIP | 1 |
| C1047 | | 10 pF,50V,D,NP0,TC,1005,R/TP | CAP,CERAMIC,CHIP | 1 |
| C1048 | | 10 pF,50V,D,NP0,TC,1005,R/TP | CAP,CERAMIC,CHIP | 1 |
| C1049 | ECCH0002001 | 100000 pF,6.3V ,K ,B ,HD ,1005 ,R/TP | CAP,CERAMIC,CHIP | 1 |
| C1050 | ECCH0002001 | 100000 pF,6.3V ,K ,B ,HD ,1005 ,R/TP | CAP,CERAMIC,CHIP | 1 |
| C1051 | ECZH0000826 | 27 pF,50V ,J ,NP0 ,TC ,1005 ,R/TP | CAP,CHIP,MAKER | 1 |
| C1053 | | 22 pF,50V,J,NP0,TC,1005,R/TP | CAP,CERAMIC,CHIP | 1 |
| C1054 | | 3.3 nF,50V,K,X7R,HD,1005,R/TP | CAP,CERAMIC,CHIP | 1 |
| C1055 | | 100 pF,50V ,J ,NP0 ,TC ,1005 ,R/TP | CAP,CHIP,MAKER | 1 |
| C1056 | | 1 nF,50V,K,X7R,HD,1005,R/TP | CAP,CERAMIC,CHIP | 1 |
| C1057 | | 100 pF,50V ,J ,NPO ,TC ,1005 ,R/TP | CAP,CHIP,MAKER | 1 |
| C1058 | | 5.6 pF,50V ,C ,NPO ,TC ,1005 ,R/TP | CAP,CERAMIC,CHIP | 1 |
| C1059 | | 33 pF,50V ,J ,NPO ,TC ,1005 ,R/TP | CAP,CHIP,MAKER | 1 |
| C106 C1060 | | 1 pF,50V ,C ,NPO ,TC ,1005 ,R/TP | CAP,CHIP,MAKER | 1 |
| | | 3.3 pF,50V ,C ,NPO ,TC ,1005 ,R/TP 56 pF,50V ,J ,NPO ,TC ,1005 ,R/TP | CAP,CERAMIC,CHIP | _ |
| C1061 C1062 | | 100 pF,50V ,J ,NP0 ,TC ,1005 ,R/TP | CAP,CHIP,MAKER CAP.CHIP.MAKER | 1 |
| C1062 | | 100 pF,50V ,J ,NPO ,TC ,1005 ,R/TP | CAP,CHIP,MAKER | 1 |
| C1063 | | 5.6 nH,S ,1005 ,R/TP , | INDUCTOR,CHIP | 1 |
| C1065 | | 100 pF,50V ,J ,NPO ,TC ,1005 ,R/TP | CAP,CHIP,MAKER | 1 |
| C1003 | | 1 nF,50V,K,X7R,HD,1005,R/TP | CAP, CERAMIC, CHIP | 1 |
| C109 | | 0.5 pF,50V ,B ,NPO ,TC ,1005 ,R/TP | CAP,CHIP,MAKER | 1 |
| C110 | | 2.2 uF,10V ,Z ,Y5V ,HD ,1608 ,R/TP | CAP,CHIP,MAKER | 1 |
| C111 | | 56 pF,50V ,J ,NPO ,TC ,1005 ,R/TP | CAP,CHIP,MAKER | 1 |
| C112 | ECCH0006201 | 4.7 uF,6.3V ,K ,X5R ,TC ,1608 ,R/TP | CAP,CERAMIC,CHIP | 1 |
| C113 | ECZH0001106 | 4700 pF,25V ,K ,X7R ,HD ,1005 ,R/TP | CAP,CHIP,MAKER | 1 |
| C114 | ECCH0000137 | 330 pF,50V ,K ,X7R ,HD ,1005 ,R/TP | CAP,CERAMIC,CHIP | 1 |
| C115 | | 330 pF,50V ,K ,X7R ,HD ,1005 ,R/TP | CAP,CERAMIC,CHIP | 1 |
| C116 | | 1 nF,50V,K,X7R,HD,1005,R/TP | CAP,CERAMIC,CHIP | 1 |
| C117 | | 1.5 nF,50V,K,X7R,HD,1005,R/TP | CAP,CERAMIC,CHIP | 1 |
| C118 | | 82 nF,10V ,K ,X5R ,HD ,1005 ,R/TP | CAP,CHIP,MAKER | 1 |
| C119 | | 10 nF,16V,K,X7R,HD,1005,R/TP | CAP,CERAMIC,CHIP | 1 |
| C120 | | 10 nF,16V,K,X7R,HD,1005,R/TP | CAP,CERAMIC,CHIP CAP,CERAMIC,CHIP | 1 |
| C121 C122 | | 18 pF,50V,J,NP0,TC,1005,R/TP 100000 pF,6.3V ,K ,B ,HD ,1005 ,R/TP | CAP,CERAMIC,CHIP | 1 |
| C122 | | 10 nF,16V,K,X7R,HD,1005,R/TP | CAP,CERAMIC,CHIP | 1 |
| | | | - ,,- | |
| C130 C131 | | 56 pF,50V ,J ,NPO ,TC ,1005 ,R/TP 100 pF,50V ,J ,NPO ,TC ,1005 ,R/TP | CAP,CHIP,MAKER CAP,CHIP,MAKER | 1 |
| C137 | | 10 nF,16V,K,X7R,HD,1005,R/TP | CAP, CERAMIC, CHIP | 1 |
| C138 | | 10 nF,16V,K,X7R,HD,1005,R/TP | CAP, CERAMIC, CHIP | 1 |
| C139 | | 100000 pF,6.3V ,K ,B ,HD ,1005 ,R/TP | CAP,CERAMIC,CHIP | 1 |
| C140 | | 100000 pF,6.3V ,K ,B ,HD ,1005 ,R/TP | CAP,CERAMIC,CHIP | 1 |
| C141 | | 100000 pF,6.3V ,K ,B ,HD ,1005 ,R/TP | CAP,CERAMIC,CHIP | 1 |
| C142 | ECZH0000813 | | CAP,CHIP,MAKER | 1 |
| C143 | ECCH0002001 | 100000 pF,6.3V ,K ,B ,HD ,1005 ,R/TP | CAP,CERAMIC,CHIP | 1 |
| C144 | | 2700 pF,50V ,K ,X7R ,HD ,1005 ,R/TP | CAP,CHIP,MAKER | 1 |
| C145 | | 47 pF,50V,J,NP0,TC,1005,R/TP | CAP,CERAMIC,CHIP | 1 |
| C146 | | 220 pF,50V ,K ,X7R ,HD ,1005 ,R/TP | CAP,CERAMIC,CHIP | 1 |
| C147 | | 6800 pF,25V ,K ,X7R ,HD ,1005 ,R/TP | CAP,CHIP,MAKER | 1 |
| C148 | | 10 uF,4V ,M ,XSR ,TC ,1608 ,R/TP | CAP,CERAMIC,CHIP | 1 |
| C149 | | 680 pF,50V ,K ,X7R ,HD ,1005 ,R/TP | CAP,CHIP,MAKER | 1 |
| C150 | | 100000 pF,6.3V ,K ,B ,HD ,1005 ,R/TP | CAP,CERAMIC,CHIP | 1 |
| C152 C153 | | 4 pF,50V,C,NP0,TC,1005,R/TP 1 nH,S ,1005 ,R/TP , | CAP,CERAMIC,CHIP INDUCTOR,CHIP | 1 |
| C153 | | 6 pF,50V,D,NP0,TC,1005,R/TP | CAP,CERAMIC,CHIP | 1 |
| C154 | | 6 pF,50V,D,NPO,TC,1005,R/TP | CAP,CERAMIC,CHIP | 1 |
| C155 | | 4.7 uF,6.3V ,K ,X5R ,TC ,1608 ,R/TP | CAP,CERAMIC,CHIP | 1 |
| | | 3.3 nF,50V,K,X7R,HD,1005,R/TP | CAP, CERAMIC, CHIP | 1 |
| (.158 | | 100 pF,50V ,J ,NP0 ,TC ,1005 ,R/TP | CAP,CHIP,MAKER | 1 |
| C158 C159 | | 100 pF,50V ,J ,NPO ,TC ,1005 ,R/TP | CAP,CHIP,MAKER | 1 |
| C159 | ECZH0000813 | 1100 DF.30V .J .NFO .1C .1003 .N/ IF | | |
| | | 100000 pF,6.3V ,K ,B ,HD ,1005 ,R/TP | CAP,CERAMIC,CHIP | 1 |
| C159 C160 | ECCH0002001 | | | 1 |
| C159 C160 C166 | ECCH0002001 ECCH0002001 | 100000 pF,6.3V ,K ,B ,HD ,1005 ,R/TP | CAP,CERAMIC,CHIP | _ |

| C170 | ECCH0002001 | 100000 pF,6.3V ,K ,B ,HD ,1005 ,R/TP | CAP,CERAMIC,CHIP | 1 |
|----------------------|-------------------|---|------------------------------------|---|
| C171 | ECCH0002001 | 100000 pF,6.3V ,K ,B ,HD ,1005 ,R/TP | CAP,CERAMIC,CHIP | 1 |
| C172 | ECZH0000813 | 100 pF,50V ,J ,NP0 ,TC ,1005 ,R/TP | CAP,CHIP,MAKER | 1 |
| C173 | ECZH0000813 | 100 pF,50V ,J ,NP0 ,TC ,1005 ,R/TP | CAP,CHIP,MAKER | 1 |
| C174 | ECCH0002001 | 100000 pF,6.3V ,K ,B ,HD ,1005 ,R/TP | CAP,CERAMIC,CHIP | 1 |
| C175 | ECCH0000115 | 22 pF,50V,J,NPO,TC,1005,R/TP | CAP,CERAMIC,CHIP | 1 |
| C176 | ECZH0000830 | 33 pF,50V ,J ,NPO ,TC ,1005 ,R/TP | CAP,CHIP,MAKER | 1 |
| C177 | | 1 nF,50V,K,X7R,HD,1005,R/TP | CAP.CERAMIC.CHIP | 1 |
| C178 | | 100 pF,50V ,J ,NPO ,TC ,1005 ,R/TP | CAP,CHIP,MAKER | 1 |
| C179 | | 2.2 uF,10V ,Z ,Y5V ,HD ,1608 ,R/TP | CAP,CHIP,MAKER | 1 |
| C180 | | 100 pF,50V ,J ,NPO ,TC ,1005 ,R/TP | CAP,CHIP,MAKER | 1 |
| C182 | | 47 pF,50V,J,NPO,TC,1005,R/TP | CAP.CERAMIC.CHIP | 1 |
| | | | CAP.CERAMIC.CHIP | |
| C183 | | 10 uF,4V ,M ,X5R ,TC ,1608 ,R/TP | - ,- | 1 |
| C184 | | 4 pF,50V,C,NPO,TC,1005,R/TP | CAP,CERAMIC,CHIP | 1 |
| C186 | | 100 pF,50V ,J ,NPO ,TC ,1005 ,R/TP | CAP,CHIP,MAKER | 1 |
| C188 | | 8.2 pF,50V ,D ,NPO ,TC ,1005 ,R/TP | CAP,CHIP,MAKER | 1 |
| C190 | | 2.2 uF,10V ,K ,X5R ,TC ,1608 ,R/TP | CAP,CERAMIC,CHIP | 1 |
| C191 | | 5.6 nH,S ,1005 ,R/TP , | INDUCTOR,CHIP | 1 |
| C194 | | 33 pF,50V ,J ,NP0 ,TC ,1005 ,R/TP | CAP,CHIP,MAKER | 1 |
| C195 | ECZH0000830 | 33 pF,50V ,J ,NPO ,TC ,1005 ,R/TP | CAP,CHIP,MAKER | 1 |
| C196 | ECZH0000813 | 100 pF,50V ,J ,NP0 ,TC ,1005 ,R/TP | CAP,CHIP,MAKER | 1 |
| C197 | ECZH0000813 | 100 pF,50V ,J ,NPO ,TC ,1005 ,R/TP | CAP,CHIP,MAKER | 1 |
| C198 | | 100000 pF,6.3V ,K ,B ,HD ,1005 ,R/TP | CAP,CERAMIC,CHIP | 1 |
| C199 | | 47 pF,50V,J,NP0,TC,1005,R/TP | CAP,CERAMIC,CHIP | 1 |
| C202 | | 33 nF,16V,K,X7R,HD,1005,R/TP | CAP,CERAMIC,CHIP | 1 |
| C206 | | 33 nF,16V,K,X7R,HD,1005,R/TP | CAP,CERAMIC,CHIP | 1 |
| C208 | | 10 nF,16V,K,X7R,HD,1005,R/TP | CAP,CERAMIC,CHIP | 1 |
| C240 | | 100000 pF,6.3V ,K ,B ,HD ,1005 ,R/TP | CAP.CERAMIC.CHIP | 1 |
| C301 | | | CAP,CERAMIC,CHIP | 1 |
| | | 100000 pF,6.3V ,K ,B ,HD ,1005 ,R/TP | | |
| C302 | | 1 nF,50V,K,X7R,HD,1005,R/TP | CAP,CERAMIC,CHIP | 1 |
| C305 | | 100 pF,50V ,J ,NPO ,TC ,1005 ,R/TP | CAP,CHIP,MAKER | 1 |
| C306 | | 1 uF,6.3V ,K ,X5R ,TC ,1005 ,R/TP | CAP,CERAMIC,CHIP | 1 |
| C307 | | 1 uF,6.3V ,K ,X5R ,TC ,1005 ,R/TP | CAP,CERAMIC,CHIP | 1 |
| C308 | | 1 uF,6.3V ,K ,X5R ,TC ,1005 ,R/TP | CAP,CERAMIC,CHIP | 1 |
| C310 | ECCH0006201 | 4.7 uF,6.3V ,K ,X5R ,TC ,1608 ,R/TP | CAP,CERAMIC,CHIP | 1 |
| C311 | ECCH0000155 | 10 nF,16V,K,X7R,HD,1005,R/TP | CAP,CERAMIC,CHIP | 1 |
| C312 | ECCH0004904 | 1 uF,6.3V ,K ,X5R ,TC ,1005 ,R/TP | CAP,CERAMIC,CHIP | 1 |
| C313 | ECCH0004904 | 1 uF,6.3V ,K ,X5R ,TC ,1005 ,R/TP | CAP,CERAMIC,CHIP | 1 |
| C314 | ECCH0004904 | 1 uF,6.3V ,K ,X5R ,TC ,1005 ,R/TP | CAP,CERAMIC,CHIP | 1 |
| C315 | | 33 pF,50V ,J ,NPO ,TC ,1005 ,R/TP | CAP,CHIP,MAKER | 1 |
| C316 | | 10 uF,6.3V ,M ,X5R ,TC ,1608 ,R/TP | CAP,CERAMIC,CHIP | 1 |
| C318 | | 1 uF,6.3V ,K ,X5R ,TC ,1005 ,R/TP | CAP,CERAMIC,CHIP | 1 |
| C319 | | 1 uF,6.3V ,K ,X5R ,TC ,1005 ,R/TP | CAP,CERAMIC,CHIP | 1 |
| C320 | | 2.2 uF,6.3V ,M ,X5R ,TC ,1005 ,R/TP | CAP,CERAMIC,CHIP | 1 |
| C321 | | 2.2 uF,6.3V ,M ,X5R ,TC ,1005 ,R/TP | CAP,CERAMIC,CHIP | 1 |
| | | | | |
| C322 | | 1 uF,6.3V ,K ,X5R ,TC ,1005 ,R/TP | CAP,CERAMIC,CHIP | 1 |
| C323 | | 10 uF,10V ,M ,STD ,1608 ,R/TP | CAP,TANTAL,CHIP | 1 |
| C324 | | 10 uF,6.3V ,M ,X5R ,TC ,1608 ,R/TP | CAP,CERAMIC,CHIP | 1 |
| C325 | | 1 uF,6.3V ,K ,X5R ,TC ,1005 ,R/TP | CAP,CERAMIC,CHIP | 1 |
| C326 | | 10 uF,10V ,M ,STD ,1608 ,R/TP | CAP,TANTAL,CHIP | 1 |
| C327 | ECTH0004301 | 10 uF,10V ,M ,STD ,1608 ,R/TP | CAP,TANTAL,CHIP | 1 |
| C328 | ECCH0004904 | 1 uF,6.3V ,K ,X5R ,TC ,1005 ,R/TP | CAP,CERAMIC,CHIP | 1 |
| C329 | ECCH0000198 | 2.2 uF,6.3V ,M ,X5R ,TC ,1005 ,R/TP | CAP,CERAMIC,CHIP | 1 |
| C330 | | 1 uF,6.3V ,K ,X5R ,TC ,1005 ,R/TP | CAP,CERAMIC,CHIP | 1 |
| C331 | | 68 pF,50V ,J ,NPO ,TC ,1005 ,R/TP | CAP,CHIP,MAKER | 1 |
| C337 | | 1 nF,50V,K,X7R,HD,1005,R/TP | CAP,CERAMIC,CHIP | 1 |
| C338 | | 1 uF,10V ,K ,X5R ,TC ,1005 ,R/TP | CAP,CHIP,MAKER | 1 |
| C339 | | 2.2 uF,6.3V ,M ,XSR ,TC ,1005 ,R/TP | CAP,CERAMIC,CHIP | 1 |
| C401 | | 100 pF,50V ,J ,NPO ,TC ,1005 ,R/TP | CAP,CHIP,MAKER | 1 |
| C402 | | 100 pF,50V ,J ,NPO ,TC ,1005 ,R/TP | CAP,CHIP,MAKER | 1 |
| C404 | | 470 pF,50V ,K ,X7R ,HD ,1005 ,R/TP | CAP,CHIP,MAKER | 1 |
| C404 | | 47 pF,50V,J,NP0,TC,1005,R/TP | CAP,CERAMIC,CHIP | 1 |
| C407 | | 100 pF,50V ,J ,NPO ,TC ,1005 ,R/TP | CAP,CERAMIC,CHIP CAP,CHIP,MAKER | 1 |
| | | | | |
| C417 | | 100 pF,50V ,J ,NPO ,TC ,1005 ,R/TP | CAP, CHIP, MAKER | 1 |
| C418 | | 100000 pF,6.3V ,K ,B ,HD ,1005 ,R/TP | CAP,CERAMIC,CHIP | 1 |
| D401 | | UMD2 ,30 V,2 A,R/TP ,SCHOTTKY BARRIER DIODE | DIODE,SWITCHING | 1 |
| DP101 | | 1880 MHz,1960 MHz,3.8 dB,3.5 dB,43 dB,52 dB,3.8*3.8*1.4 ,SMD ,FBAR | DUPLEXER,PCS | 1 |
| DP104 | | 836.5 MHz,881.5 MHz,2.3 dB,3.5 dB,57 dB,45 dB,3.0*2.5*0.8 ,SMD ,SAW Duplexe | | 1 |
| F101 | | 881.5 MHz,2.0*1.4*0.8 ,SMD , | FILTER,SAW | 1 |
| F102 | SFSY0024901 | 1960 MHz,2.0*1.4*0.68 ,SMD ,5pin, Unbal-Bal, 50/100, B7834 Low Loss ver. | FILTER,SAW | 1 |
| F103 | SFSY0018301 | 1575.42 MHz,2.0*1.4*0.78 ,SMD , | FILTER,SAW | 1 |
| F104 | SFSY0020301 | 1880 MHz,2.0*1.6*1.0 ,SMD , | FILTER,SAW | 1 |
| F105 | | 836.5 MHz,2.0*1.4*0.8 ,SMD ,DCN Tx Filter | FILTER,SAW | 1 |
| F401 | SFEY0013201 | SMD ,1608 ,EMI-ESD Filter, 4ch, 14V, 15pF, 100ohm | FILTER,EMI/POWER | 1 |
| F402 | SFEY0013201 | SMD ,1608 ,EMI-ESD Filter, 4ch, 14V, 15pF, 100ohm | FILTER,EMI/POWER | 1 |
| F403 | SFEY0013201 | SMD ,1608 ,EMI-ESD Filter, 4ch, 14V, 15pF, 1000hm | FILTER,EMI/POWER | 1 |
| F406 | SFEY0013201 | SMD ,1608 ,EMI-ESD Filter, 4ch, 14V, 15pF, 1000hm | FILTER,EMI/POWER | 1 |
| F406 F409 | | SMD ,1608 ,EMI-ESD Filter, 4ch, 14V, 15pF, 1000hm | FILTER,EMI/POWER | 1 |
| | SFEY0013201 | | | |
| L104 | | 33 nH,J ,1005 ,R/TP , | INDUCTOR, CHIP | 1 |
| 110- | ELCH0004723 | 1.8 nH,S ,1005 ,R/TP , | INDUCTOR,CHIP | 1 |
| L105 | EL 0110 (- : - : | | | |
| L105 L106 L108 | | 1.8 nH,S ,1005 ,R/TP , 10 nH,J ,1005 ,R/TP , | INDUCTOR,CHIP INDUCTOR,CHIP | 1 |

| 1111 | | | | | |
|--|--------|--------------|--------------------------------|----------------|-----|
| L115 EL-GROWATOS E. P. P. J. 1005 ATP. BOUCTOS COPP 1 | L111 | ELCH0004718 | 5.6 nH,S ,1005 ,R/TP , | INDUCTOR,CHIP | 1 |
| L115 ELG-9004769 2 Part 1,005 APP BDUCTOR COPP 1 | | | | | |
| L116 EL-GOOD4705 S. P. H.J. 1005 APP. BOULTON.CHIP 1 | | | | | |
| L118 | | | | | _ |
| L118 | | | | | |
| 1126 | L116 | ELCH0004713 | 6.8 nH,J ,1005 ,R/TP , | INDUCTOR,CHIP | 1 |
| 1.126 | L118 | ELCH0004729 | 56 nH,J ,1005 ,R/TP , | INDUCTOR,CHIP | 1 |
| L129 L100004712 3 or His , 1000 MPTP. NDLCTOR.CREP 1 | L122 | ELCH0004727 | 100 nH,J ,1005 ,R/TP , | INDUCTOR,CHIP | 1 |
| L129 L100004712 3 or His , 1000 MPTP. NDLCTOR.CREP 1 | 1126 | FI CH0004718 | 5.6 nH S. 1005 R/TP | INDLICTOR CHIP | 1 |
| L129 | | | | | _ |
| L139 | | | | | |
| L132 | | | | , | _ |
| L138 | | | | , | |
| L134 | L131 | ELCH0010401 | 2.2 uH,M ,1005 ,R/TP , | INDUCTOR,CHIP | 1 |
| L134 | L132 | ELCH0004715 | 27 nH,J ,1005 ,R/TP , | INDUCTOR,CHIP | 1 |
| L146 | | | | | _ |
| L146 | | | | | |
| L148 | | | | , | _ |
| L151 | | | | , | |
| L152 ELCHOO0476 10 mL J. 1005 R/TP C. P. CHEMAKER 1 | | | | | |
| L154 | L149 | ELCH0004726 | 1.5 nH,J ,1005 ,R/TP , | INDUCTOR,CHIP | 1 |
| L156 | L151 | ELCH0004706 | 10 nH,J ,1005 ,R/TP , | INDUCTOR,CHIP | 1 |
| L156 | L152 | FC7H0000813 | 100 pF 50V J NPO TC 1005 R/TP | | 1 |
| L166 | | | | | |
| L161 | | | | | |
| L162 ELCHOD04712 39 mts, 1005 R/TP, NDUCTOR,CHP 1 | | | | | |
| L163 | | | | / . | _ |
| L164 | L161 | ELCH0004727 | 100 nH,J ,1005 ,R/TP , | INDUCTOR,CHIP | 1 |
| L164 | L162 | ELCH0004712 | 3.9 nH,S ,1005 ,R/TP , | INDUCTOR,CHIP | 1 |
| 1.165 | | | | , | _ |
| L165 | | | | | |
| L301 | | | | | |
| L303 | | | | | _ |
| L304 ELCP0010001 [2.2 wt.M.; 5.52.0x.1.0, R/TP; chip MLCl::,,20%,NON SHIELD ,2.5X2X1MM, INDUCTOR,SMD,POWER 1 L305 ELCH0004708 [2.7 mt.S], 1005, R/TP, chip MLCl::,,20%,NON SHIELD ,2.5X2X1MM, INDUCTOR,SMD,POWER 1 L401 SFEY0006001 SMD, | | | | | |
| L304 ELCP0010001 [2.2 wt.M.; 5.52.0x.1.0, R/TP; chip MLCl::,,20%,NON SHIELD ,2.5X2X1MM, INDUCTOR,SMD,POWER 1 L305 ELCH0004708 [2.7 mt.S], 1005, R/TP, chip MLCl::,,20%,NON SHIELD ,2.5X2X1MM, INDUCTOR,SMD,POWER 1 L401 SFEY0006001 SMD, | | | | | 1 |
| L305 | L304 | | | | 1 |
| L401 SFEY0006001 SMD FLITER, EMI/POWER 1 | | | | | 1 |
| Q101 EUSY0072401 SSOP5-P-0.65A_S PIN.R/TP_INVESTER, Pb Free IC 1 1 1 1 1 1 1 1 1 | | | | , | |
| Q-201 E-QRN0012-402 VSM_100 mW.R/TP_EPITAML_PLANAR_NPN_PNP TRANSISTOR TR.R.JT.NPN 1 | | | - / | | _ |
| G401 EQBA0000602 TESY_200 mW_R/TF_EPITAMAL_PLANAR_NPN/PNP_TRANSISTOR | | | | | |
| R1001 ERIZODO0424 16 ohm.176 W. J.1005 R/TP RES.CHP.MAKER 1 | | | , , , | | _ |
| R1002 ERHZ0000424 16 ohm,1716W J, 1005 R/TP RES,CHIP MAKER 1 R102 ERHZ0000401 0 ohm,1716W J, 1005 R/TP RES,CHIP MAKER 1 R102 ERHZ0000401 0 ohm,1716W J, 1005 R/TP RES,CHIP MAKER 1 R102 ERHZ0000206 10 ohm,1716W J, 1005 R/TP RES,CHIP MAKER 1 R103 ERHZ0000206 10 ohm,1716W J, 1005 R/TP RES,CHIP MAKER 1 R1032 ERHZ0000409 51 ohm,1716W J, 1005 R/TP RES,CHIP MAKER 1 R1033 ERHZ0000409 0 ohm,1716W J, 1005 R/TP RES,CHIP MAKER 1 R1034 ERHZ0000400 0 ohm,1716W J, 1005 R/TP RES,CHIP MAKER 1 R1034 ERHZ0000401 0 ohm,1716W J, 1005 R/TP RES,CHIP MAKER 1 R1034 ERHZ0000401 0 ohm,1716W J, 1005 R/TP RES,CHIP MAKER 1 R104 ERHZ0003203 11.3 Kohn,1716W J, 1005 R/TP RES,CHIP MAKER 1 R106 ERHZ0003203 11.3 Kohn,1716W J, 1005 R/TP RES,CHIP MAKER 1 R107 ERHZ0000299 5600 ohm,1716W J, 1005 R/TP RES,CHIP MAKER 1 R108 ERHZ0000209 5600 ohm,1716W J, 1005 R/TP RES,CHIP MAKER 1 R109 ERHZ0000201 10 ohm,1716W J, 1005 R/TP RES,CHIP MAKER 1 R110 ERHZ0000203 10 Kohm,1716W J, 1005 R/TP RES,CHIP MAKER 1 R111 ERHZ0000203 10 Kohm,1716W J, 1005 R/TP RES,CHIP MAKER 1 R111 ERHZ0000203 10 Kohm,1716W J, 1005 R/TP RES,CHIP MAKER 1 R111 ERHZ0000203 10 Kohm,1716W J, 1005 R/TP RES,CHIP MAKER 1 R111 ERHZ0000203 10 Kohm,1716W J, 1005 R/TP RES,CHIP MAKER 1 R111 ERHZ0000203 10 Kohm,1716W J, 1005 R/TP RES,CHIP MAKER 1 R111 ERHZ0000203 10 Kohm,1716W J, 1005 R/TP RES,CHIP MAKER 1 R112 ERHZ0000204 100 Kohm,1716W J, 1005 R/TP RES,CHIP MAKER 1 R113 ERHZ0000204 100 Kohm,1716W J, 1005 R/TP RES,CHIP MAKER 1 R114 ERHZ0000303 10 Kohm,1716W J, 1005 R/TP RES,CHIP MAKER 1 R115 ERHZ0000204 100 Kohm,1716W J, 1005 R/TP RES,CHIP MAKER 1 R116 ERHZ0000303 2000 ohm,1716W J, 1005 R/TP RES,CHIP MAKER 1 R117 ERHZ0000040 10 Kohm,1716W J, 1005 R/TP RES,CHIP MAKER 1 R118 ERHZ0000040 10 Kohm,1716W J, 1005 R/TP RES,CHIP MAKER 1 R124 ERHZ000031 49.9 ohm,1716W J, 1005 R/TP RES,CHIP MAKER 1 R125 ERHZ0000031 10 Kohm,1716W J, 1 | Q401 | | | TR,BJT,ARRAY | 1 |
| R1003 ERHZ0000424 16 ohm,1716W J,1005 ,R/TP RES.CHIP MAKER 1 R1027 ECCH0000109 8 pF,50V,DNPO,TC,1005,R/TP RES.CHIP MAKER 1 R1027 ECCH0000109 8 pF,50V,DNPO,TC,1005,R/TP RES.CHIP MAKER 1 R1032 R2HZ0000206 10 ohm,1716W J,1005 ,R/TP RES.CHIP MAKER 1 R1032 R2HZ0000206 10 ohm,1716W J,1005 ,R/TP RES.CHIP MAKER 1 R1033 R2HZ0000401 0 ohm,1716W J,1005 ,R/TP RES.CHIP MAKER 1 R1034 R2HZ0000401 0 ohm,1716W J,1005 ,R/TP RES.CHIP MAKER 1 R1034 R2HZ0000401 0 ohm,1716W J,1005 ,R/TP RES.CHIP MAKER 1 R104 R2HY0003201 1000 ohm,1716W J,1005 ,R/TP RES.CHIP MAKER 1 R104 R2HY0003201 1000 ohm,1716W J,1005 ,R/TP RES.CHIP MAKER 1 R106 R2HZ00003201 1000 ohm,1716W J,1005 ,R/TP RES.CHIP MAKER 1 R106 R2HZ0000401 0 ohm,1716W J,1005 ,R/TP RES.CHIP MAKER 1 R106 R2HZ0000205 S600 ohm,1716W J,1005 ,R/TP RES.CHIP MAKER 1 R107 R2HZ0000206 10 ohm,1716W J,1005 ,R/TP R2HZ0000206 10 ohm,1716W J,1005 ,R/TP R2HZ0000206 10 ohm,1716W J,1005 ,R/TP R2HZ0000207 R2HZ0000206 10 ohm,1716W J,1005 ,R/TP R2HZ0000207 R2HZ0000207 10 ohm,1716W J,1005 ,R/TP R2HZ0000207 R2HZ0000207 10 ohm,1716W J,1005 ,R/TP R2HZ0000207 R2HZ00 | R1001 | ERHZ0000424 | 16 ohm,1/16W ,J ,1005 ,R/TP | RES,CHIP,MAKER | 1 |
| R1003 ERHZ0000424 16 ohm,1716W J,1005 ,R/TP RES.CHIP MAKER 1 R1027 ECCH0000109 8 pF,50V,DNPO,TC,1005,R/TP RES.CHIP MAKER 1 R1027 ECCH0000109 8 pF,50V,DNPO,TC,1005,R/TP RES.CHIP MAKER 1 R1032 R2HZ0000206 10 ohm,1716W J,1005 ,R/TP RES.CHIP MAKER 1 R1032 R2HZ0000206 10 ohm,1716W J,1005 ,R/TP RES.CHIP MAKER 1 R1033 R2HZ0000401 0 ohm,1716W J,1005 ,R/TP RES.CHIP MAKER 1 R1034 R2HZ0000401 0 ohm,1716W J,1005 ,R/TP RES.CHIP MAKER 1 R1034 R2HZ0000401 0 ohm,1716W J,1005 ,R/TP RES.CHIP MAKER 1 R104 R2HY0003201 1000 ohm,1716W J,1005 ,R/TP RES.CHIP MAKER 1 R104 R2HY0003201 1000 ohm,1716W J,1005 ,R/TP RES.CHIP MAKER 1 R106 R2HZ00003201 1000 ohm,1716W J,1005 ,R/TP RES.CHIP MAKER 1 R106 R2HZ0000401 0 ohm,1716W J,1005 ,R/TP RES.CHIP MAKER 1 R106 R2HZ0000205 S600 ohm,1716W J,1005 ,R/TP RES.CHIP MAKER 1 R107 R2HZ0000206 10 ohm,1716W J,1005 ,R/TP R2HZ0000206 10 ohm,1716W J,1005 ,R/TP R2HZ0000206 10 ohm,1716W J,1005 ,R/TP R2HZ0000207 R2HZ0000206 10 ohm,1716W J,1005 ,R/TP R2HZ0000207 R2HZ0000207 10 ohm,1716W J,1005 ,R/TP R2HZ0000207 R2HZ0000207 10 ohm,1716W J,1005 ,R/TP R2HZ0000207 R2HZ00 | R1002 | ERHZ0000424 | 16 ohm.1/16W .J .1005 .R/TP | RES.CHIP.MAKER | 1 |
| R102 | | | | | _ |
| R1027 ECCHOO01019 8 pf.50V_DNPO,TC.1005,R/TP | | | | | |
| R103 | | | | | |
| R1032 | | | | | |
| R1033 | R103 | ERHZ0000206 | 10 ohm,1/16W ,F ,1005 ,R/TP | RES,CHIP,MAKER | 1 |
| R1034 | R1032 | ERHZ0000490 | 51 ohm,1/16W ,J ,1005 ,R/TP | RES,CHIP,MAKER | 1 |
| R1034 | R1033 | ERHZ0000401 | 0 ohm,1/16W ,J ,1005 ,R/TP | RES,CHIP,MAKER | 1 |
| R104 ERHYDOO3201 1000 ohm,1/16W,F,1005,R/TP RES,CHIP,MAKER 1 1 1 1 1 1 1 1 1 | | | | | |
| R106 ERHZ0003203 11.3 Kohm,1/16W,F,1005,R/TP RES,CHIP,MAKER 1 R107 ERHZ0000401 0.0hm,1/16W,F,1005,R/TP RES,CHIP,MAKER 1 R110 ERHZ0000299 5600 ohm,1/16W,F,1005,R/TP RES,CHIP,MAKER 1 R110 ERHZ0000203 10 Kohm,1/16W,F,1005,R/TP RES,CHIP,MAKER 1 R110 ERHZ0000203 10 Kohm,1/16W,F,1005,R/TP RES,CHIP,MAKER 1 R111 ERHZ0000203 20 Kohm,1/16W,F,1005,R/TP RES,CHIP,MAKER 1 R112 ERHZ0000203 20 Kohm,1/16W,F,1005,R/TP RES,CHIP,MAKER 1 R112 ERHZ0000401 100 Kohm,1/16W,F,1005,R/TP RES,CHIP,MAKER 1 R113 ERHZ0000203 10 Kohm,1/16W,F,1005,R/TP RES,CHIP,MAKER 1 R114 ERHZ0003203 13 Kohm,1/16W,F,1005,R/TP RES,CHIP,MAKER 1 R115 ERHZ0000201 100 Kohm,1/16W,F,1005,R/TP RES,CHIP,MAKER 1 R115 ERHZ0000201 10 ohm,1/16W,F,1005,R/TP RES,CHIP,MAKER 1 R117 ERHZ0000402 10 ohm,1/16W,F,1005,R/TP RES,CHIP,MAKER 1 R117 ERHZ0000402 10 ohm,1/16W,F,1005,R/TP RES,CHIP,MAKER 1 R117 ERHZ0000402 10 ohm,1/16W,F,1005,R/TP RES,CHIP,MAKER 1 R119 ERHZ0000402 10 ohm,1/16W,F,1005,R/TP RES,CHIP,MAKER 1 R119 ERHZ0000402 220 ohm,1/16W,F,1005,R/TP RES,CHIP,MAKER 1 R119 ERHZ0000402 20 ohm,1/16W,F,1005,R/TP RES,CHIP,MAKER 1 R120 ERHZ0000402 20 ohm,1/16W,F,1005,R/TP RES,CHIP,MAKER 1 R120 ERHZ0000401 12 Kohm,1/16W,F,1005,R/TP RES,CHIP,MAKER 1 R120 ERHZ0000401 12 Kohm,1/16W,F,1005,R/TP RES,CHIP,MAKER 1 R120 ERHZ0000409 10 Kohm,1/16W,F,1005,R/TP RES,CHIP,MAKER 1 R120 ERHZ0000400 10 Kohm,1/16W,F,1005,R/TP RES,CHIP,MAKER 1 R201 ERHZ0000400 10 Kohm,1/16W,F,1005,R/TP RES,CHIP,MAKER 1 R201 ERHZ0000405 | | | | | _ |
| R1107 | | | | | |
| R108 | | | | | |
| R109 | | | | | |
| R110 | R108 | ERHZ0000299 | 5600 ohm,1/16W ,F ,1005 ,R/TP | RES,CHIP,MAKER | 1 |
| R110 | R109 | ERHZ0000206 | 10 ohm,1/16W ,F ,1005 ,R/TP | RES,CHIP,MAKER | 1 |
| R111 | | | | | _ |
| R112 | | | | | |
| R113 | | | | | |
| R114 | | | | | |
| R115 ERHZ0000291 49.9 ohm,1/16W,F,1005,R/TP RES,CHIP,MAKER 1 R117 ERHZ0000402 10 ohm,1/16W,J,1005,R/TP RES,CHIP,MAKER 1 R118 ERHZ0000402 10 ohm,1/16W,J,1005,R/TP RES,CHIP,MAKER 1 R119 ERHZ0000242 220 ohm,1/16W,F,1005,R/TP RES,CHIP,MAKER 1 R120 ERHZ000328 24000 ohm,1/16W,F,1005,R/TP RES,CHIP,MAKER 1 R121 ERHZ0002401 12 Kohm,1/16W,J,1005,R/TP RES,CHIP,MAKER 1 R122 ERHZ0000405 10 Kohm,1/16W,J,1005,R/TP RES,CHIP,MAKER 1 R123 ERHZ0000522 24 ohm,1/16W,J,1005,R/TP RES,CHIP,MAKER 1 R124 ERHZ0000490 51 ohm,1/16W,J,1005,R/TP RES,CHIP,MAKER 1 R125 ERHZ0000490 51 ohm,1/16W,J,1005,R/TP RES,CHIP,MAKER 1 R126 ERHZ0000490 51 ohm,1/16W,J,1005,R/TP RES,CHIP,MAKER 1 R127 ERHY0003301 100 ohm,1/16W,J,1005,R/TP RES,CHIP,MAKER 1 R128 ERHZ0000402 10 ohm,1 | | | | | |
| R117 | R114 | | | | 1 |
| R117 | R115 | ERHZ0000291 | 49.9 ohm,1/16W ,F ,1005 ,R/TP | RES,CHIP,MAKER | 1 |
| R118 ERHZ0000402 10 ohm,1/16W,J,1005,R/TP RES,CHIP,MAKER 1 R119 ERHZ0000242 220 ohm,1/16W,F,1005,R/TP RES,CHIP,MAKER 1 R120 ERHZ00002401 12 Kohm,1/16W,J,1005,R/TP RES,CHIP,MAKER 1 R121 ERHZ0002401 12 Kohm,1/16W,J,1005,R/TP RES,CHIP,MAKER 1 R122 ERHZ0000405 10 Kohm,1/16W,J,1005,R/TP RES,CHIP,MAKER 1 R123 ERHZ0000522 24 ohm,1/16W,J,1005,R/TP RES,CHIP,MAKER 1 R124 ERHZ0000490 51 ohm,1/16W,J,1005,R/TP RES,CHIP,MAKER 1 R125 ERHZ0000490 51 ohm,1/16W,J,1005,R/TP RES,CHIP,MAKER 1 R126 ERHZ0000490 51 ohm,1/16W,J,1005,R/TP RES,CHIP,MAKER 1 R127 ERHY0003301 100 ohm,1/16W,J,1005,R/TP RES,CHIP,MAKER 1 R129 ERHZ0000402 100 ohm,1/16W,J,1005,R/TP RES,CHIP,MAKER 1 R201 ERHZ0000281 39.2 Kohm,1/16W,F,1005,R/TP RES,CHIP,MAKER 1 R203 SETY0001401 NTC,68 | | | | | |
| R119 ERHZ0000242 220 ohm,1/16W,F,1005,R/TP RES,CHIP,MAKER 1 R120 ERHZ000328 24000 ohm,1/16W,F,1005,R/TP RES,CHIP,MAKER 1 R121 ERHZ0002401 12 Kohm,1/16W,J,1005,R/TP RES,CHIP,MAKER 1 R122 ERHZ0000405 10 Kohm,1/16W,J,1005,R/TP RES,CHIP,MAKER 1 R123 ERHZ0000291 49.9 ohm,1/16W,F,1005,R/TP RES,CHIP,MAKER 1 R124 ERHZ0000490 51 ohm,1/16W,J,1005,R/TP RES,CHIP,MAKER 1 R125 ERHZ0000490 51 ohm,1/16W,J,1005,R/TP RES,CHIP,MAKER 1 R126 ERHZ0000490 51 ohm,1/16W,J,1005,R/TP RES,CHIP,MAKER 1 R127 ERHZ0000400 100 ohm,1/16W,J,1005,R/TP RES,CHIP,MAKER 1 R128 ERHZ0000402 10 ohm,1/16W,J,1005,R/TP RES,CHIP,MAKER 1 R129 ERHZ0000402 10 ohm,1/16W,F,1005,R/TP RES,CHIP,MAKER 1 R201 ERHZ0000402 10 ohm,1/16W,F,1005,R/TP RES,CHIP,MAKER 1 R203 SETY0001401 NTC,68 K | | | | | |
| R120 ERHZ0000328 24000 ohm,1/16W,F,1005,R/TP RES,CHIP,MAKER 1 R121 ERHZ0002401 12 Kohm,1/16W,J,1005,R/TP RES,CHIP,MAKER 1 R122 ERHZ0000405 10 Kohm,1/16W,J,1005,R/TP RES,CHIP,MAKER 1 R123 ERHZ0000522 24 ohm,1/16W,J,1005,R/TP RES,CHIP,MAKER 1 R124 ERHZ0000291 49.9 ohm,1/16W,J,1005,R/TP RES,CHIP,MAKER 1 R125 ERHZ0000490 51 ohm,1/16W,J,1005,R/TP RES,CHIP,MAKER 1 R126 ERHZ0000490 51 ohm,1/16W,J,1005,R/TP RES,CHIP,MAKER 1 R127 ERHZ0000490 51 ohm,1/16W,J,1005,R/TP RES,CHIP,MAKER 1 R128 ERHZ0000406 100 ohm,1/16W,J,1005,R/TP RES,CHIP,MAKER 1 R129 ERHZ0000402 10 ohm,1/16W,J,1005,R/TP RES,CHIP,MAKER 1 R201 ERHZ0000281 39.2 Kohm,1/16W,J,1005,R/TP RES,CHIP,MAKER 1 R203 SETY0001401 NTC,68 Kohm,SMD, THERMISTOR 1 R204 ERHZ00002221 150 Kohm,1/16W,F | | | | | |
| R121 ERHZ0002401 12 Kohm,1/16W ,J ,1005 ,R/TP RES,CHIP,MAKER 1 R122 ERHZ0000405 10 Kohm,1/16W ,J ,1005 ,R/TP RES,CHIP,MAKER 1 R123 ERHZ0000522 24 ohm,1/16W ,J ,1005 ,R/TP RES,CHIP,MAKER 1 R124 ERHZ0000291 49.9 ohm,1/16W ,J ,1005 ,R/TP RES,CHIP,MAKER 1 R125 ERHZ0000490 51 ohm,1/16W ,J ,1005 ,R/TP RES,CHIP,MAKER 1 R126 ERHZ0000490 51 ohm,1/16W ,J ,1005 ,R/TP RES,CHIP,MAKER 1 R127 ERHY0003301 100 ohm,1/16W ,J ,1005 ,R/TP RES,CHIP,MAKER 1 R128 ERHZ0000406 100 Kohm,1/16W ,J ,1005 ,R/TP RES,CHIP,MAKER 1 R129 ERHZ0000420 10 ohm,1/16W ,J ,1005 ,R/TP RES,CHIP,MAKER 1 R201 ERHZ0000281 39.2 Kohm,1/16W ,F ,1005 ,R/TP RES,CHIP,MAKER 1 R203 SETY0001401 NTC ,68 Kohm,SMD , THERMISTOR 1 R204 ERHZ0000222 150 Kohm,1/16W ,F ,1005 ,R/TP RES,CHIP,MAKER 1 R206 ERHZ000023 | | | | | _ |
| R122 ERHZ0000405 10 Kohm,1/16W,J,1005,R/TP RES,CHIP,MAKER 1 R123 ERHZ0000522 24 ohm,1/16W,J,1005,R/TP RES,CHIP,MAKER 1 R124 ERHZ0000291 49.9 ohm,1/16W,F,1005,R/TP RES,CHIP,MAKER 1 R125 ERHZ0000490 51 ohm,1/16W,J,1005,R/TP RES,CHIP,MAKER 1 R126 ERHZ0000490 51 ohm,1/16W,J,1005,R/TP RES,CHIP,MAKER 1 R127 ERHY0003301 100 ohm,1/16W,J,1005,R/TP RES,CHIP,MAKER 1 R128 ERHZ0000406 100 Kohm,1/16W,J,1005,R/TP RES,CHIP,MAKER 1 R129 ERHZ00002401 10 ohm,1/16W,J,1005,R/TP RES,CHIP,MAKER 1 R201 ERHZ0000281 139.2 Kohm,1/16W,F,1005,R/TP RES,CHIP,MAKER 1 R203 SETY0001401 NTC,68 Kohm,SMD, THERMISTOR 1 R205 ERHZ0000222 150 Kohm,1/16W,F,1005,R/TP RES,CHIP,MAKER 1 R206 ERHZ0000236 2000 ohm,1/16W,F,1005,R/TP RES,CHIP,MAKER 1 R223 ERHZ0000236 2000 ohm,1/16 | | | | | |
| R123 ERHZ0000522 24 ohm,1/16W,J,1005,R/TP RES,CHIP,MAKER 1 R124 ERHZ0000291 49.9 ohm,1/16W,F,1005,R/TP RES,CHIP,MAKER 1 R125 ERHZ0000490 51 ohm,1/16W,J,1005,R/TP RES,CHIP,MAKER 1 R126 ERHZ0000490 51 ohm,1/16W,J,1005,R/TP RES,CHIP,MAKER 1 R127 ERHY0003301 100 ohm,1/16W,J,1005,R/TP RES,CHIP 1 R128 ERHZ0000406 100 Kohm,1/16W,J,1005,R/TP RES,CHIP,MAKER 1 R129 ERHZ0000402 10 ohm,1/16W,J,1005,R/TP RES,CHIP,MAKER 1 R201 ERHZ0000281 39.2 Kohm,1/16W,F,1005,R/TP RES,CHIP,MAKER 1 R203 SETY0001401 NTC,68 Kohm,SMD, THERMISTOR 1 R205 ERHZ0000222 150 Kohm,1/16W,F,1005,R/TP RES,CHIP,MAKER 1 R206 ERHZ0000236 2000 ohm,1/16W,F,1005,R/TP RES,CHIP,MAKER 1 R207 ERHY0003201 1000 ohm,1/16W,J,1005,R/TP RES,CHIP,MAKER 1 R301 ERHZ0000405 10 Kohm,1/16W,J,1005 | | | | | |
| R124 ERHZ0000291 49.9 ohm,1/16W ,F ,1005 ,R/TP RES,CHIP,MAKER 1 R125 ERHZ0000490 51 ohm,1/16W ,J ,1005 ,R/TP RES,CHIP,MAKER 1 R126 ERHZ0000490 51 ohm,1/16W ,J ,1005 ,R/TP RES,CHIP,MAKER 1 R127 ERHY0003301 100 ohm,1/16W ,J ,1005 ,R/TP RES,CHIP,MAKER 1 R128 ERHZ0000406 100 Kohm,1/16W ,J ,1005 ,R/TP RES,CHIP,MAKER 1 R129 ERHZ0000402 10 ohm,1/16W ,J ,1005 ,R/TP RES,CHIP,MAKER 1 R201 ERHZ0000281 39.2 Kohm,1/16W ,F ,1005 ,R/TP RES,CHIP,MAKER 1 R203 SETY0001401 NTC ,68 Kohm,SMD , THERMISTOR 1 R205 ERHZ0000222 150 Kohm,1/16W ,F ,1005 ,R/TP RES,CHIP,MAKER 1 R206 ERHZ0000236 2000 ohm,1/16W ,F ,1005 ,R/TP RES,CHIP,MAKER 1 R207 ERHY0003201 1000 ohm,1/16W ,F ,1005 ,R/TP RES,CHIP,MAKER 1 R301 ERHZ0000444 22 Kohm,1/16W ,J ,1005 ,R/TP RES,CHIP,MAKER 1 R302 ERHZ000 | | | | | |
| R124 ERHZ0000291 49.9 ohm,1/16W ,F ,1005 ,R/TP RES,CHIP,MAKER 1 R125 ERHZ0000490 51 ohm,1/16W ,J ,1005 ,R/TP RES,CHIP,MAKER 1 R126 ERHZ0000490 51 ohm,1/16W ,J ,1005 ,R/TP RES,CHIP,MAKER 1 R127 ERHY0003301 100 ohm,1/16W ,J ,1005 ,R/TP RES,CHIP,MAKER 1 R128 ERHZ0000406 100 Kohm,1/16W ,J ,1005 ,R/TP RES,CHIP,MAKER 1 R129 ERHZ0000402 10 ohm,1/16W ,J ,1005 ,R/TP RES,CHIP,MAKER 1 R201 ERHZ0000281 39.2 Kohm,1/16W ,F ,1005 ,R/TP RES,CHIP,MAKER 1 R203 SETY0001401 NTC ,68 Kohm,SMD , THERMISTOR 1 R205 ERHZ0000221 150 Kohm,1/16W ,F ,1005 ,R/TP RES,CHIP,MAKER 1 R206 ERHZ0000223 2000 ohm,1/16W ,F ,1005 ,R/TP RES,CHIP,MAKER 1 R207 ERHZ0000236 2000 ohm,1/16W ,F ,1005 ,R/TP RES,CHIP,MAKER 1 R301 ERHZ0000444 22 Kohm,1/16W ,J ,1005 ,R/TP RES,CHIP,MAKER 1 R302 ERHZ000 | R123 | ERHZ0000522 | 24 ohm,1/16W ,J ,1005 ,R/TP | RES,CHIP,MAKER | _ 1 |
| R125 ERHZ0000490 51 ohm,1/16W,J,1005,R/TP RES,CHIP,MAKER 1 R126 ERHZ0000490 51 ohm,1/16W,J,1005,R/TP RES,CHIP,MAKER 1 R127 ERHY0003301 100 ohm,1/16W,J,1005,R/TP RES,CHIP 1 R128 ERHZ0000406 100 Kohm,1/16W,J,1005,R/TP RES,CHIP,MAKER 1 R129 ERHZ0000402 10 ohm,1/16W,J,1005,R/TP RES,CHIP,MAKER 1 R201 ERHZ0000281 39.2 Kohm,1/16W,F,1005,R/TP RES,CHIP,MAKER 1 R203 SETY0001401 NTC,68 Kohm,SMD, THERMISTOR 1 R205 ERHZ0000222 150 Kohm,1/16W,F,1005,R/TP RES,CHIP,MAKER 1 R206 ERHZ0000236 2000 ohm,1/16W,F,1005,R/TP RES,CHIP,MAKER 1 R207 ERHY0003201 1000 ohm,1/16W,F,1005,R/TP RES,CHIP,MAKER 1 R301 ERHZ0000444 22 Kohm,1/16W,J,1005,R/TP RES,CHIP,MAKER 1 R302 ERHZ0000405 10 Kohm,1/16W,J,1005,R/TP RES,CHIP,MAKER 1 R303 ERHZ0000301 10 Kohm,1/16W,J,1005 | R124 | | | RES,CHIP,MAKER | 1 |
| R126 ERHZ0000490 51 ohm,1/16W,J,1005,R/TP RES,CHIP,MAKER 1 R127 ERHY0003301 100 ohm,1/16W,J,1005,R/TP RES,CHIP 1 R128 ERHZ0000406 100 Kohm,1/16W,J,1005,R/TP RES,CHIP,MAKER 1 R129 ERHZ0000402 10 ohm,1/16W,J,1005,R/TP RES,CHIP,MAKER 1 R201 ERHZ00002281 39.2 Kohm,1/16W,F,1005,R/TP RES,CHIP,MAKER 1 R203 SETY0001401 NTC,68 Kohm,SMD, THERMISTOR 1 R205 ERHZ0000222 150 Kohm,1/16W,F,1005,R/TP RES,CHIP,MAKER 1 R206 ERHZ0000236 2000 ohm,1/16W,F,1005,R/TP RES,CHIP,MAKER 1 R207 ERHY0003201 1000 ohm,1/16W,F,1005,R/TP RES,CHIP,MAKER 1 R301 ERHZ0000444 22 Kohm,1/16W,J,1005,R/TP RES,CHIP,MAKER 1 R302 ERHZ0000405 10 Kohm,1/16W,J,1005,R/TP RES,CHIP,MAKER 1 R303 ERHZ00003301 100 ohm,1/16W,J,1005,R/TP RES,CHIP,MAKER 1 R304 ERHZ0003301 100 ohm,1/16W,J,1 | | | | | |
| R127 ERHY0003301 100 ohm,1/16W ,J ,1005 ,R/TP RES,CHIP 1 R128 ERHZ0000406 100 Kohm,1/16W ,J ,1005 ,R/TP RES,CHIP,MAKER 1 R129 ERHZ0000402 10 ohm,1/16W ,J ,1005 ,R/TP RES,CHIP,MAKER 1 R201 ERHZ00002281 39.2 Kohm,1/16W ,F ,1005 ,R/TP RES,CHIP,MAKER 1 R203 SETY0001401 NTC ,68 Kohm,SMD , THERMISTOR 1 R205 ERHZ0000222 150 Kohm,1/16W ,F ,1005 ,R/TP RES,CHIP,MAKER 1 R206 ERHZ0000236 2000 ohm,1/16W ,F ,1005 ,R/TP RES,CHIP,MAKER 1 R207 ERHY0003201 1000 ohm,1/16W ,F ,1005 ,R/TP RES,CHIP,MAKER 1 R301 ERHZ0000444 22 Kohm,1/16W ,J ,1005 ,R/TP RES,CHIP,MAKER 1 R302 ERHZ0000405 10 Kohm,1/16W ,J ,1005 ,R/TP RES,CHIP,MAKER 1 R303 ERHZ0000301 100 ohm,1/16W ,J ,1005 ,R/TP RES,CHIP,MAKER 1 R304 ERHY0003301 100 ohm,1/16W ,J ,1005 ,R/TP RES,CHIP 1 R304 ERHZ0000275 | | | | | _ |
| R128 ERHZ0000406 100 Kohm,1/16W ,J ,1005 ,R/TP RES,CHIP,MAKER 1 R129 ERHZ0000402 10 ohm,1/16W ,J ,1005 ,R/TP RES,CHIP,MAKER 1 R201 ERHZ0000281 39.2 Kohm,1/16W ,F ,1005 ,R/TP RES,CHIP,MAKER 1 R203 SETY0001401 NTC ,68 Kohm,SMD , THERMISTOR 1 R205 ERHZ0000222 150 Kohm,1/16W ,F ,1005 ,R/TP RES,CHIP,MAKER 1 R206 ERHZ0000236 2000 ohm,1/16W ,F ,1005 ,R/TP RES,CHIP,MAKER 1 R207 ERHY0003201 1000 ohm,1/16W ,F ,1005 ,R/TP RES,CHIP,MAKER 1 R301 ERHZ0000444 22 Kohm,1/16W ,J ,1005 ,R/TP RES,CHIP,MAKER 1 R302 ERHZ0000405 10 Kohm,1/16W ,J ,1005 ,R/TP RES,CHIP,MAKER 1 R303 ERHZ00003301 100 ohm,1/16W ,J ,1005 ,R/TP RES,CHIP,MAKER 1 R304 ERHY0003301 100 ohm,1/16W ,J ,1005 ,R/TP RES,CHIP 1 R305 ERHZ0000275 360 Kohm,1/16W ,F ,1005 ,R/TP RES,CHIP,MAKER 1 R308 ERHZ000023 | | | | | |
| R129 ERHZ0000402 10 ohm,1/16W,J,1005,R/TP RES,CHIP,MAKER 1 R201 ERHZ0000281 39.2 Kohm,1/16W,F,1005,R/TP RES,CHIP,MAKER 1 R203 SETY0001401 NTC,68 Kohm,SMD, THERMISTOR 1 R205 ERHZ0000222 150 Kohm,1/16W,F,1005,R/TP RES,CHIP,MAKER 1 R206 ERHZ0000236 2000 ohm,1/16W,F,1005,R/TP RES,CHIP,MAKER 1 R207 ERHZ0003201 1000 ohm,1/16W,F,1005,R/TP RES,CHIP 1 R223 ERHZ0000444 22 Kohm,1/16W,J,1005,R/TP RES,CHIP,MAKER 1 R301 ERHZ0000405 10 Kohm,1/16W,J,1005,R/TP RES,CHIP,MAKER 1 R302 ERHZ0000405 10 Kohm,1/16W,J,1005,R/TP RES,CHIP,MAKER 1 R303 ERHY0003301 100 ohm,1/16W,J,1005,R/TP RES,CHIP,MAKER 1 R304 ERHY0003301 100 ohm,1/16W,J,1005,R/TP RES,CHIP,MAKER 1 R305 ERHZ0000275 360 Kohm,1/16W,F,1005,R/TP RES,CHIP,MAKER 1 R308 ERHZ0000238 200 Kohm,1/16W,F,1 | | | | | |
| R201 ERHZ0000281 39.2 Kohm,1/16W ,F ,1005 ,R/TP RES,CHIP,MAKER 1 R203 SETY0001401 NTC ,68 Kohm,SMD , THERMISTOR 1 R205 ERHZ0000222 150 Kohm,1/16W ,F ,1005 ,R/TP RES,CHIP,MAKER 1 R206 ERHZ0000236 2000 ohm,1/16W ,F ,1005 ,R/TP RES,CHIP,MAKER 1 R207 ERHY0003201 1000 ohm,1/16W ,F ,1005 ,R/TP RES,CHIP 1 R223 ERHZ0000444 22 Kohm,1/16W ,J ,1005 ,R/TP RES,CHIP,MAKER 1 R301 ERHZ0000405 10 Kohm,1/16W ,J ,1005 ,R/TP RES,CHIP,MAKER 1 R302 ERHZ0000405 10 Kohm,1/16W ,J ,1005 ,R/TP RES,CHIP,MAKER 1 R303 ERHY0003301 100 ohm,1/16W ,J ,1005 ,R/TP RES,CHIP,MAKER 1 R304 ERHY0003301 100 ohm,1/16W ,J ,1005 ,R/TP RES,CHIP,MAKER 1 R305 ERHZ0000275 360 Kohm,1/16W ,F ,1005 ,R/TP RES,CHIP,MAKER 1 R308 ERHZ0000238 200 Kohm,1/16W ,F ,1005 ,R/TP RES,CHIP,MAKER 1 | | | | | |
| R203 SETY0001401 NTC ,68 Kohm,SMD , THERMISTOR 1 R205 ERHZ0000222 150 Kohm,1/16W ,F ,1005 ,R/TP RES,CHIP,MAKER 1 R206 ERHZ0000236 2000 ohm,1/16W ,F ,1005 ,R/TP RES,CHIP,MAKER 1 R207 ERHY0003201 1000 ohm,1/16W ,F ,1005 ,R/TP RES,CHIP 1 R223 ERHZ0000444 22 Kohm,1/16W ,J ,1005 ,R/TP RES,CHIP,MAKER 1 R301 ERHZ0000405 10 Kohm,1/16W ,J ,1005 ,R/TP RES,CHIP,MAKER 1 R302 ERHZ0000405 10 Kohm,1/16W ,J ,1005 ,R/TP RES,CHIP,MAKER 1 R303 ERHY0003301 100 ohm,1/16W ,J ,1005 ,R/TP RES,CHIP,MAKER 1 R304 ERHY0003301 100 ohm,1/16W ,J ,1005 ,R/TP RES,CHIP,MAKER 1 R305 ERHZ0000275 360 Kohm,1/16W ,F ,1005 ,R/TP RES,CHIP,MAKER 1 R308 ERHZ0000238 200 Kohm,1/16W ,F ,1005 ,R/TP RES,CHIP,MAKER 1 | | | | | |
| R205 ERHZ0000222 150 Kohm,1/16W ,F ,1005 ,R/TP RES,CHIP,MAKER 1 R206 ERHZ0000236 2000 ohm,1/16W ,F ,1005 ,R/TP RES,CHIP,MAKER 1 R207 ERHY0003201 1000 ohm,1/16W ,F ,1005 ,R/TP RES,CHIP 1 R223 ERHZ0000444 22 Kohm,1/16W ,J ,1005 ,R/TP RES,CHIP,MAKER 1 R301 ERHZ0000405 10 Kohm,1/16W ,J ,1005 ,R/TP RES,CHIP,MAKER 1 R302 ERHZ0000405 10 Kohm,1/16W ,J ,1005 ,R/TP RES,CHIP,MAKER 1 R303 ERHY0003301 100 ohm,1/16W ,J ,1005 ,R/TP RES,CHIP 1 R304 ERHY0003301 100 ohm,1/16W ,J ,1005 ,R/TP RES,CHIP 1 R305 ERHZ0000275 360 Kohm,1/16W ,F ,1005 ,R/TP RES,CHIP,MAKER 1 R308 ERHZ0000238 200 Kohm,1/16W ,F ,1005 ,R/TP RES,CHIP,MAKER 1 | R201 | ERHZ0000281 | 39.2 Kohm,1/16W ,F ,1005 ,R/TP | RES,CHIP,MAKER | 1 |
| R205 ERHZ0000222 150 Kohm,1/16W ,F ,1005 ,R/TP RES,CHIP,MAKER 1 R206 ERHZ0000236 2000 ohm,1/16W ,F ,1005 ,R/TP RES,CHIP,MAKER 1 R207 ERHY0003201 1000 ohm,1/16W ,F ,1005 ,R/TP RES,CHIP 1 R223 ERHZ0000444 22 Kohm,1/16W ,J ,1005 ,R/TP RES,CHIP,MAKER 1 R301 ERHZ0000405 10 Kohm,1/16W ,J ,1005 ,R/TP RES,CHIP,MAKER 1 R302 ERHZ0000405 10 Kohm,1/16W ,J ,1005 ,R/TP RES,CHIP,MAKER 1 R303 ERHY0003301 100 ohm,1/16W ,J ,1005 ,R/TP RES,CHIP 1 R304 ERHY0003301 100 ohm,1/16W ,J ,1005 ,R/TP RES,CHIP 1 R305 ERHZ0000275 360 Kohm,1/16W ,F ,1005 ,R/TP RES,CHIP,MAKER 1 R308 ERHZ0000238 200 Kohm,1/16W ,F ,1005 ,R/TP RES,CHIP,MAKER 1 | R203 | SETY0001401 | NTC ,68 Kohm,SMD , | THERMISTOR | 1 |
| R206 ERHZ0000236 2000 ohm,1/16W ,F ,1005 ,R/TP RES,CHIP,MAKER 1 R207 ERHY0003201 1000 ohm,1/16W ,F ,1005 ,R/TP RES,CHIP 1 R223 ERHZ0000444 22 Kohm,1/16W ,J ,1005 ,R/TP RES,CHIP,MAKER 1 R301 ERHZ0000405 10 Kohm,1/16W ,J ,1005 ,R/TP RES,CHIP,MAKER 1 R302 ERHZ0000405 10 Kohm,1/16W ,J ,1005 ,R/TP RES,CHIP,MAKER 1 R303 ERHY0003301 100 ohm,1/16W ,J ,1005 ,R/TP RES,CHIP 1 R304 ERHY0003301 100 ohm,1/16W ,J ,1005 ,R/TP RES,CHIP 1 R305 ERHZ0000275 360 Kohm,1/16W ,F ,1005 ,R/TP RES,CHIP,MAKER 1 R308 ERHZ0000238 200 Kohm,1/16W ,F ,1005 ,R/TP RES,CHIP,MAKER 1 | | | | | |
| R207 ERHY0003201 1000 ohm,1/16W ,F ,1005 ,R/TP RES,CHIP 1 R223 ERHZ0000444 22 Kohm,1/16W ,J ,1005 ,R/TP RES,CHIP,MAKER 1 R301 ERHZ0000405 10 Kohm,1/16W ,J ,1005 ,R/TP RES,CHIP,MAKER 1 R302 ERHZ0000405 10 Kohm,1/16W ,J ,1005 ,R/TP RES,CHIP,MAKER 1 R303 ERHY0003301 100 ohm,1/16W ,J ,1005 ,R/TP RES,CHIP 1 R304 ERHY0003301 100 ohm,1/16W ,J ,1005 ,R/TP RES,CHIP 1 R305 ERHZ0000275 360 Kohm,1/16W ,F ,1005 ,R/TP RES,CHIP,MAKER 1 R308 ERHZ0000238 200 Kohm,1/16W ,F ,1005 ,R/TP RES,CHIP,MAKER 1 | | | | | |
| R223 ERHZ0000444 22 Kohm,1/16W ,J,1005 ,R/TP RES,CHIP,MAKER 1 R301 ERHZ0000405 10 Kohm,1/16W ,J,1005 ,R/TP RES,CHIP,MAKER 1 R302 ERHZ0000405 10 Kohm,1/16W ,J,1005 ,R/TP RES,CHIP,MAKER 1 R303 ERHY0003301 100 ohm,1/16W ,J,1005 ,R/TP RES,CHIP 1 R304 ERHY0003301 100 ohm,1/16W ,J,1005 ,R/TP RES,CHIP 1 R305 ERHZ0000275 360 Kohm,1/16W ,F,1005 ,R/TP RES,CHIP,MAKER 1 R308 ERHZ0000238 200 Kohm,1/16W ,F,1005 ,R/TP RES,CHIP,MAKER 1 | | | | | |
| R301 ERHZ0000405 10 Kohm,1/16W ,J ,1005 ,R/TP RES,CHIP,MAKER 1 R302 ERHZ0000405 10 Kohm,1/16W ,J ,1005 ,R/TP RES,CHIP,MAKER 1 R303 ERHY0003301 100 ohm,1/16W ,J ,1005 ,R/TP RES,CHIP 1 R304 ERHY0003301 100 ohm,1/16W ,J ,1005 ,R/TP RES,CHIP 1 R305 ERHZ0000275 360 Kohm,1/16W ,F ,1005 ,R/TP RES,CHIP,MAKER 1 R308 ERHZ0000238 200 Kohm,1/16W ,F ,1005 ,R/TP RES,CHIP,MAKER 1 | | | | , | _ |
| R302 ERHZ0000405 10 Kohm,1/16W ,J ,1005 ,R/TP RES,CHIP,MAKER 1 R303 ERHY0003301 100 ohm,1/16W ,J ,1005 ,R/TP RES,CHIP 1 R304 ERHY0003301 100 ohm,1/16W ,J ,1005 ,R/TP RES,CHIP 1 R305 ERHZ0000275 360 Kohm,1/16W ,F ,1005 ,R/TP RES,CHIP,MAKER 1 R308 ERHZ0000238 200 Kohm,1/16W ,F ,1005 ,R/TP RES,CHIP,MAKER 1 | | | | | |
| R303 ERHY0003301 100 ohm,1/16W ,J ,1005 ,R/TP RES,CHIP 1 R304 ERHY0003301 100 ohm,1/16W ,J ,1005 ,R/TP RES,CHIP 1 R305 ERHZ0000275 360 Kohm,1/16W ,F ,1005 ,R/TP RES,CHIP,MAKER 1 R308 ERHZ0000238 200 Kohm,1/16W ,F ,1005 ,R/TP RES,CHIP,MAKER 1 | R301 | | | | |
| R303 ERHY0003301 100 ohm,1/16W ,J ,1005 ,R/TP RES,CHIP 1 R304 ERHY0003301 100 ohm,1/16W ,J ,1005 ,R/TP RES,CHIP 1 R305 ERHZ0000275 360 Kohm,1/16W ,F ,1005 ,R/TP RES,CHIP,MAKER 1 R308 ERHZ0000238 200 Kohm,1/16W ,F ,1005 ,R/TP RES,CHIP,MAKER 1 | R302 | ERHZ0000405 | 10 Kohm,1/16W ,J ,1005 ,R/TP | RES,CHIP,MAKER | 1 |
| R304 ERHY0003301 100 ohm,1/16W ,J ,1005 ,R/TP RES,CHIP 1 R305 ERHZ0000275 360 Kohm,1/16W ,F ,1005 ,R/TP RES,CHIP,MAKER 1 R308 ERHZ0000238 200 Kohm,1/16W ,F ,1005 ,R/TP RES,CHIP,MAKER 1 | | | | | 1 |
| R305 ERHZ0000275 360 Kohm,1/16W ,F ,1005 ,R/TP RES,CHIP,MAKER 1 R308 ERHZ0000238 200 Kohm,1/16W ,F ,1005 ,R/TP RES,CHIP,MAKER 1 | | | | | |
| R308 ERHZ0000238 200 Kohm,1/16W ,F ,1005 ,R/TP RES,CHIP,MAKER 1 | | | | | _ |
| | | | | | |
| R309 ERHZ0000443 2200 ohm,1/16W ,J ,1005 ,R/TP RES,CHIP,MAKER 1 | | | | | |
| | I D200 | ERHZ0000443 | 2200 ohm,1/16W ,J ,1005 ,R/TP | RES,CHIP,MAKER | 1 |

| ED1170000440 | 2200 1/100 1/200 B/TD | DEC OURD MAKER | T . |
|--------------|--|--|--|
| | , , , , , | , , | 1 |
| | | · · · · · | 1 |
| | | , , | 1 |
| | , , , , | | 1 |
| ERHZ0000406 | 100 Kohm,1/16W ,J ,1005 ,R/TP | RES,CHIP,MAKER | 1 |
| ERHY0003301 | 100 ohm,1/16W ,J ,1005 ,R/TP | RES,CHIP | 1 |
| ERHZ0000326 | 330 ohm,1/16W ,F ,1005 ,R/TP | RES,CHIP | 1 |
| ERHZ0000444 | 22 Kohm,1/16W ,J ,1005 ,R/TP | RES,CHIP,MAKER | 1 |
| ERHZ0000485 | 4700 ohm,1/16W ,J ,1005 ,R/TP | RES,CHIP,MAKER | 1 |
| ERHZ0000243 | 2200 ohm,1/16W ,F ,1005 ,R/TP | RES,CHIP,MAKER | 1 |
| ERHY0003301 | 100 ohm,1/16W ,J ,1005 ,R/TP | RES,CHIP | 1 |
| ERHY0003301 | 100 ohm,1/16W ,J ,1005 ,R/TP | RES,CHIP | 1 |
| ERHZ0000406 | 100 Kohm,1/16W ,J ,1005 ,R/TP | RES,CHIP,MAKER | 1 |
| ERHZ0000404 | 1 Kohm,1/16W ,J ,1005 ,R/TP | RES,CHIP,MAKER | 1 |
| SEVY0003601 | 5.6 V, ,SMD ,100pF, 1005 | VARISTOR | 1 |
| | | VARISTOR | 1 |
| SPFY0137301 | FR-4 ,.8 mm,STAGGERED-10 ,MAIN ,; , , , , , , , | PCB,MAIN | 1 |
| | | TR,FET,P-CHANNEL | 1 |
| EUSY0257801 | QFN ,32 PIN,R/TP ,No-lead, RF transmitter IC | IC | 1 |
| ENWY0000107 | RF CONN. ,ETC ,0.15 dB,HIROSE | CONN,RF SWITCH | 1 |
| SFAD0000502 | 859 MHz,70 MHz,0.8 dB,20 dB,20 dB,42 dB,15 dB,1575.42 MHz,2 MHz,1.8 dB,42 | FILTER,SEPERATOR,SP3T | 1 |
| EUSY0257701 | QFN ,56 PIN,R/TP ,No-lead, Dual RF Receiver IC | IC | 1 |
| EUSY0186102 | 4-bump Micro SMD ,4 PIN,R/TP ,RF Power Detector for CDMA and WCDMA , -15 to + | IC | 1 |
| EUSY0265501 | 2.0*2.0*1.1 ,6 PIN,R/TP ,LNA with Shutdown function | IC | 1 |
| SMPY0012801 | 28 dBm, %, A, dBc, dB,3.0x5.0x1.0 ,SMD , | PAM | 1 |
| SCDY0003402 | -20 dB,-0.25 dB,-35 dB,1.0*0.58*0.35 ,SMD ,1850M ~ 1910M, 4pin, Pb Free | COUPLER,RF DIRECTIONAL | 1 |
| SCDY0003401 | -22 dB,-0.2 dB,-37 dB,1.0*0.58*0.35 ,SMD ,824M ~ 849M, 4pin, Pb Free | COUPLER,RF DIRECTIONAL | 1 |
| EUSY0300101 | WQFN ,10 PIN,R/TP ,Small package Dual SPDT analog Switch, PB-Free | IC | 1 |
| EUSY0260001 | Micropak ,10 PIN,R/TP ,Dual Analog switch, Pb Free | IC | 1 |
| SMZY0012601 | 4.5x3.2x1.2 Bluetooth RF Module | MODULE,ETC | 1 |
| EUSY0310101 | Microfil ,49 PIN,R/TP ,3.5x3.5, PMIC | IC | 1 |
| | | IC | 1 |
| | | IC | 1 |
| | | VCTCXO | 1 |
| | ERHZ0000410 ERHZ0000410 ERHZ0000401 ERHZ0000401 ERHZ0000301 ERHZ0000326 ERHZ0000444 ERHZ0000485 ERHZ0000485 ERHZ0000485 ERHZ0000485 ERHZ0000406 ERHZ0000502 EVY003601 SPY0137301 EVY0257801 EVY0257801 EVY0257801 EVY0265501 SMPY0012801 EUSY0265501 SMPY0012801 EUSY0265001 EUSY0260001 EUSY0260001 EUSY0260001 EUSY0300101 EUSY0320008 EUSY0320008 | ERHZ0000410 12 ohm,1/16W,J,1005,R/TP ERHZ0000401 0 ohm,1/16W,J,1005,R/TP ERHZ0000406 100 Kohm,1/16W,J,1005,R/TP ERHZ0000326 330 ohm,1/16W,J,1005,R/TP ERHZ0000326 330 ohm,1/16W,J,1005,R/TP ERHZ0000444 22 Kohm,1/16W,J,1005,R/TP ERHZ0000485 4700 ohm,1/16W,J,1005,R/TP ERHZ0000243 2200 ohm,1/16W,J,1005,R/TP ERHZ0000243 100 ohm,1/16W,J,1005,R/TP ERHZ0000405 100 ohm,1/16W,J,1005,R/TP ERHZ0000406 100 Kohm,1/16W,J,1005,R/TP ERHZ0000406 100 Kohm,1/16W,J,1005,R/TP ERHZ0000406 15.6 V,,SMD,100PF,1005 SEVY0003601 5.6 V,,SMD,100PF,1005 SEVY0003601 7.5 V,,SMD, | ERHZ0000410 12 ohm,1/16W, J,1005, R/TP RES,CHIP,MAKER ERHZ0000410 12 ohm,1/16W, J,1005, R/TP RES,CHIP,MAKER ERHZ0000406 10 ohm,1/16W, J,1005, R/TP RES,CHIP,MAKER ERHZ0000301 100 ohm,1/16W, J,1005, R/TP RES,CHIP,MAKER ERHZ0000320 330 ohm,1/16W, J,1005, R/TP RES,CHIP ERHZ0000430 330 ohm,1/16W, J,1005, R/TP RES,CHIP ERHZ0000440 22 Kohm,1/16W, J,1005, R/TP RES,CHIP,MAKER ERHZ0000485 4700 ohm,1/16W, J,1005, R/TP RES,CHIP,MAKER ERHZ0000243 2200 ohm,1/16W, J,1005, R/TP RES,CHIP,MAKER ERHY0003301 100 ohm,1/16W, J,1005, R/TP RES,CHIP,MAKER ERHY0003301 100 ohm,1/16W, J,1005, R/TP RES,CHIP,MAKER ERHZ0000406 100 kohm,1/16W, J,1005, R/TP RES,CHIP,MAKER ERHZ0000406 1 Kohm,1/16W, J,1005, R/TP RES,CHIP,MAKER ERVY0003601 5.6 V, SMD, 100pF, 1005 VARISTOR SEVY0003601 5.6 V, SMD, 100pF, 1005 VARISTOR SEYV0003601 5.6 V, SMD, 100pF, 1005 VARISTOR EUSY02577801 GPN, 32 PIN,R/TP, No-lead, Dual Rr F |

D-6. KEY PCB TOP

| Ref No | LG Part No | Value | Description | QTY |
|--------|-------------|-----------------------------------|----------------|-----|
| LED103 | EDLH0013403 | WHITE ,ETC ,R/TP ,3.8*1.2*0.6T ,; | DIODE,LED,CHIP | 1 |
| LED104 | EDLH0013403 | WHITE ,ETC ,R/TP ,3.8*1.2*0.6T ,; | DIODE,LED,CHIP | 1 |

D-7. KEY PCB BOT

| Ref No | LG Part No | Value | Description | QTY |
|--------|----------------------------|--|----------------------------------|-----|
| C101 | ECCH0000198 | 2.2 uF,6.3V ,M ,X5R ,TC ,1005 ,R/TP | CAP,CERAMIC,CHIP | 1 |
| C102 | ECCH0000155 | 10 nF,16V,K,X7R,HD,1005,R/TP | CAP,CERAMIC,CHIP | 1 |
| C103 | ECCH0002001 | 100000 pF,6.3V ,K ,B ,HD ,1005 ,R/TP | 1 | 1 |
| C104 | ECZH0000813 | 100 pF,50V ,J ,NP0 ,TC ,1005 ,R/TP | CAP,CHIP,MAKER | 1 |
| C105 | ECTZ0001316 | 10 uF,10V ,M ,STD ,2012 ,R/TP | CAP,TANTAL,CHIP,MAKER | 1 |
| C106 | ECCH0000137 | 330 pF,50V ,K ,X7R ,HD ,1005 ,R/TP | CAP,CERAMIC,CHIP | 1 |
| C107 | ECCH0000137 | 330 pF,50V ,K ,X7R ,HD ,1005 ,R/TP | CAP,CERAMIC,CHIP | 1 |
| C108 | ECTH0002701 | 2.2 uF,10V ,M ,STD ,1608 ,R/TP | CAP,TANTAL,CHIP | 1 |
| C109 | ECCH0000155 | 10 nF,16V,K,X7R,HD,1005,R/TP | CAP,CERAMIC,CHIP | 1 |
| C110 | ECCH0000143 | 1 nF,50V,K,X7R,HD,1005,R/TP | CAP,CERAMIC,CHIP | 1 |
| C111 | ECCH0000115 | 10 nF,16V,K,X7R,HD,1005,R/TP | CAP,CERAMIC,CHIP | 1 |
| C112 | ECZH0001216 | 220 nF,10V ,K ,X5R ,TC ,1005 ,R/TP | CAP,CHIP,MAKER | 1 |
| C113 | ECZH0001216 | 220 nF,10V ,K ,X5R ,TC ,1005 ,R/TP | CAP,CHIP,MAKER | 1 |
| C114 | ECCH0001210 | 100000 pF,6.3V ,K ,B ,HD ,1005 ,R/TP | CAP, CERAMIC, CHIP | 1 |
| C115 | ECTZ0000406 | 33 uF,10V ,M ,STD ,3216 ,R/TP | CAP,TANTAL,CHIP,MAKER | 1 |
| C116 | ECTZ0000406 | 33 uF,10V ,M ,STD ,3216 ,R/TP | CAP, TANTAL, CHIP, MAKER | 1 |
| C117 | ECZH0000813 | 100 pF,50V ,J ,NPO ,TC ,1005 ,R/TP | CAP,CHIP,MAKER | 1 |
| C118 | ECZH0000813 | 100 pF,50V ,J ,NPO ,TC ,1003 ,R/TP | | 1 |
| C119 | | • | CAP, CHIP, MAKER | 1 |
| C120 | ECZH0000813 ECZH0000813 | 100 pF,50V ,J ,NPO ,TC ,1005 ,R/TP | CAP, CHIP, MAKER | 1 |
| C120 | | 100 pF,50V ,J ,NPO ,TC ,1005 ,R/TP 100 pF,50V ,J ,NPO ,TC ,1005 ,R/TP | CAP, CHIP, MAKER | _ |
| C122 | ECZH0000813 | | CAP, CHIP, MAKER | 1 |
| C124 | ECZH0000813 | 100 pF,50V ,J ,NPO ,TC ,1005 ,R/TP | CAP,CHIP,MAKER CAP,CHIP,MAKER | 1 |
| C125 | ECZH0000813 | 100 pF,50V ,J ,NPO ,TC ,1005 ,R/TP | | |
| | ECZH0000813 | 100 pF,50V ,J ,NPO ,TC ,1005 ,R/TP | CAP, CHIP, MAKER | 1 |
| C126 | ECZH0000813 | 100 pF,50V ,J ,NPO ,TC ,1005 ,R/TP | CAP, CHIP, MAKER | 1 |
| C127 | ECZH0000813 | 100 pF,50V ,J ,NPO ,TC ,1005 ,R/TP | CAP, CHIP, MAKER | 1 |
| C128 | ECZH0000813 | 100 pF,50V ,J ,NPO ,TC ,1005 ,R/TP | CAP, CFPAMIC CUIP | 1 |
| C130 | ECCH0000198 | 2.2 uF,6.3V ,M ,X5R ,TC ,1005 ,R/TP | CAP,CERAMIC,CHIP | 1 |
| C131 | ECZH0000844 | 68 pF,50V ,J ,NPO ,TC ,1005 ,R/TP | CAP, CHIP, MAKER | 1 |
| C132 | ECCH0002001 | 100000 pF,6.3V ,K ,B ,HD ,1005 ,R/TP | CAP, CERAMIC, CHIP | 1 |
| C133 | ECCH0002001 | 100000 pF,6.3V ,K ,B ,HD ,1005 ,R/TP | CAP,CERAMIC,CHIP | 1 |
| C135 | ECZH0000841 | 56 pF,50V ,J ,NPO ,TC ,1005 ,R/TP | CAP, CHIP, MAKER | 1 |
| C136 | ECZH0000830 | 33 pF,50V ,J ,NPO ,TC ,1005 ,R/TP | CAP, CHIP, MAKER | 1 |
| C137 | ECZH0000830 | 33 pF,50V ,J ,NPO ,TC ,1005 ,R/TP | CAP, CHIP, MAKER | 1 |
| C138 | ECZH0000830 | 33 pF,50V ,J ,NPO ,TC ,1005 ,R/TP | CAP,CHIP,MAKER | 1 |
| C139 | ECZH0000830 | 33 pF,50V ,J ,NPO ,TC ,1005 ,R/TP | CAP,CHIP,MAKER | 1 |
| C140 | ECCH0000113 | 18 pF,50V,J,NPO,TC,1005,R/TP | CAP,CERAMIC,CHIP | 1 |
| C141 | ECZH0000830 | 33 pF,50V ,J ,NPO ,TC ,1005 ,R/TP | CAP,CHIP,MAKER | 1 |
| C142 | ECZH0000830 | 33 pF,50V ,J ,NPO ,TC ,1005 ,R/TP | CAP,CHIP,MAKER | 1 |
| C143 | ECZH0001216 | 220 nF,10V ,K ,X5R ,TC ,1005 ,R/TP | CAP,CHIP,MAKER | 1 |
| C144 | ECZH0001216 | 220 nF,10V ,K ,X5R ,TC ,1005 ,R/TP | CAP,CHIP,MAKER | 1 |
| C146 | ECCH0005604 | 10 uF,6.3V ,M ,X5R ,TC ,1608 ,R/TP | CAP,CERAMIC,CHIP | 1 |
| C147 | ECCH0005604 | 10 uF,6.3V ,M ,X5R ,TC ,1608 ,R/TP | CAP,CERAMIC,CHIP | 1 |
| C148 | ECZH0000830 | 33 pF,50V ,J ,NPO ,TC ,1005 ,R/TP | CAP,CHIP,MAKER | 1 |
| C151 | ECZH0000841 | 56 pF,50V ,J ,NPO ,TC ,1005 ,R/TP | CAP,CHIP,MAKER | 1 |
| C152 | ECZH0001215 | 1 uF,10V ,K ,X5R ,TC ,1005 ,R/TP | CAP,CHIP,MAKER | 1 |
| C153 | ECZH0000841 | 56 pF,50V ,J ,NPO ,TC ,1005 ,R/TP | CAP,CHIP,MAKER | 1 |
| CON104 | ENBY0040801 | 50 PIN, mm,ETC , , ,; , ,0.40MM ,STRAIG | | 1 |
| CON105 | ENSY0018801 | 8 PIN,ETC , ,2.54 mm,Micro-SD Socket, I | | 1 |
| D1 | EDSY0000401 | EMD3 ,80 V,.3 A,R/TP , | DIODE,SWITCHING | 1 |
| L102 | SFBH0000903 | 600 ohm,1005 , | FILTER,BEAD,CHIP | 1 |
| L103 | SFBH0000903 | 600 ohm,1005 , | FILTER,BEAD,CHIP | 1 |
| M101 | SUMY0010602 | UNIT ,-42 dB,6.15*3.76*1.25 ,Silicon m | | 1 |
| Q102 | EQBN0007601 | SOT-23 ,0.15 W,R/TP ,EMT3 | TR,BJT,NPN | 1 |
| Q103 | EQBA0000602 | TESV ,200 mW,R/TP ,EPITAXIAL PLANA | TR,BJT,ARRAY | 1 |
| R101 | ERHZ0000404 | 1 Kohm,1/16W ,J ,1005 ,R/TP | RES,CHIP,MAKER | 1 |
| R104 | ERHZ0000441 | 22 ohm,1/16W ,J ,1005 ,R/TP | RES,CHIP,MAKER | 1 |

| R107 R108 | ERHY0003301 ERHY0003301 | 100 ohm,1/16W ,J ,1005 ,R/TP | RES,CHIP | 1. |
|--------------|----------------------------|--|------------------|----|
| R108 | ERHY0003301 | | INLU, OF HE | 1 |
| | | 100 ohm,1/16W ,J ,1005 ,R/TP | RES,CHIP | 1 |
| R109 | ERHY0003301 | 100 ohm,1/16W ,J ,1005 ,R/TP | RES,CHIP | 1 |
| R110 | ERHY0003301 | 100 ohm,1/16W ,J ,1005 ,R/TP | RES,CHIP | 1 |
| R111 | ERHY0003301 | 100 ohm,1/16W ,J ,1005 ,R/TP | RES,CHIP | 1 |
| R112 | ERHY0003301 | 100 ohm,1/16W ,J ,1005 ,R/TP | RES,CHIP | 1 |
| R113 | ERHY0003301 | 100 ohm,1/16W ,J ,1005 ,R/TP | RES,CHIP | 1 |
| R114 | ERHY0003301 | 100 ohm,1/16W ,J ,1005 ,R/TP | RES,CHIP | 1 |
| R115 | ERHY0003301 | 100 ohm,1/16W ,J ,1005 ,R/TP | RES,CHIP | 1 |
| R116 | ERHZ0000486 | 47 Kohm,1/16W ,J ,1005 ,R/TP | RES,CHIP,MAKER | 1 |
| R117 | ERHY0003301 | 100 ohm,1/16W ,J ,1005 ,R/TP | RES,CHIP | 1 |
| R118 | ERHY0003301 | 100 ohm,1/16W ,J ,1005 ,R/TP | RES,CHIP | 1 |
| R126 | ERHZ0000243 | 2200 ohm,1/16W ,F ,1005 ,R/TP | RES,CHIP,MAKER | 1 |
| R127 | ERHZ0000443 | 2200 ohm,1/16W ,J ,1005 ,R/TP | RES,CHIP,MAKER | 1 |
| R137 | ERHZ0000405 | 10 Kohm,1/16W ,J ,1005 ,R/TP | RES,CHIP,MAKER | 1 |
| R138 | ERHZ0000404 | 1 Kohm,1/16W ,J ,1005 ,R/TP | RES,CHIP,MAKER | 1 |
| R139 | ERHZ0000406 | 100 Kohm,1/16W ,J ,1005 ,R/TP | RES,CHIP,MAKER | 1 |
| R142 | ERHZ0000485 | 4700 ohm,1/16W ,J ,1005 ,R/TP | RES,CHIP,MAKER | 1 |
| R143 | ERHZ0000445 | 220 Kohm,1/16W ,J ,1005 ,R/TP | RES,CHIP,MAKER | 1 |
| R144 | ERHZ0000405 | 10 Kohm,1/16W ,J ,1005 ,R/TP | RES,CHIP,MAKER | 1 |
| R146 | ERHZ0000463 | 33 ohm,1/16W ,J ,1005 ,R/TP | RES,CHIP,MAKER | 1 |
| R147 | ERHZ0000463 | 33 ohm,1/16W ,J ,1005 ,R/TP | RES,CHIP,MAKER | 1 |
| R148 | ERHZ0000405 | 10 Kohm,1/16W ,J ,1005 ,R/TP | RES,CHIP,MAKER | 1 |
| R149 | ERHZ0000405 | 10 Kohm,1/16W ,J ,1005 ,R/TP | RES,CHIP,MAKER | 1 |
| U101 | EUSY0294901 | SON1612-6, 6 PIN,R/TP, 2.6V 150mA L | IC | 1 |
| U102 | EUSY0313401 | QFN ,4 PIN,R/TP ,1.8X1.2X0.5 size wide | IC | 1 |
| U103 | EUSY0243201 | Micro SMD ,25 PIN,R/TP ,Output Capacit | IC | 1 |
| U105 | EUSY0232812 | SON1612-6,6 PIN,R/TP,2.8V, 150mA L | IC | 1 |
| U106 | EQFP0003501 | SC70JW-8 ,714 mW,6 V,2.3 A,R/TP ,Sle | TR,FET,P-CHANNEL | 1 |
| X101 | EXSY0021306 | 24.5454 MHz,50 PPM,15 pF,SMD ,3.2*2 | OSCILLATOR | 1 |